

EC GPIO	Use As	Signal Name
GPA0	O	PWR_LED#
GPA1	O	CHG_LED#
GPA2	O	CHG_FULL_LED#
GPA3	-	-
GPA4	O	LCD_BL_PWM
GPA5	O	FAN0_PWM
GPA6	-	-
GPA7	-	-
GPB0	O	BATSEL_0
GPB1	O	BATSEL_1
GPB2	-	ME_AC_PRESENT_EC
GPB3	IO	SMB0_CLK
GPB4	IO	SMB0_DAT
GPB5	O	A20GATE
GPB6	O	RCIN#
GPB7	O	PM_RSMRST#
GPC0	-	-
GPC1	IO	SMB1_CLK
GPC2	IO	SMB1_DAT
GPC3	O	PM_PWRBTN#
GPC4	I	AC_IN_OC#
GPC5	O	OP_SD#
GPC6	I	BAT1_IN_OC#
GPC7	I	-
GPD0	I	PWRLIMIT#
GPD1	I	PM_SUSC#
GPD2	I	BUF_PLT_RST#
GPD3	O	EXT_SCI#
GPD4	O	EXT_SMI#
GPD5	O	LCD_BACKOFF#
GPD6	I	FAN0_TACH
GPD7	O	SD_CD#_EC
GPE0	O	VSUS_ON
GPE1	O	-
GPE2	O	-
GPE3	O	-
GPE4	I	PWR_SW#
GPE5	-	-
GPE6	I	LID_SW#
GPE7	-	-
GPF0	O	-
GPF1	-	-
GPF2	I	-
GPF3	-	-
GPF4	I	TP_CLK
GPF5	IO	TP_DAT
GPF6	O	THRO_CPU
GPF7	-	PCH_SPI_OV
GPG0	-	ME_SusPwrDnAck_EC
PGP1	I	PM_SUSB#
GP2	O	OCMV_CTL0
GPG6	O	OCMV_CTL1
PH0	IO	PM_CLKRUN#
GPH1	O	-
GPH2	O	CHG_EN
GPH3	O	SUSC_EC#
GPH4	O	SUSB_EC#
GPH5	O	NUM_LED#
GPH6	O	CAP_LED#
GPI0	-	-
GPI1	I	SUS_PWRGD
GPI2	I	ALL_SYSTEM_PWRGD
GPI3	I	VRM_PWRGD
GPI4	I	PCH_TEMP_ALERT#
GPI5	I	-
GPI6	I	-
GPI7	I	-
GPU0	O	CPU_VRON
GPJ1	O	PM_PWROK
GPJ2	O	VSET_EC
GPJ3	O	ISSET_EC
GPJ4	O	-
GPJ5	-	-

EC GPIO	Use As	Signal Name
GPIO0	I	-
GPIO1	I	-
GPIO2	-	-
GPIO3	-	-
GPIO4	I	-
GPIO5	I	-
GPIO6	O	-
GPIO7	-	-
GPIO8	-	-
GPIO9	-	-
GPIO10	-	-
GPIO11	-	-
GPIO12	O	-
GPIO13	-	-
GPIO14	O	-
GPIO15	-	-
GPIO16	-	-
GPIO17	-	-
GPIO18	-	-
GPIO19	-	-
GPIO20	-	-
GPIO21	-	-
GPIO22	-	-
GPIO23	-	-
GPIO24	-	-
GPIO25	-	-
GPIO26	-	-
GPIO27	-	-
GPIO28	-	-
GPIO29	-	-
GPIO30	-	-
GPIO31	-	-
GPIO32	-	-
GPIO33	-	-
GPIO34	-	-
GPIO35	-	-
GPIO36	-	-
GPIO37	-	-

SM_BUS ADDRESS :

PCH Master		
SM-Bus Device	SM-Bus Address	
Clock Generator(IC59LRS3162)	1101001x (D2)	
SO-DIMM 0	1010000x (A0)	
SO-DIMM 1	1010001x (A2)	
EC Master (SMB1)		
SM-Bus Device	SM-Bus Address	
CPU Thermal Sensor(G781)	1001100x (98)	
VGA Thermal IC(G781-1)	1001101x (9A)	

Device Identification

CPU Thermal Sensor P/N:			component name
1st	06G023048011		G781F
S			
S			
S			
Clock Gen P/N:			component name
1st	06G011610010		ICS9LRS3162
S			
S			
VGA Thermal Sensor			component name
1st	06G023048020		G781-1
S			
S			

PCIE 1	
PCIE 2	Minicard WLAN
PCIE 3	
PCIE 4	
PCIE 5	
PCIE 6	GLAN
PCIE 7	
PCIE 8	

SATA 0	SATA HDD (1)
SATA1	SATA ODD
SATA4	SATA HDD (2)
SATA5	

	K72J
0	USB port
1	USB port
2	USB port (D/B)
3	USB port (D/B)
4	
5	MiniCard (Full)
6	
7	
8	MiniCard (Half)
9	Camera
10	
11	Card Reader
12	Bluetooth
13	

FDI disable: (For discrete graphic)

1. NC:

FDI_TX[0:7], FDI_RX[0:7], FDI_RX[0:7], FDI_RX[0:7]
VCC_AXGSENSE, VSS_AXGSENSE

2. Pull-down to GND via 1KΩ ± 5% resistor:

FDI_FSYNC[0:1], FDI_LSYNC[0:1], FDI_INT, GFX_IMON
~15mW power saving. (DG R0.8 P.70)

3. Connected to GND:

VCCAXG,

4. Can be connected to GND directly:

DPLL_REF_CLK, DPLL_REF_CLK#

5. Connect to +V1.05S rail:

VCCFDIPLL



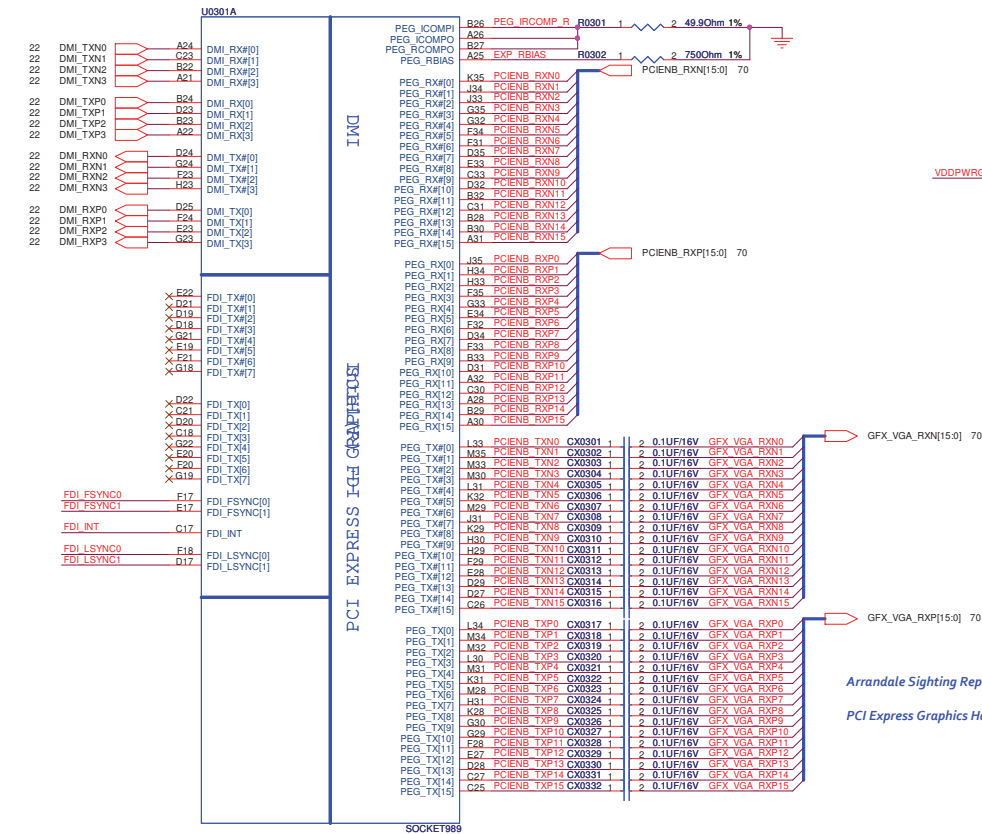
DG R1.1 P.83:

*FDI_FSYNC[0], FDI_FSYNC[1], FDI_LSYNC[0], FDI_LSYNC[1] can be ganged together with one resistor.

*On the other hand, FDI_FSYNC[0], FDI_FSYNC[1], FDI_LSYNC[0], FDI_LSYNC[1], and FDI_INT signals on PCH side can be left as no connect without any power or functional impact.

Arrandale Sighting Report :

System May Hang With DMI L1 Enabled.



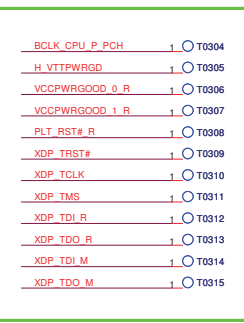
Arrandale Sighting Report :

PCI Express Graphics Hang With L1 Enabled in Rare Cases.

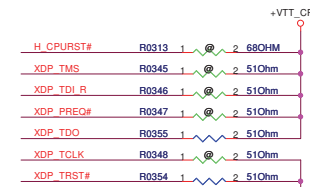
CPU Socket : 12G011909890

Molex : 12G011909891

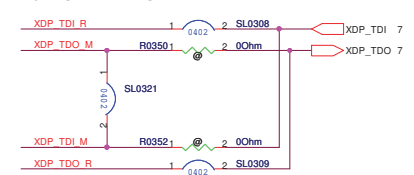
Tape & Reel : 12G011909893



For CPU Boundary Scan



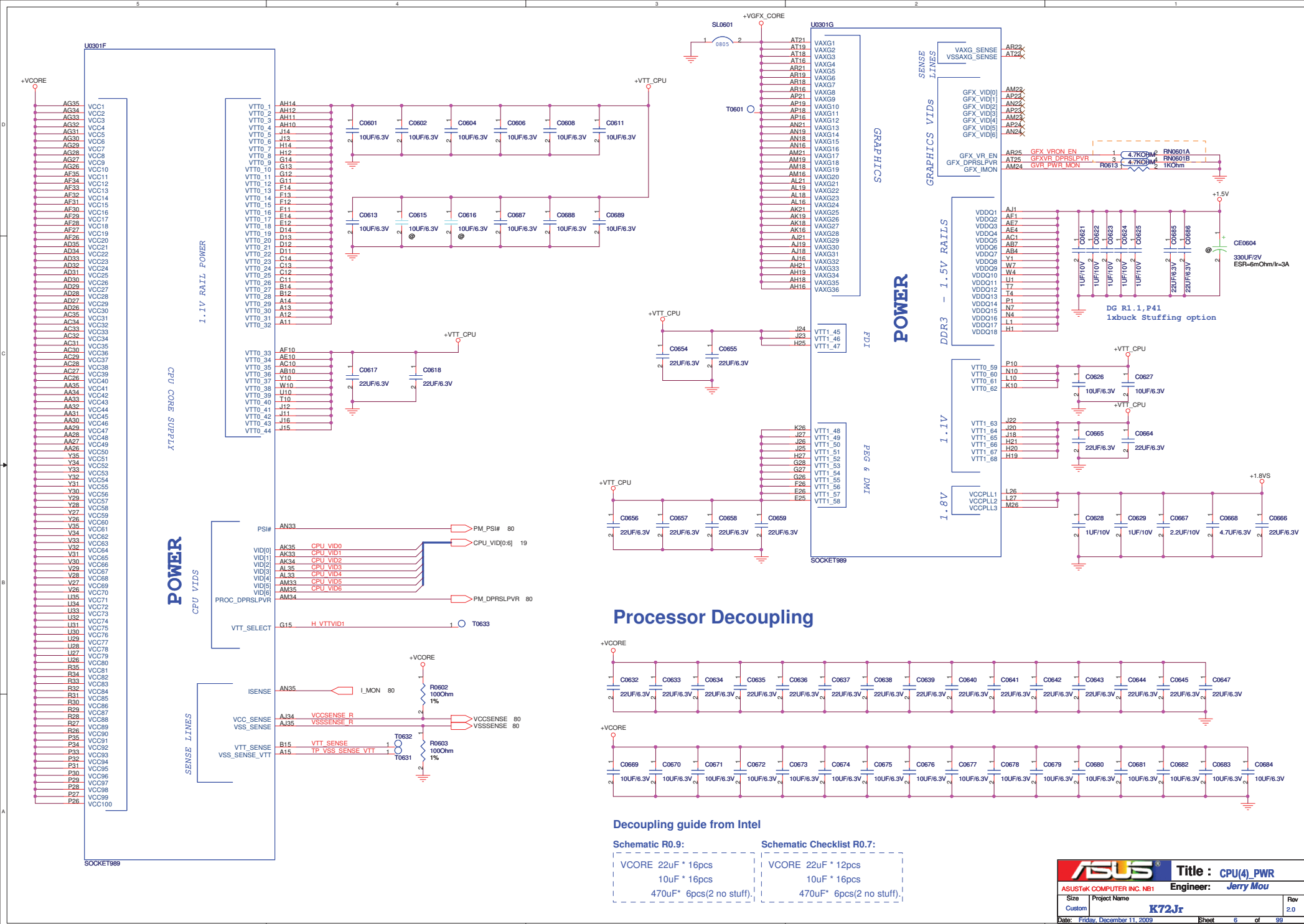
JTAG MAPPING



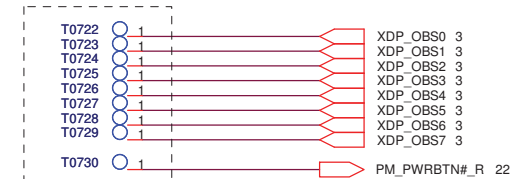
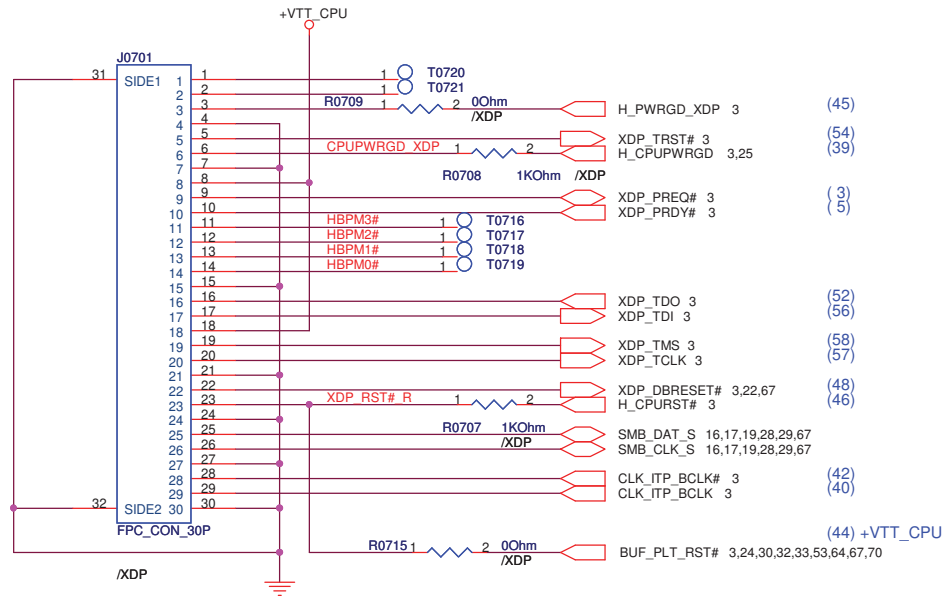
DG R1.1 P.109:

*On Clarkfield rPGA only designs, VCCPWRGOOD_1 on the Clarkfield processor can be left as No Connect.

		Title : CPU(1)_DMI,PEG	
ASUSTek COMPUTER INC. NBI		Engineer: Jerry Mou	
Size Custom	Project Name K72Jr		Rev 2.0
Date: Friday, December 11, 2009		Sheet	3 of 99



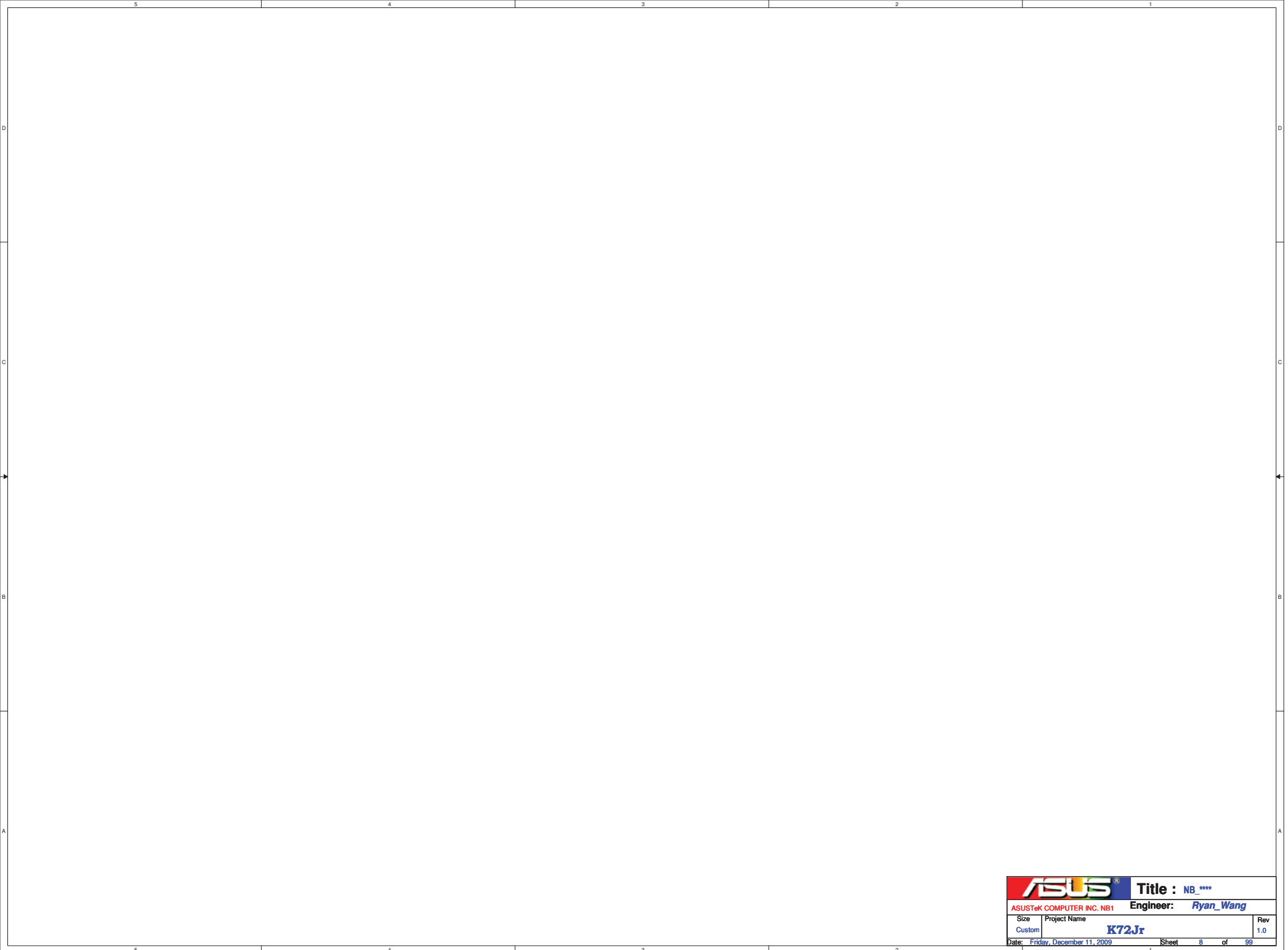
CPU XDP connector



Put these test point near J0701.

Put it away from the FFC path.

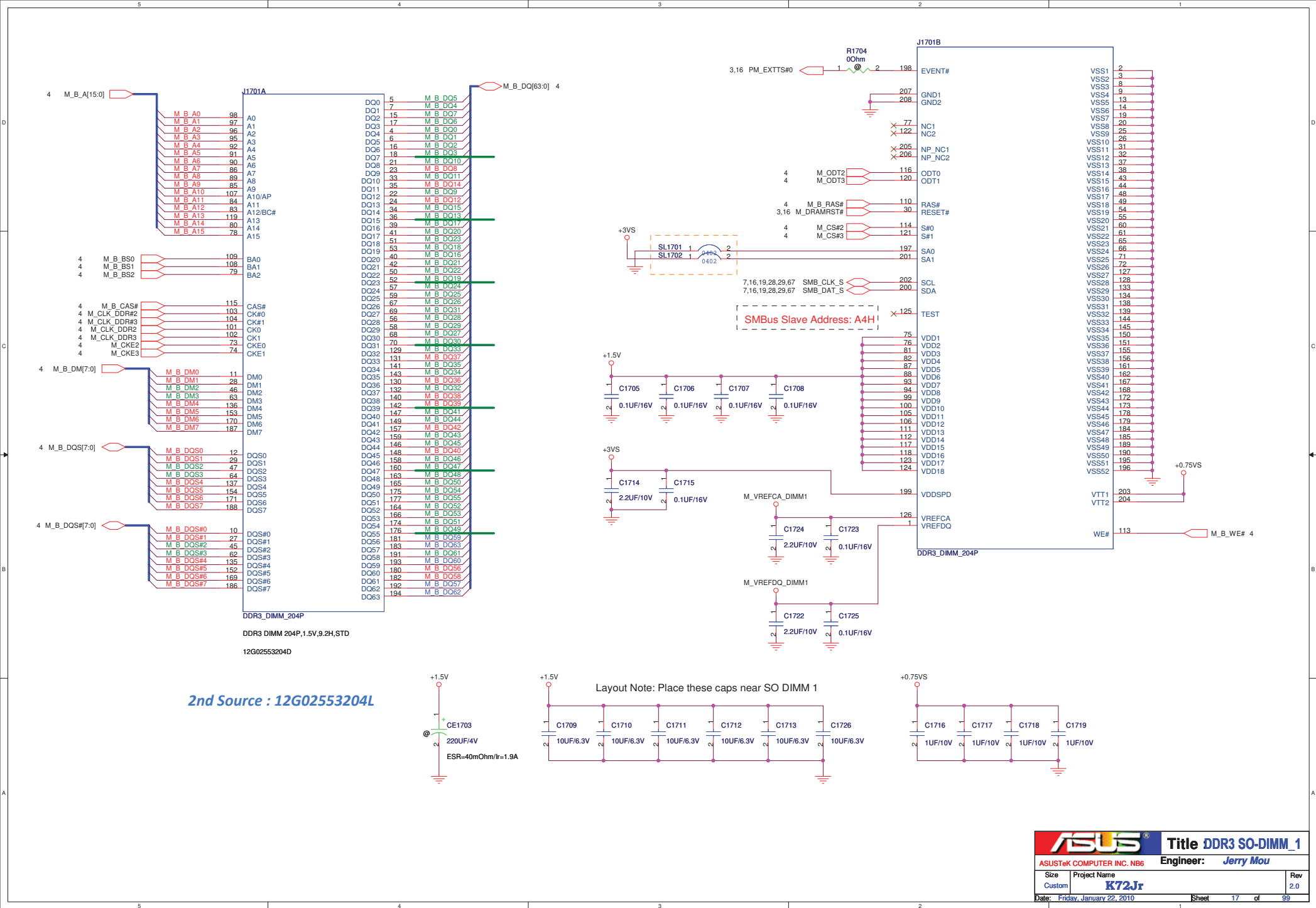
ASUS		Title : CPU(5)_XDP	
ASUSTeK COMPUTER INC. NB1		Engineer: Jerry Mou	
Size	Project Name	K72Jr	Rev 2.0
Custom			
Date: Friday, December 11, 2009		Sheet	7 of 99



		Title : NB_****	
ASUSTeK COMPUTER INC. NB1		Engineer: <i>Ryan_Wang</i>	
Size Custom	Project Name K72Jr		Rev 1.0
Date: Friday, December 11, 2009		Sheet	8 of 99



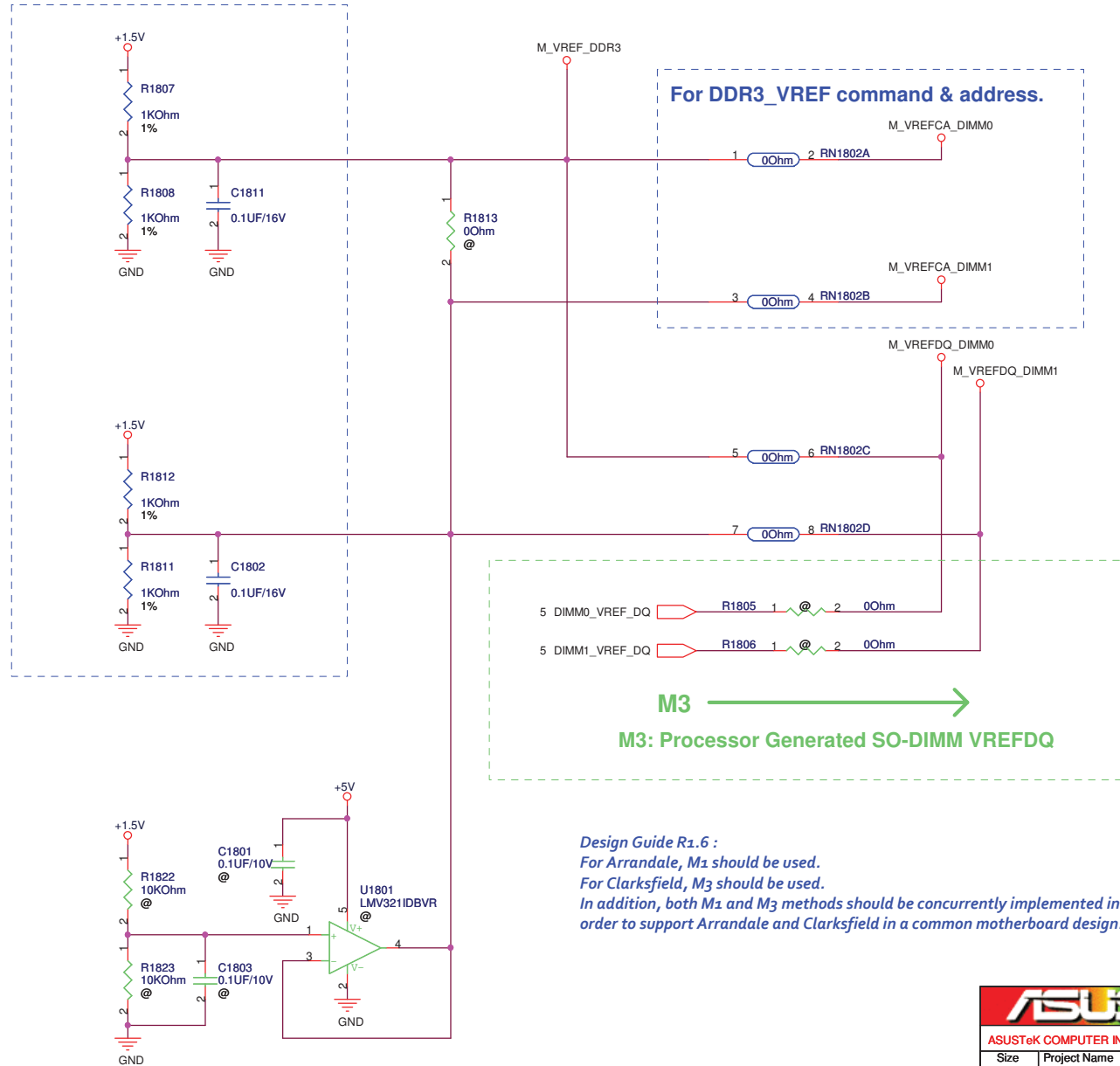
		Title :	
ASUSTeK COMPUTER INC. NB6		Engineer: <i>Ryan_Wang</i>	
Size A	Project Name K72Jr		Rev 1.0
Date: <i>Friday, December 11, 2009</i>		Sheet	15 of 99



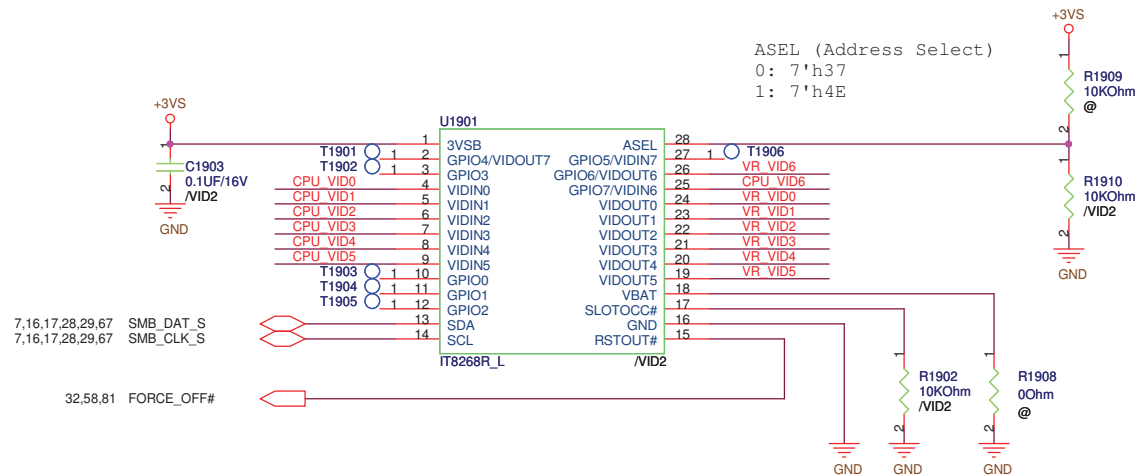
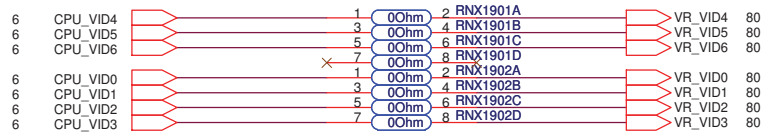
Default M1 

DDR3 Vref

Intel Document Number: 400755

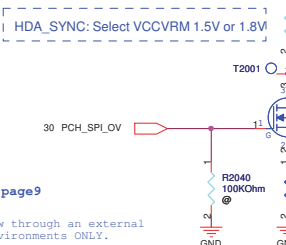
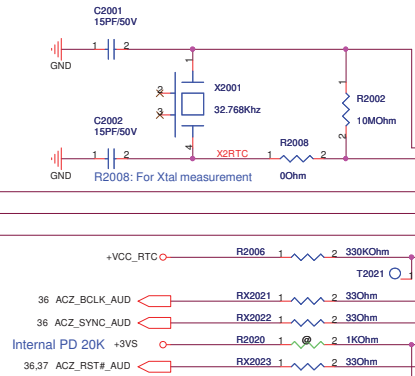
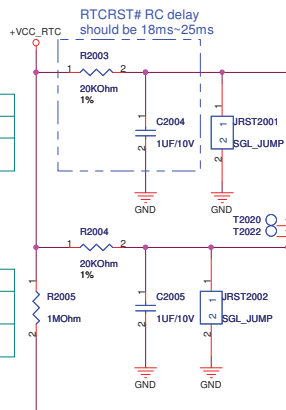


		Title : DDR3 VREF	
ASUSTeK COMPUTER INC. NB1		Engineer: Jerry Mou	
Size Custom	Project Name K72Jr		Rev 2.0
Date: Friday, December 11, 2009		Sheet	18 of 96



CMOS Settings	JRST2001
Clear CMOS	Shunt
Keep CMOS	Open (Default)

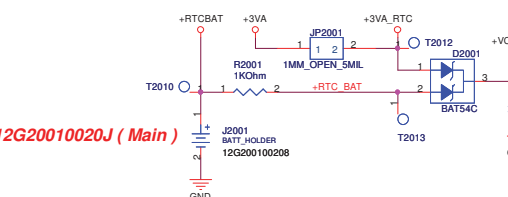
TPM Settings	JRST2002
Clear ME RTC Registers	Shunt
Keep ME RTC Registers	Open (Default)



414044 Design Guide R1.11 Update: page9

GPIO33:
This signal should be only asserted low through an external pull-down in manufacturing or debug environments ONLY.

Without connecting GPIO33, customers may not be able to override SPI flash contents.



12G20010020J (Main)

Strap information:

HDA_SPKR: No reboot strap
Low: Disable.
High: Enable

HDA_DOCK_EN#:
1. Flash descriptor security:
Sampled low: override
Sampled high: in effect.
2. GPIO33 low on the rising edge of PWROK,
Will also disable Intel ME.

SPI_MOSI: iTPM strap.
Mount R2015: Enable
Unmount R2015: Disable(default)

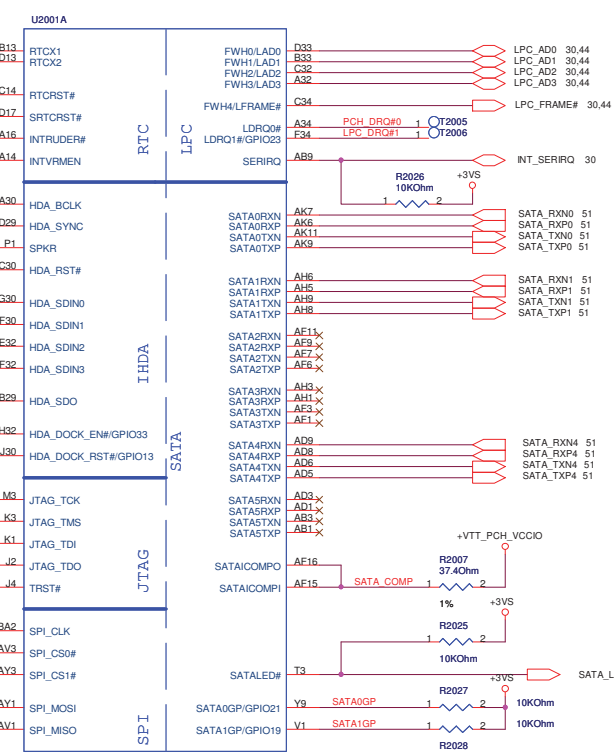
MoW 11, 2009 :

Ibex peak JTAG and Ibex Peak Test Interface requirements

For pre-production systems, please refer to the latest Calpella Platform Debug Port Design Guide (Doc #385422)

		Pre-Production Systems	Production Systems
PCH Pin	RefDes	ES1	ES2
TDO	R1	No Stff	200 Ohms
	R2	No Stff	100 Ohms
	R3	200 Ohms	200 Ohms
TMS	R4	100 Ohms	100 Ohms
	R5	200 Ohms	200 Ohms
TDI	R6	100 Ohms	100 Ohms
TCK	R7	51 Ohms	51 Ohms
	R8	20K Ohms	Not Applicable ¹
		10K Ohms	Not Applicable ¹
TRST#	R9	Not Applicable ¹	Not Applicable ¹

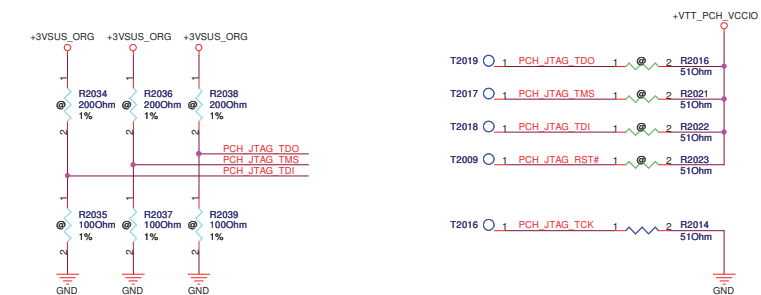
Note 1: For IBX ES2 and later, TRST# does not require an external pull-up; but should be routed to a test point pad for PCH JTAG debug purposes



02G010026101

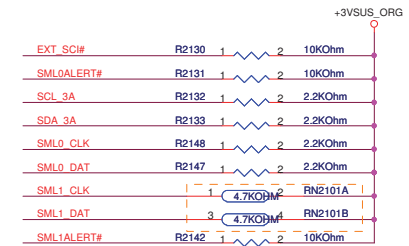
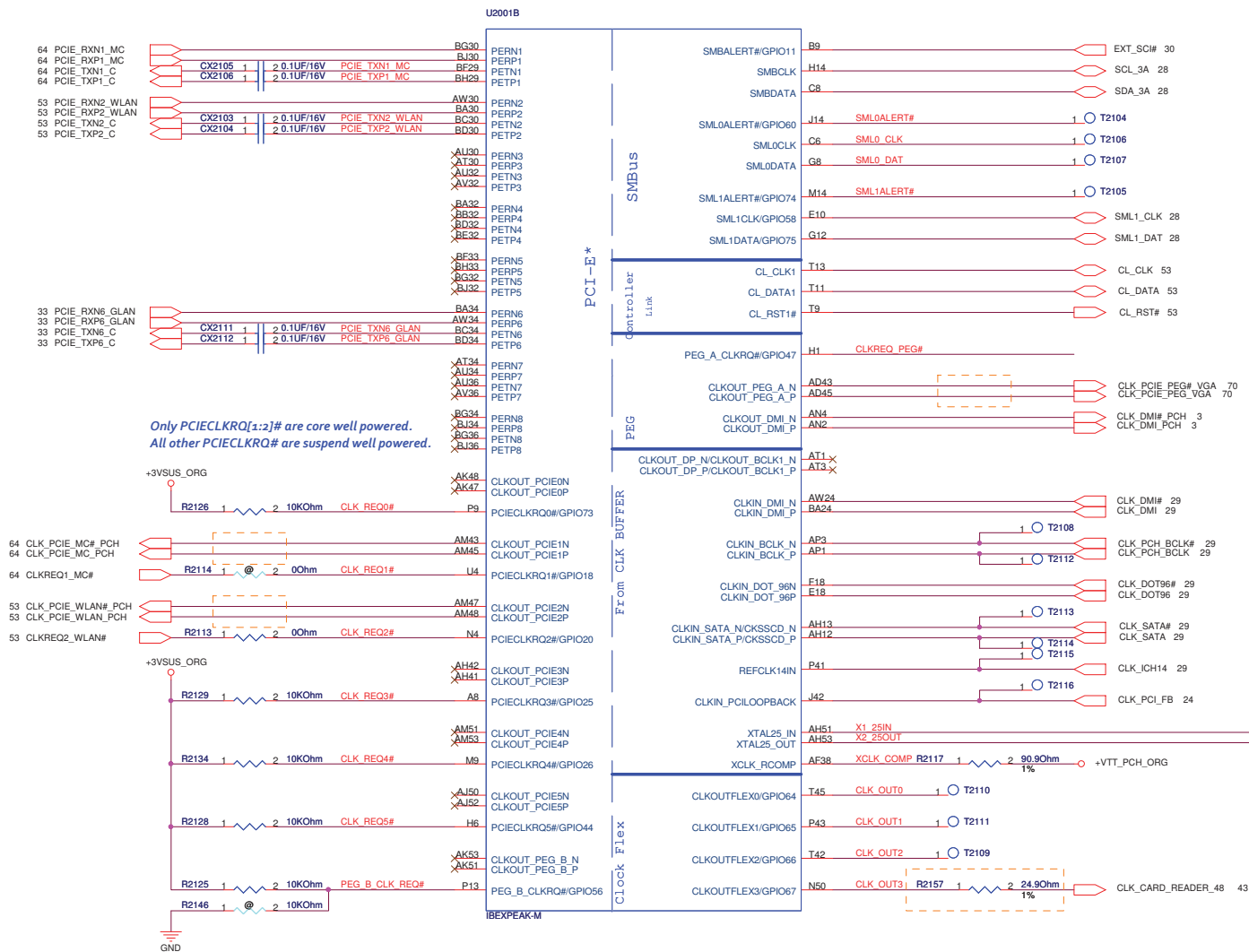
C.S BD82HM55 904127

GA INT IBEXPEAK HM55

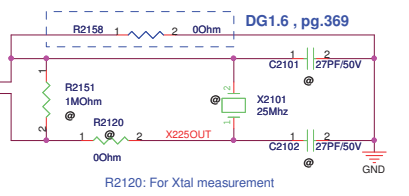
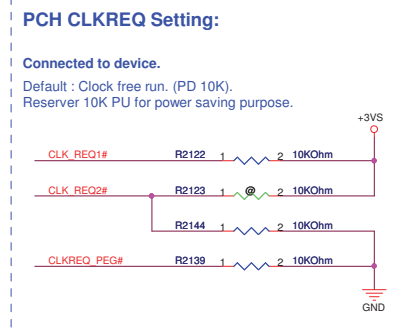


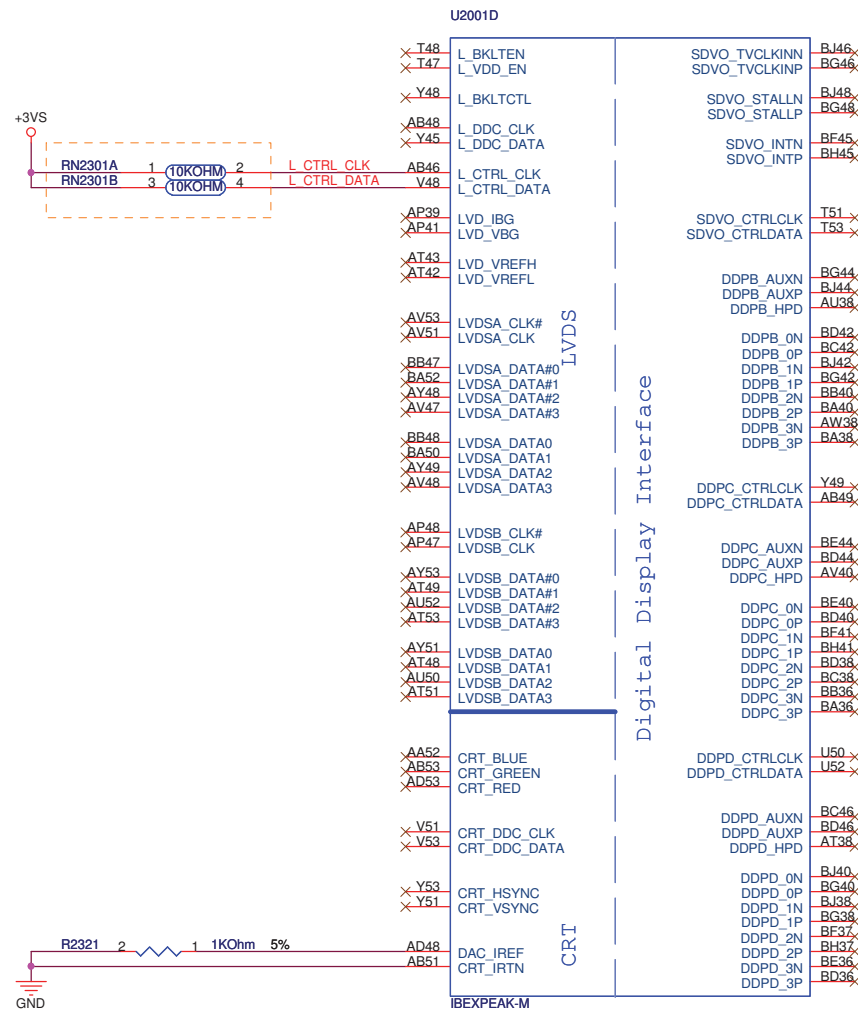
ASUS		Title : PCH - SATA.HDA	
ASUSTek COMPUTER INC. N96		Engineer: Jerry Mou	
Size	Project Name		Rev
Custom	K72Jr		2.0
Date:	Fri, Dec 11, 2009	Sheet	20 of 99

<http://laptop-motherboard-schematic.blogspot.com/>



DG R1.1, page 43:
The pull-up resistor value for SML0DATA and SML0CLK has been updated from 4.7 K $\pm 5\%$ to 2.2 K $\pm 5\%$ to support 400-kHz bus speed





Port	Strap	How to enable the port	How to Disable the Port
LVDS	L_DDC_DATA	Pulled the signal high to 3.3V through 2.2K Ohm resistor	NC
Port B	SDVO_CTRLDATA	Pulled the signal high to 3.3V through 2.2K Ohm resistor	NC
Port C	DDPC_CTRLDATA	Pulled the signal high to 3.3V through 2.2K Ohm resistor	NC
Port D	DDPD_CTRLDATA	Pulled the signal high to 3.3V through 2.2K Ohm resistor	NC
eDP on CPU	CFG[4]	Pulled the signal down to the GND through a 3.3K ohm resistor	NC

Title : PCH - LVDS,CRT

ASUSTeK COMPUTER INC. NB6
 Engineer: Jerry Mou

Size	Project Name	Rev
Custom	K72Jr	2.0

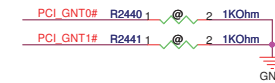
Date: Friday, December 11, 2009
 Sheet 23 of 99

GNT0#,GNT1#: Boot BIOS Strap.

Boot BIOS Strap

PCI_GNT1#	PCI_GNT0#	Boot BIOS Location
0	0	LPC
0	1	PCI
1	0	Reserved
1	1	SPI (PCH)

Sampled on rising edge of PWROK.



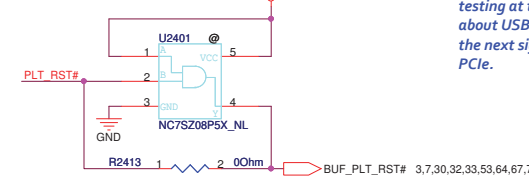
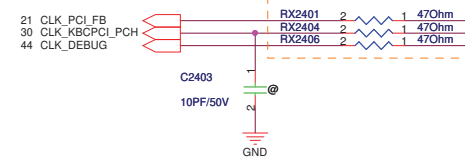
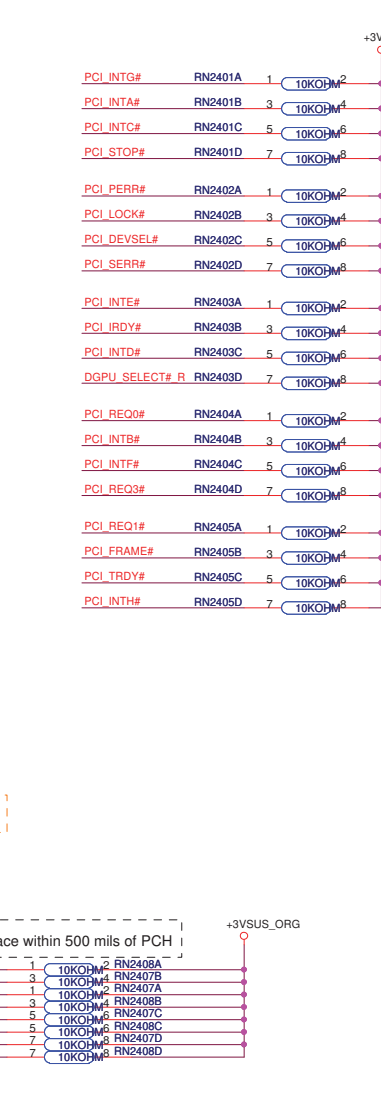
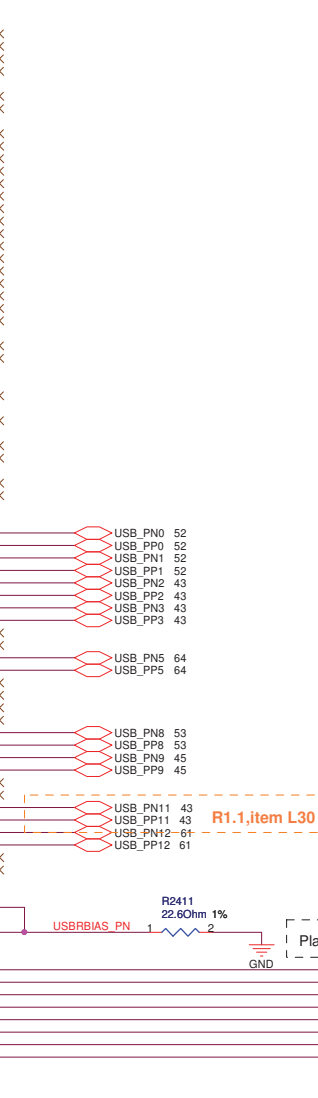
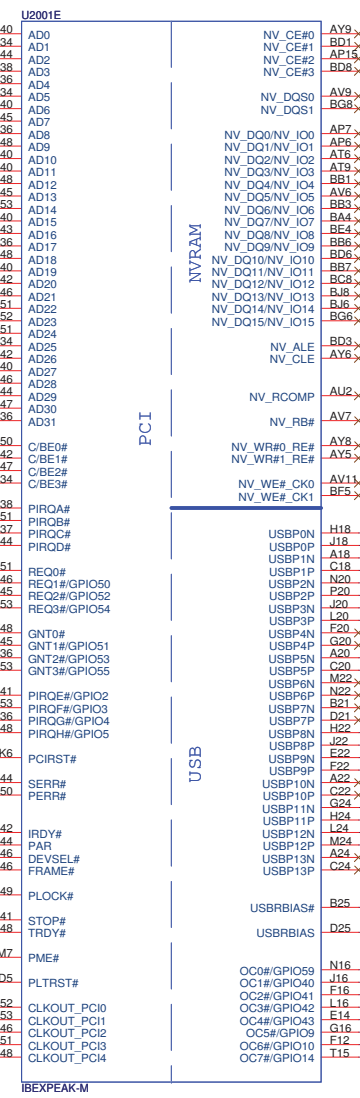
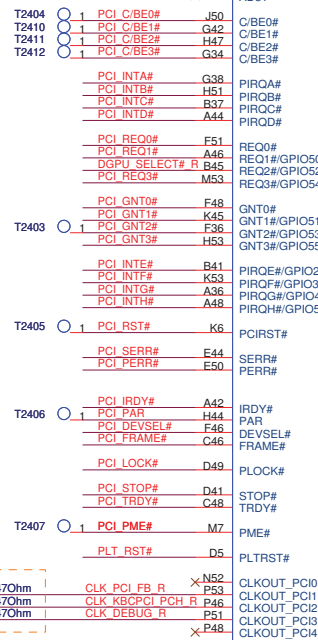
GNT3#: A16 swap override Strap/ Top-Block swap override jumper

Low=Enabled A16 swap override/
Top-Block swap override

High=Default

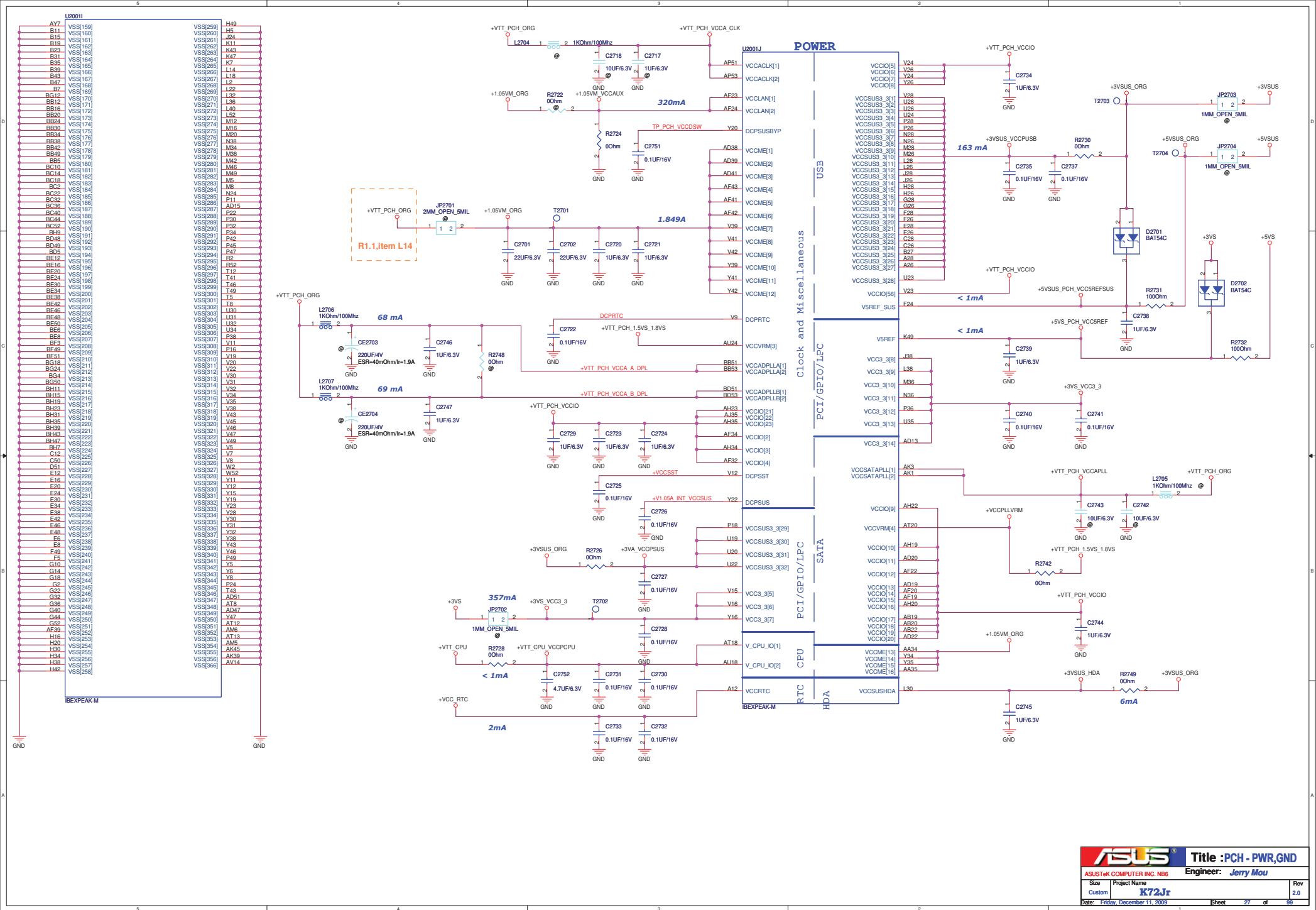


K72J	
0	USB port
1	USB port
2	USB port (D/B)
3	USB port (D/B)
4	
5	MiniCard (Full)
6	
7	
8	MiniCard (Half)
9	Camera
10	
11	Card Reader
12	Bluetooth
13	



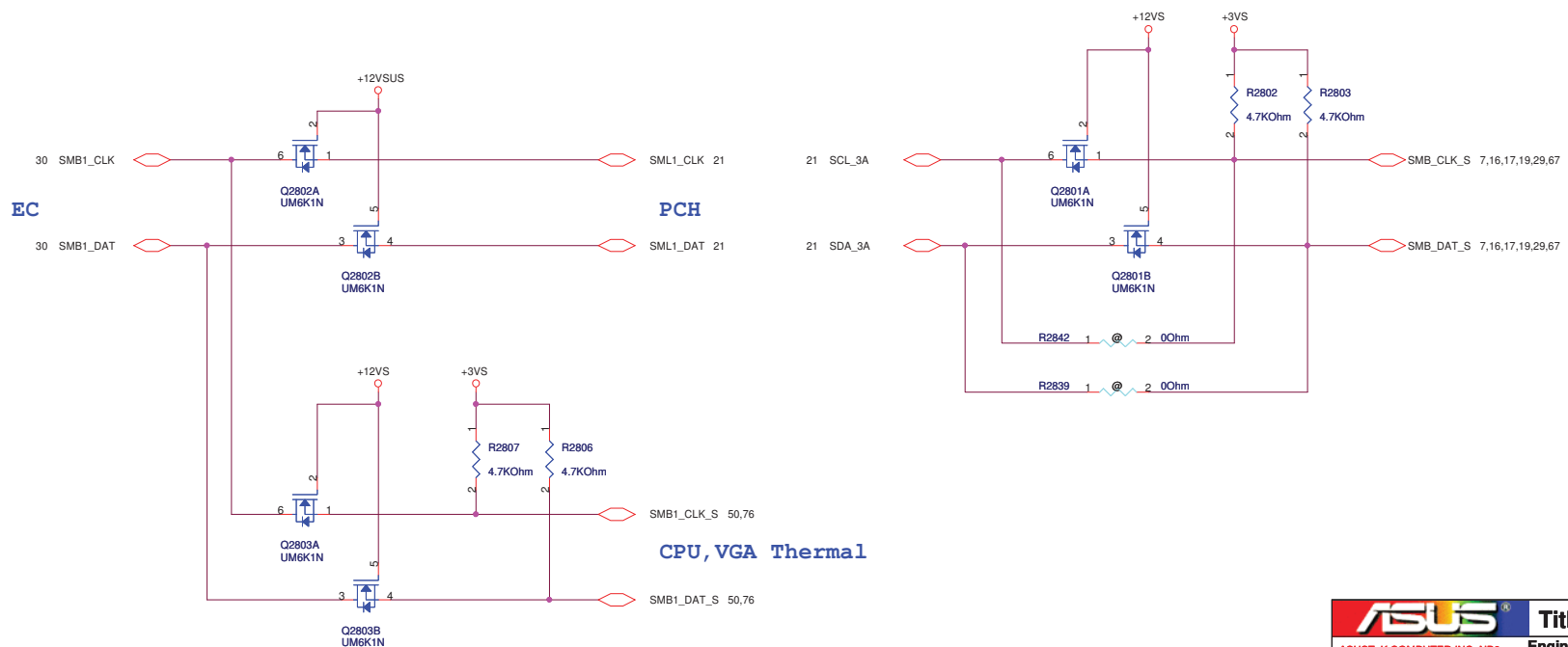
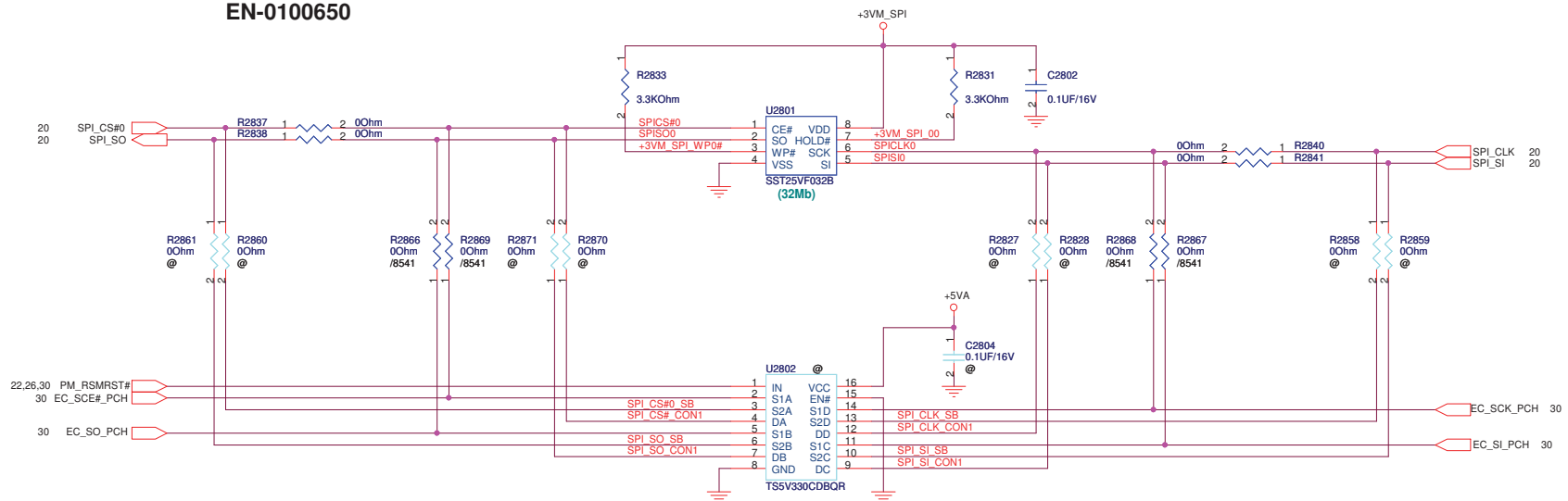
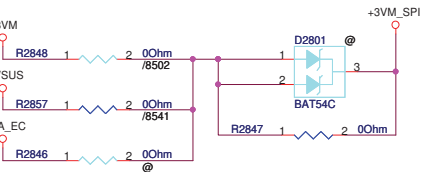
MoW 02, 2009
Intel recommends that customers do not perform USB or SATA Signal Quality testing at this time. Ibox Peak Sightings Report Rev. 004 contains a new sighting about USB Eye Diagram Failure. A similar sighting about SATA will be available in the next sightings report release. Customers may begin Signal Quality testing on PCIe.

ASUS		Title : PCH - PCI,USB	
ASUSTek COMPUTER INC. N86		Engineer: Jerry Mou	
Size Custom	Project Name K72Jr	Rev 2.0	
Date: Friday, December 11, 2009	Sheet 24	of 99	

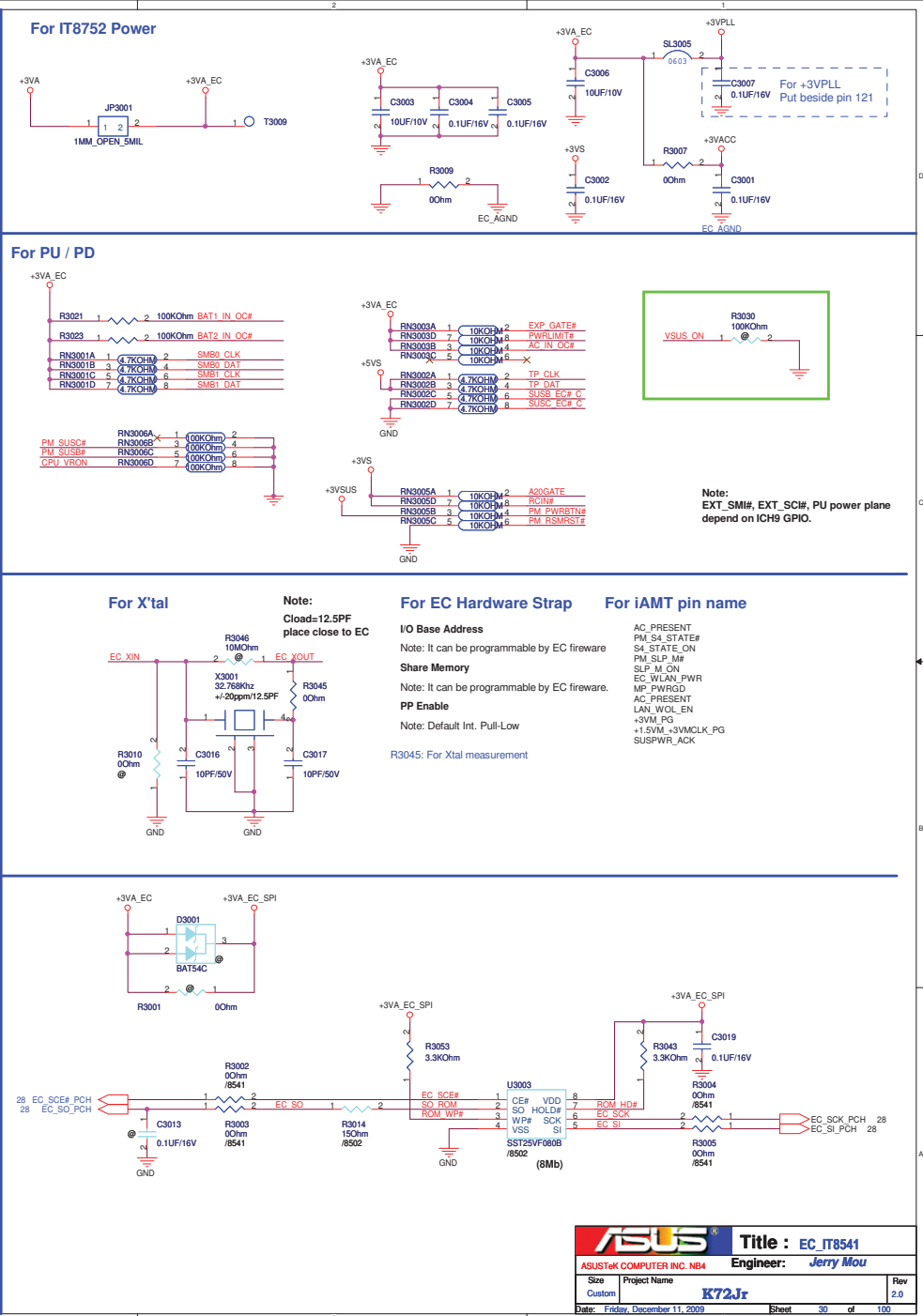
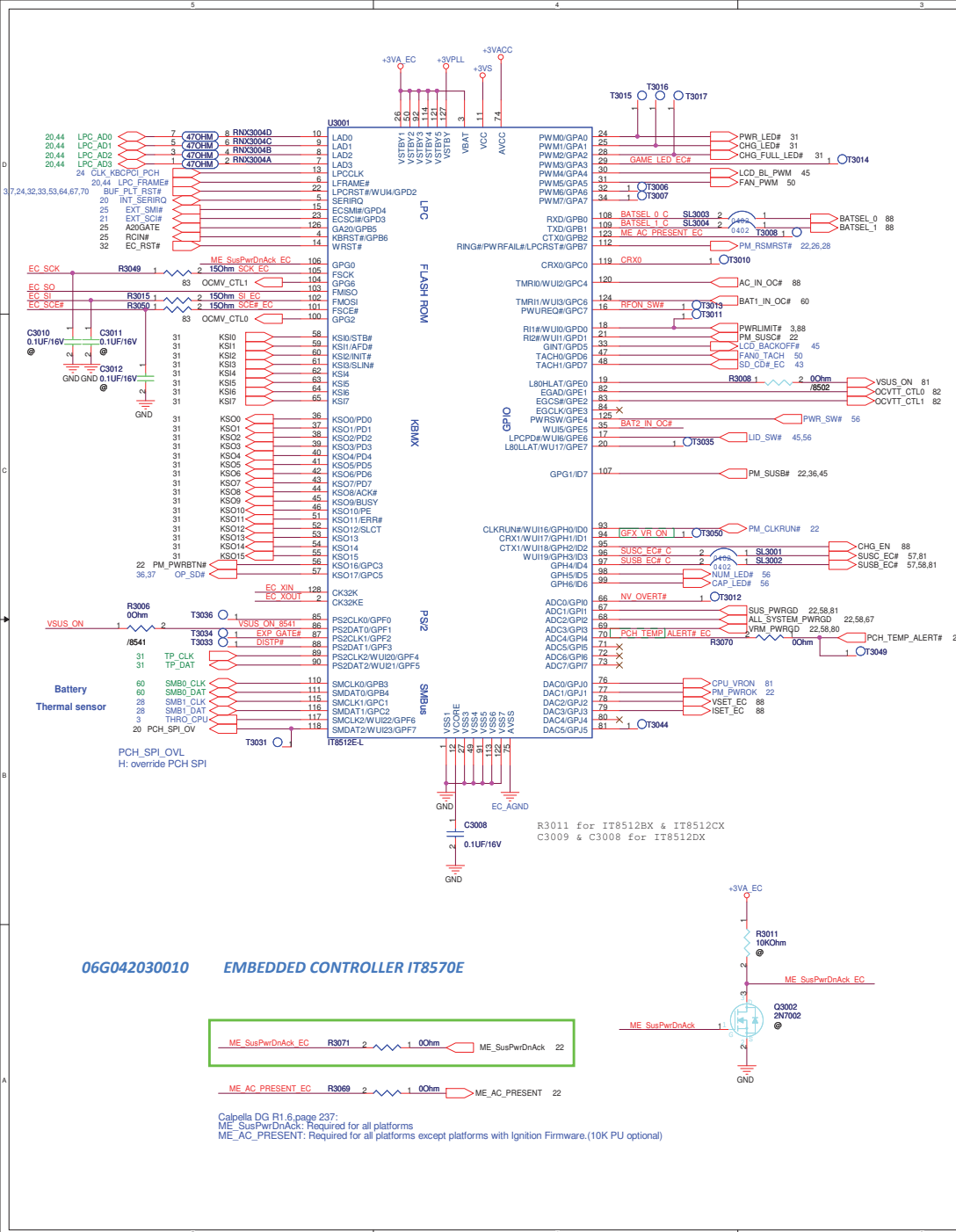


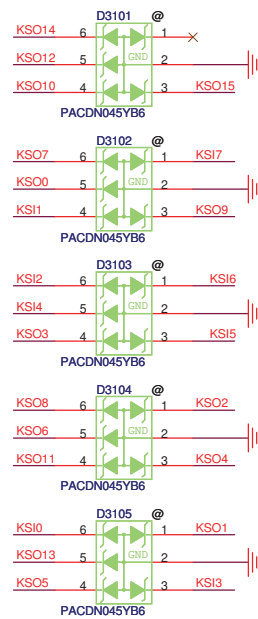
PCH SPI ROM

EN-0100650

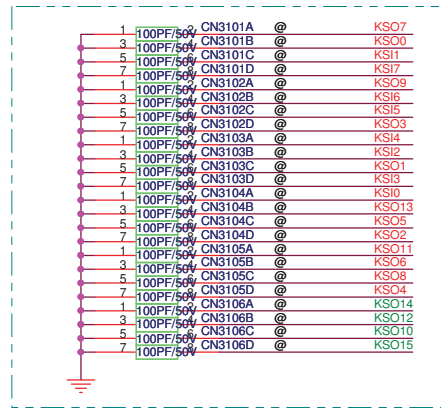


<http://laptop-motherboard-schematic.blogspot.com/>



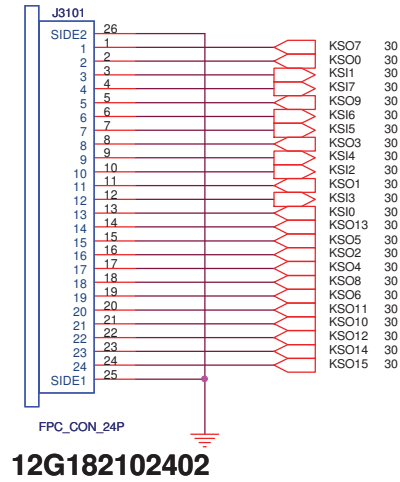


EMI



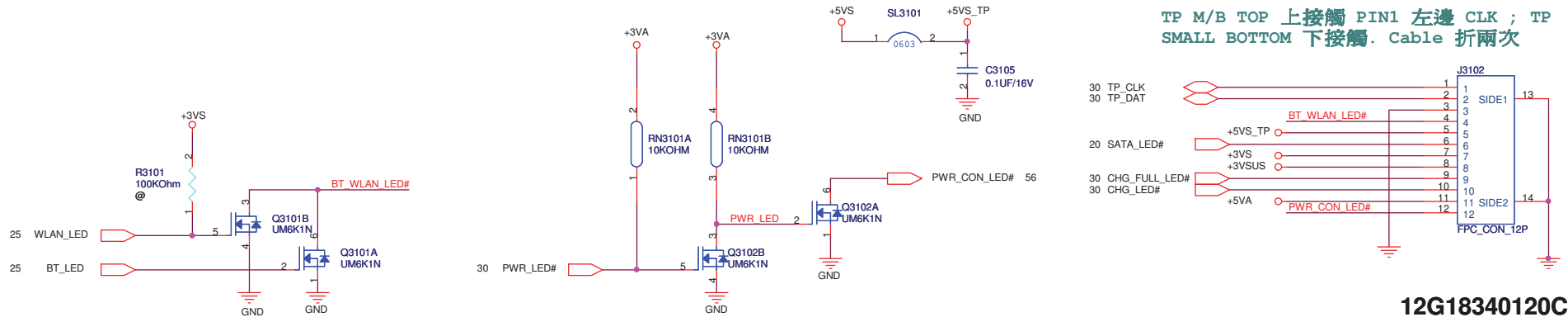
Keyboard

TOP connector 下接觸
PIN1上面 KSO7 ; 下面 KSO24



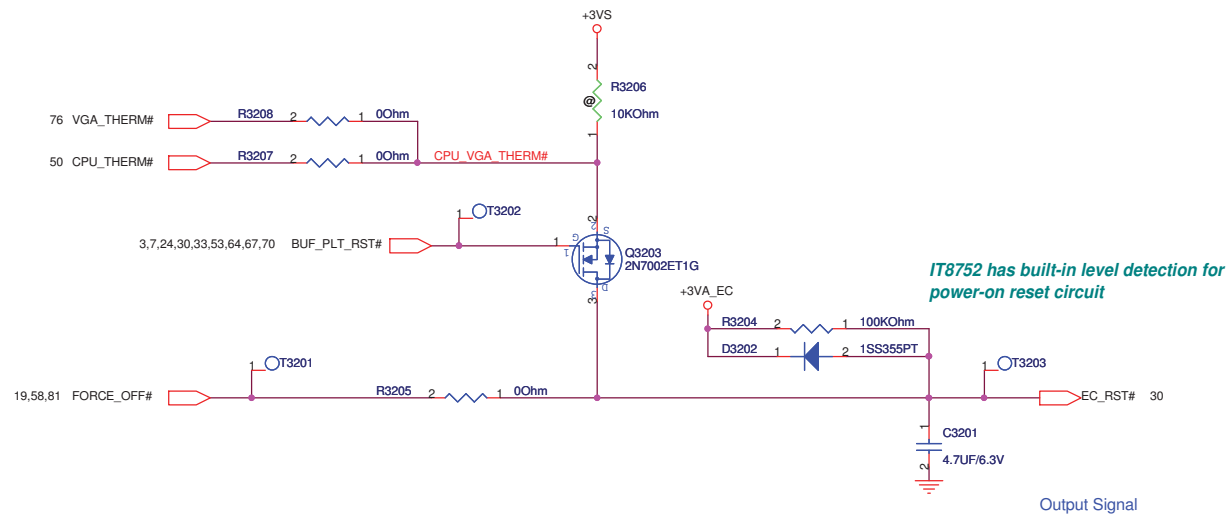
12 Pin Touch-Pad Conn.

TP M/B TOP 上接觸 PIN1 左邊 CLK ; TP
SMALL BOTTOM 下接觸. Cable 折兩次



ASUS		Title : EC_IT8541(2/2)KB, TP	
ASUSTek COMPUTER INC. NB4		Engineer: Ryan_Wang	
Size B	Project Name K72Jr		Rev 2.0
Date: Friday, December 11, 2009		Sheet 31 of 100	

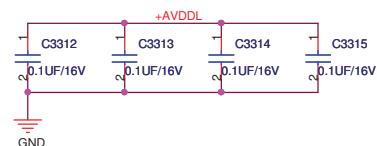
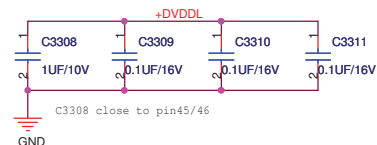
Thermal Policy



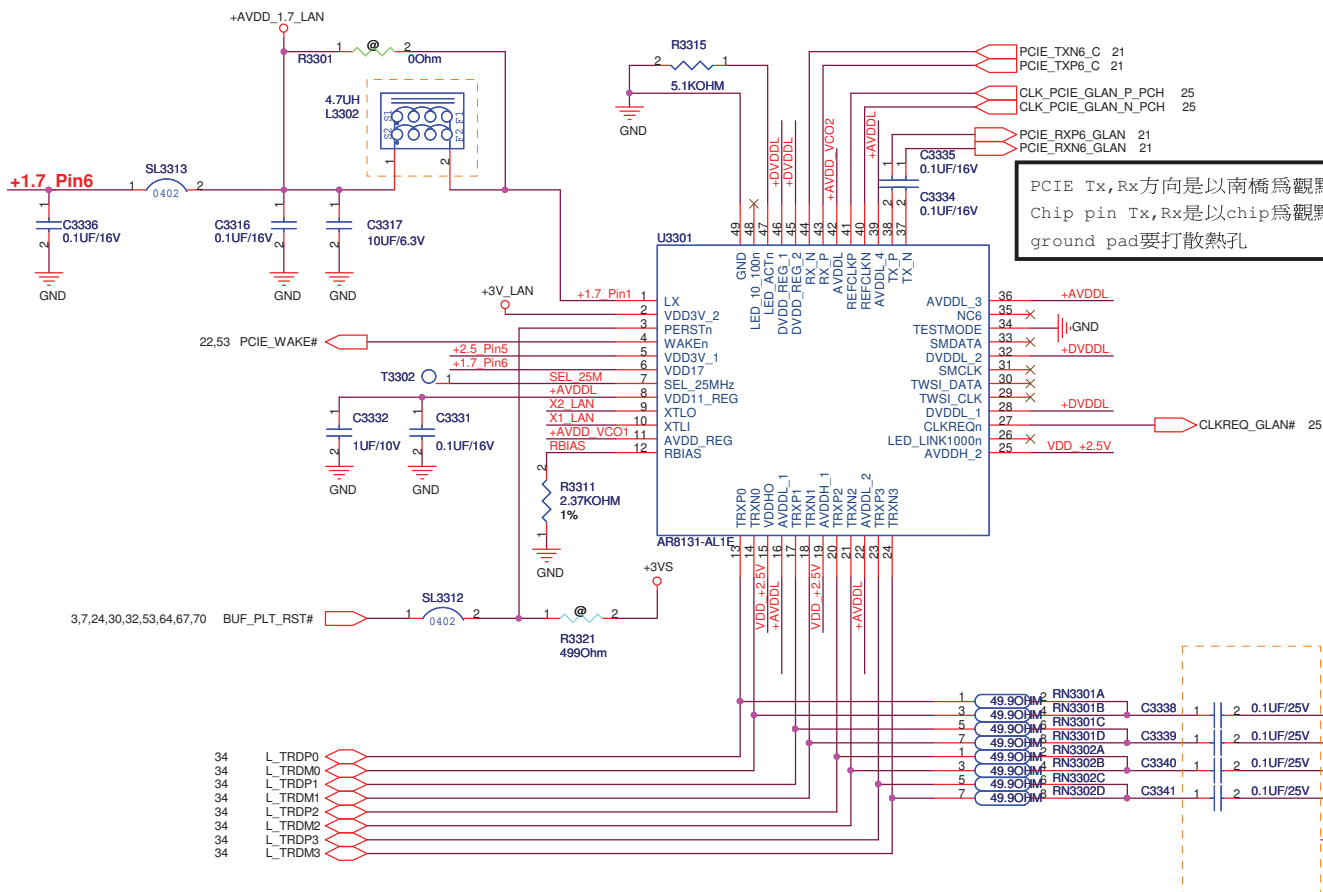
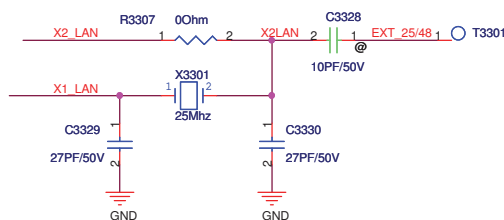
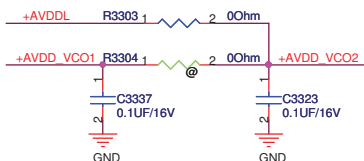
ASUS		Title : RST_Reset Circuit	
ASUSTeK COMPUTER INC. NB4		Engineer: Jerry Mou	
Size B	Project Name K72Jr		Rev 2.0
Date: Friday, December 11, 2009		Sheet 32 of 100	

C3301 C3302 C3303 C3304 close to pin2

C3305 close to pin15

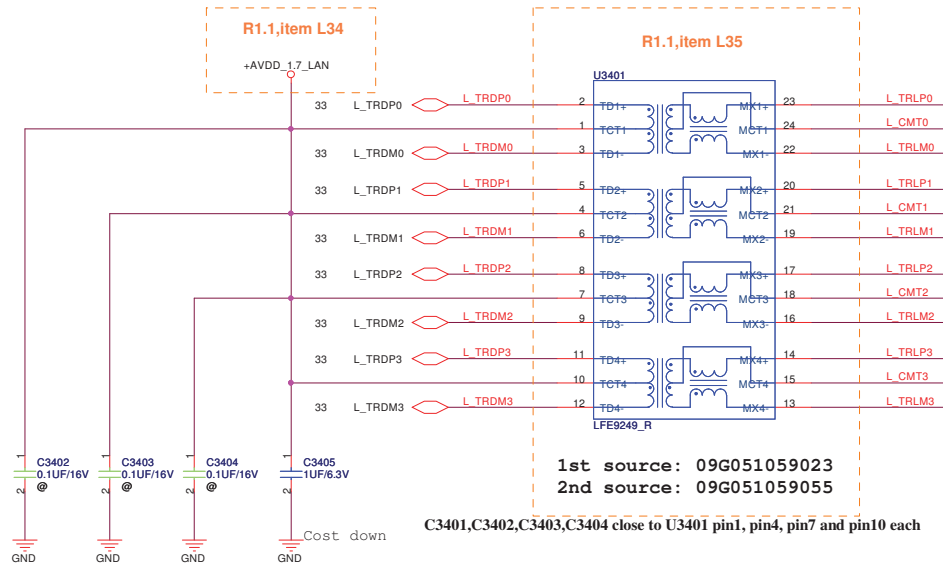


AR8131/25MHz: Remove C3328

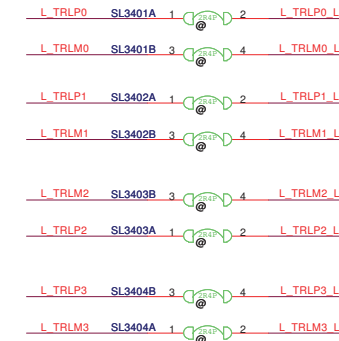
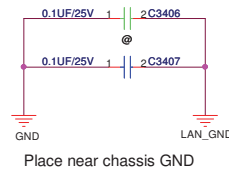
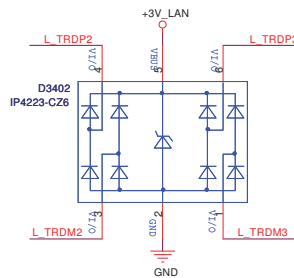
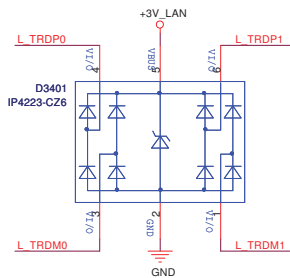
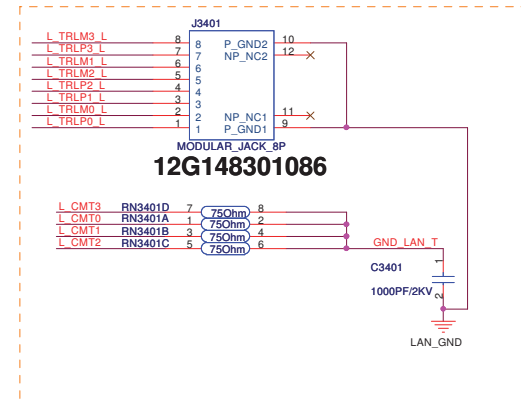


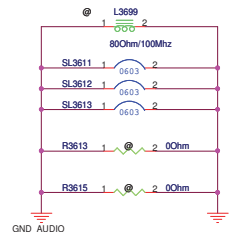
PCIE Tx,Rx方向是以南橋為觀點
Chip pin Tx,Rx是以chip為觀點
ground pad要打散熱孔

		Title : LAN-AR8131	
ASUSTek® COMPUTER INC. NB4		Engineer: Jerry Mou	
Size B	Project Name K72Jr	Rev 2.0	
Date: Fridav, December 11, 2009		Sheet 33 of 100	

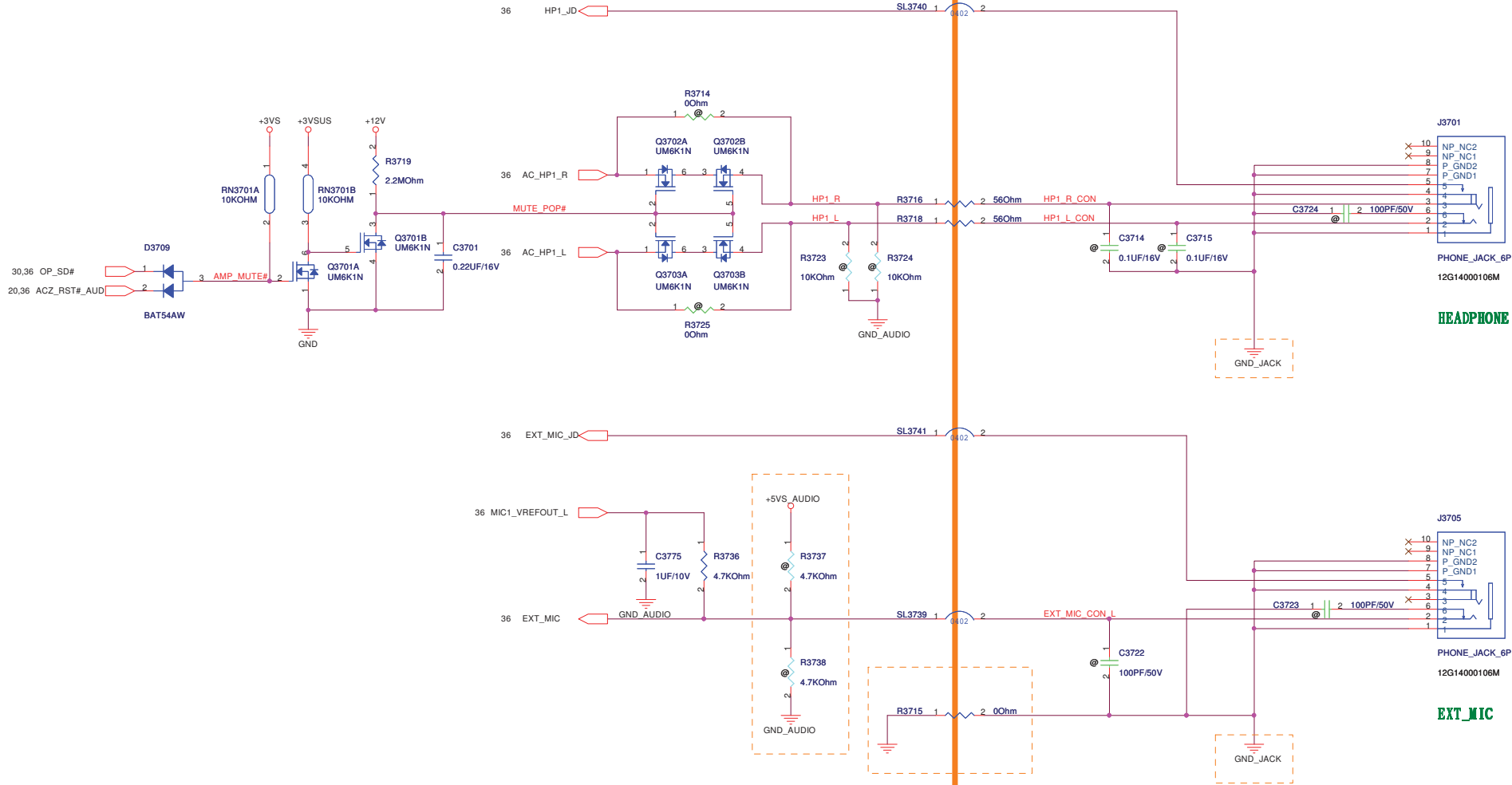


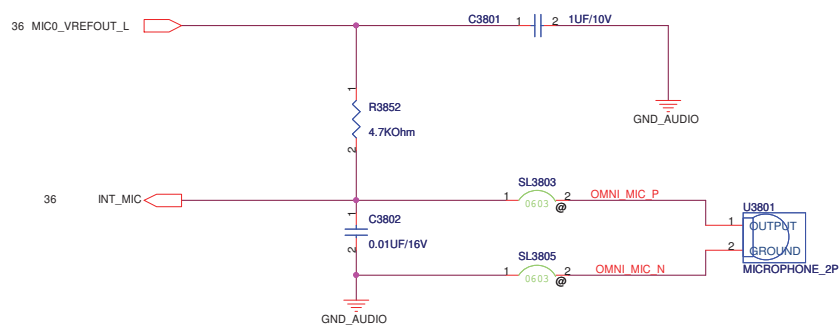
connector without modem



[illegible]

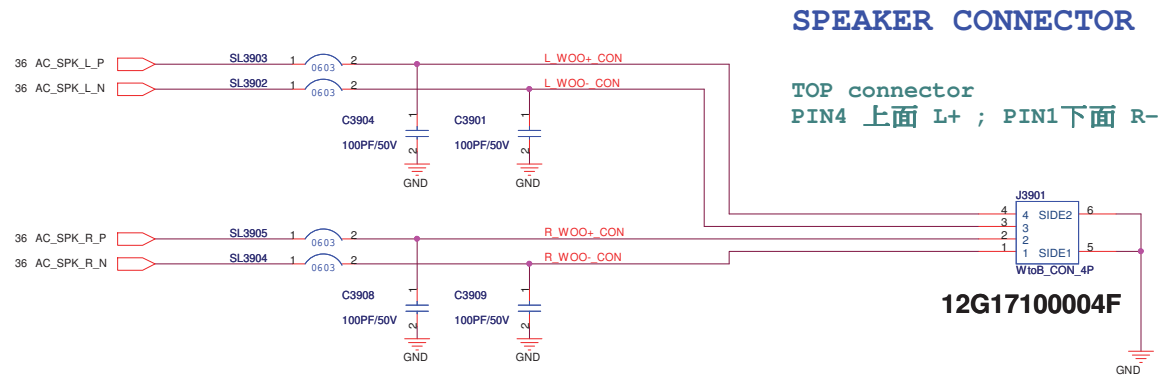
ASUS		Title : CODEC IDT92HD81	
ASUSTeK COMPUTER INC. NB2		Engineer: Jerry Mou	
Size Custom	Project Name K72Jr	Rev 2.0	
Date: Friday, December 11, 2009	Sheet	36	of 100

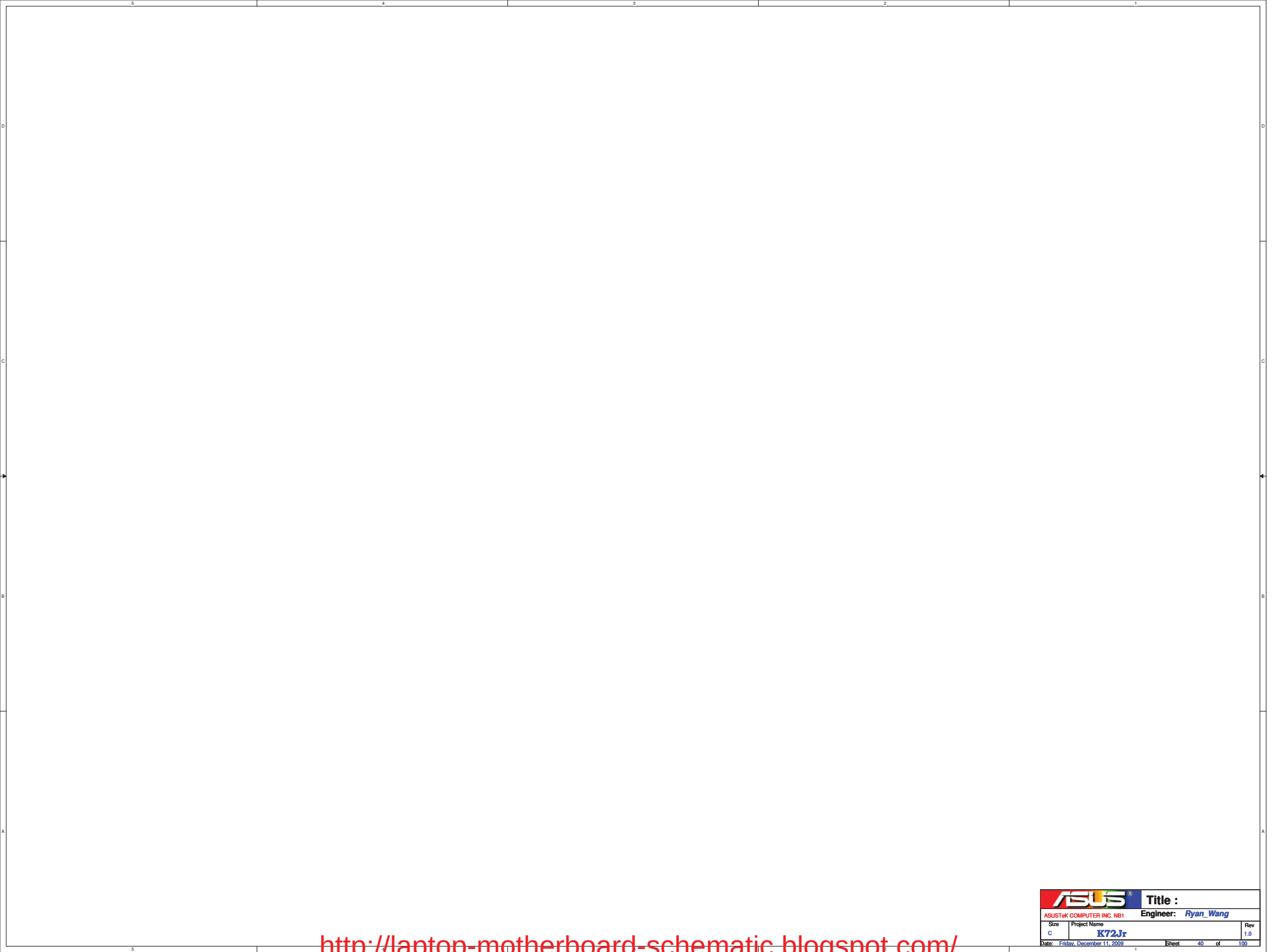




<Variant Name>

ASUS		Title : AUD_I_MIC	
ASUSTeK COMPUTER INC. NB2		Engineer: Jerry Mou	
Size Custom	Project Name K72Jr		Rev 2.0
Date: Friday, December 11, 2009		Sheet	38 of 100





<http://laptop-motherboard-schematic.blogspot.com/>

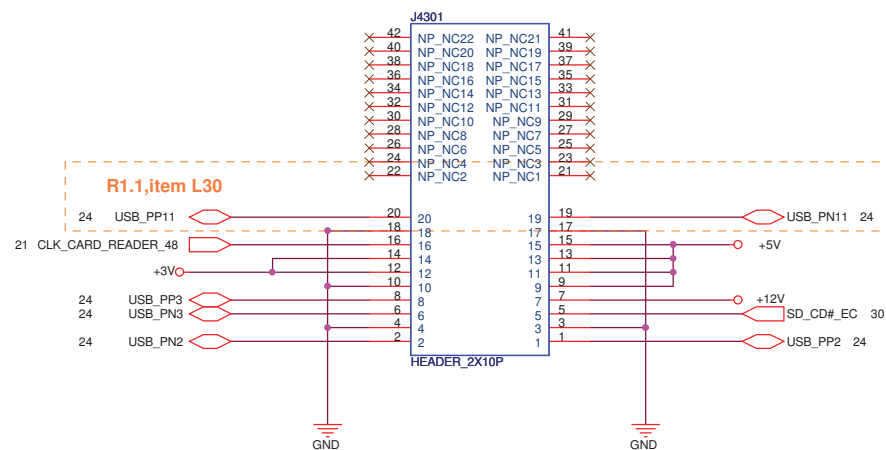
		Title :	
ASUSTeK COMPUTER INC. NB1		Engineer: <i>Ryan_Wang</i>	
Size	Project Name		Rev
C	K72Jr		1.0
Date: Friday, December 11, 2009		Sheet	40 of 100

K72J USB Board_20 Pin CON

TOP connector

左上 PIN20 USB_PP4 ; 右上 PIN19 USB_PN4

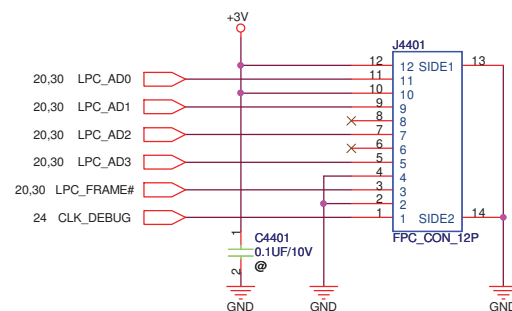
左下 PIN2 USB_PN2 ; 右下 PIN1 USB_PP2



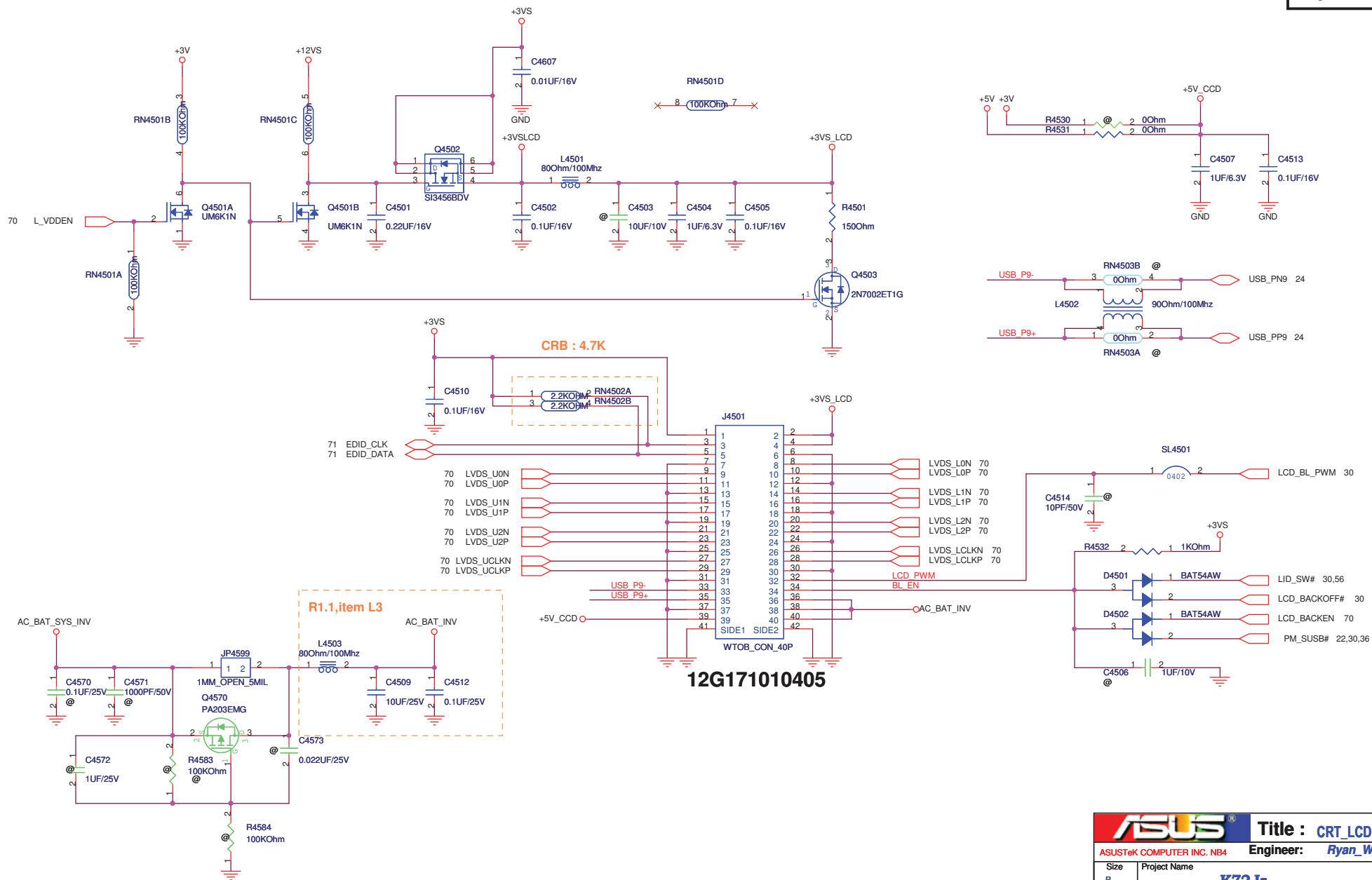
2nd : 12G06120020A

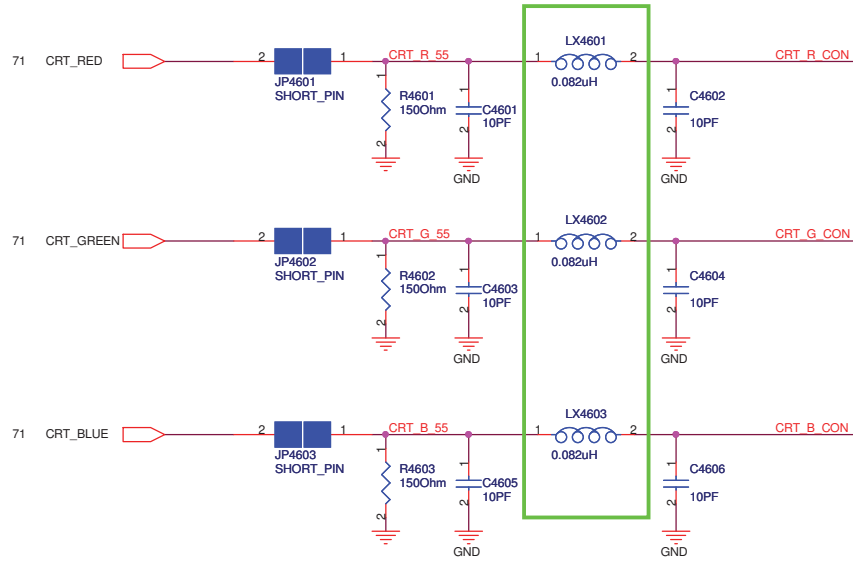
ASUS		Title :	
ASUSTeK COMPUTER INC. NB4		Engineer: <i>Ryan_Wang</i>	
Size B	Project Name K72Jr		Rev 2.0
Date: Friday, December 11, 2009		Sheet 43 of 100	

LPC Debug Port

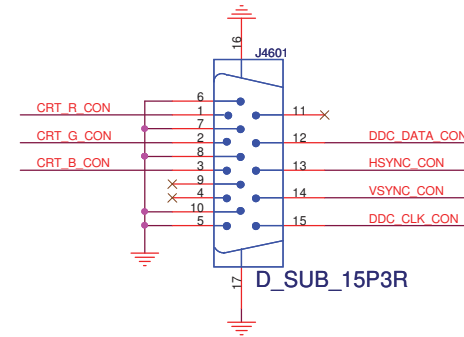
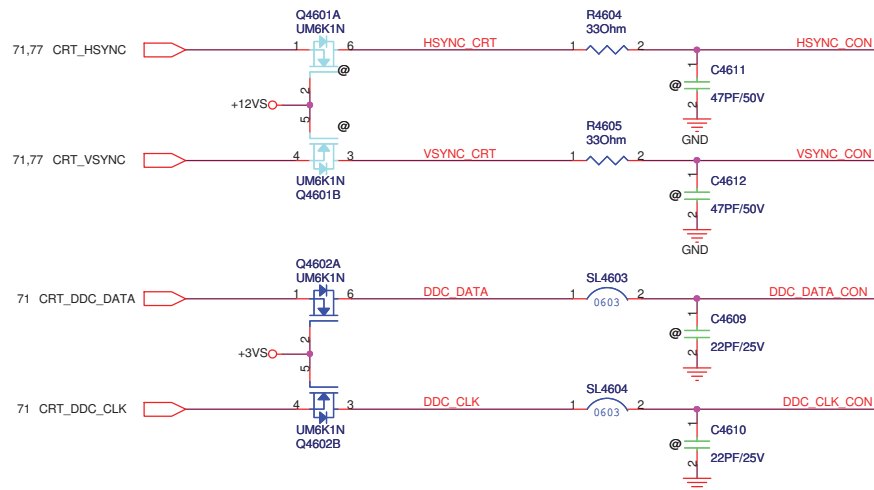


TP M/B TOP 下接觸 PIN1 上面 CLK ; Pin 12 下面 +3V

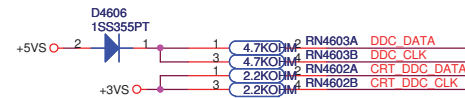
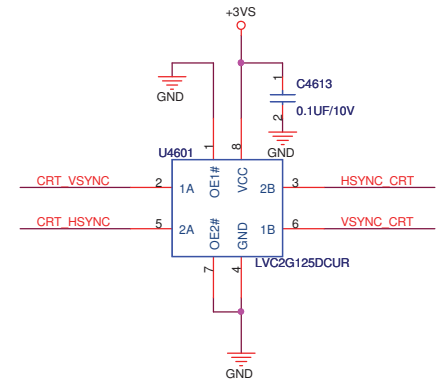




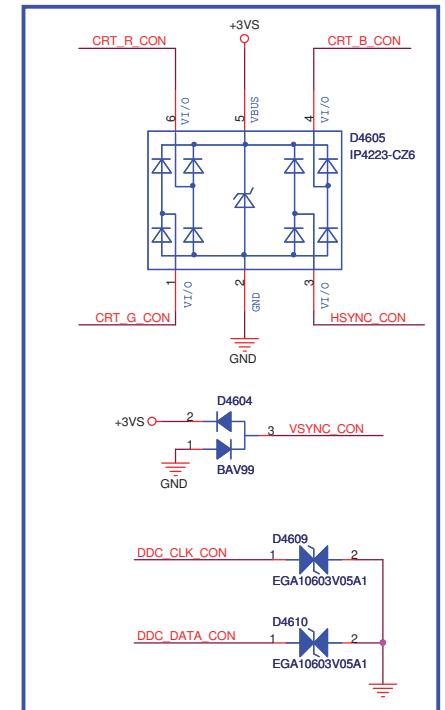
09G013047105



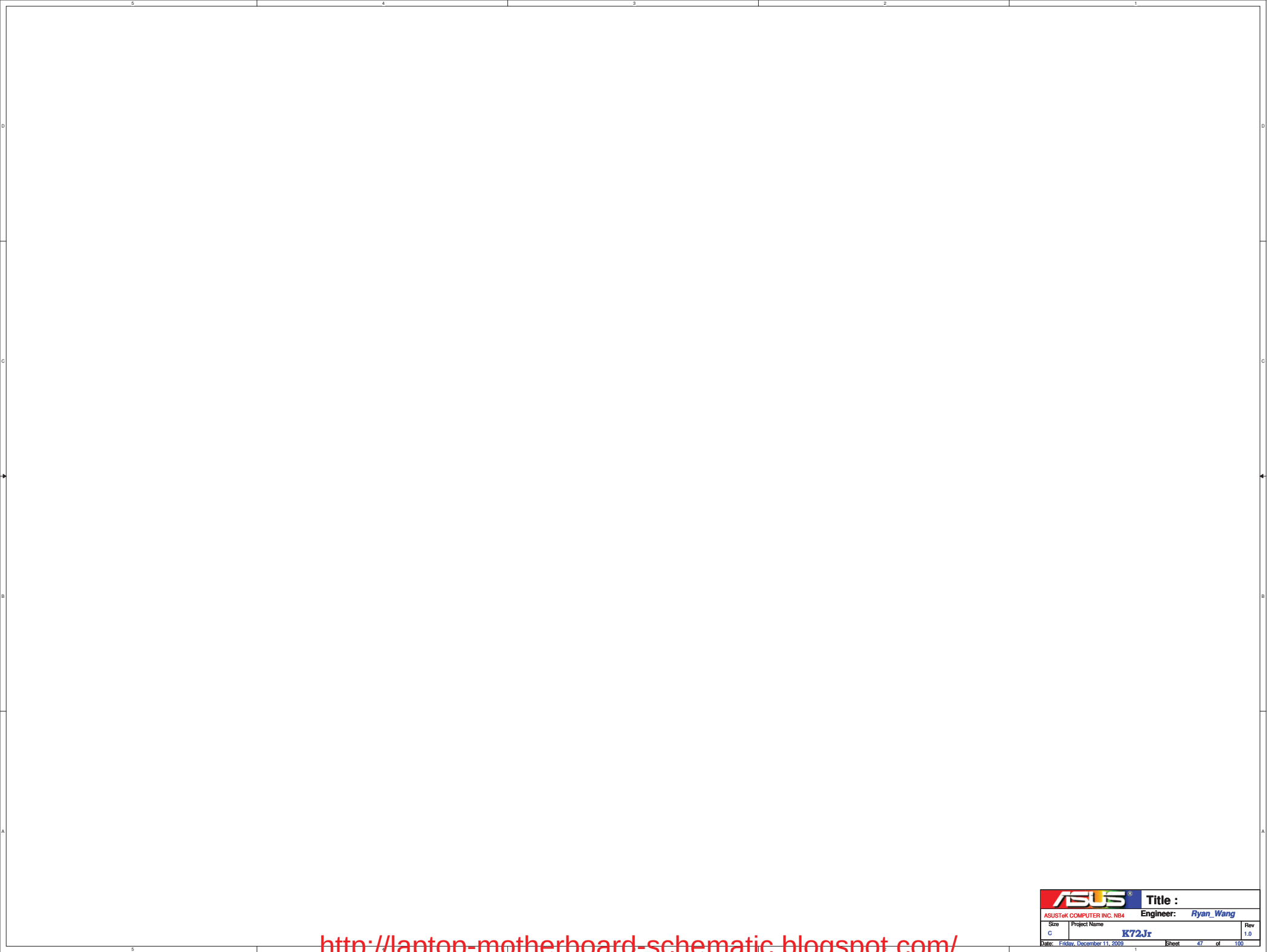
12G101102155



PLACE ESD Diodes near connector



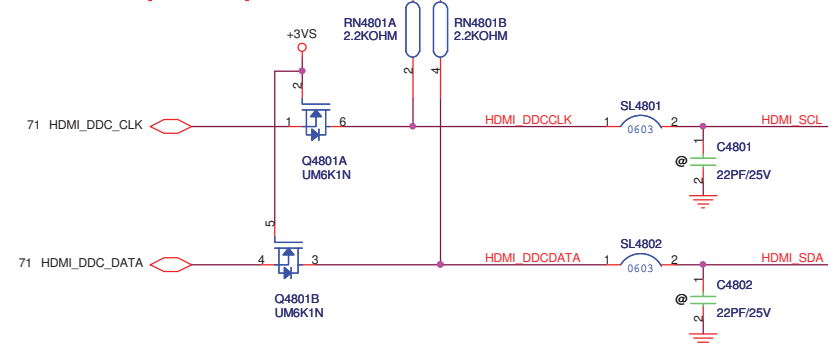
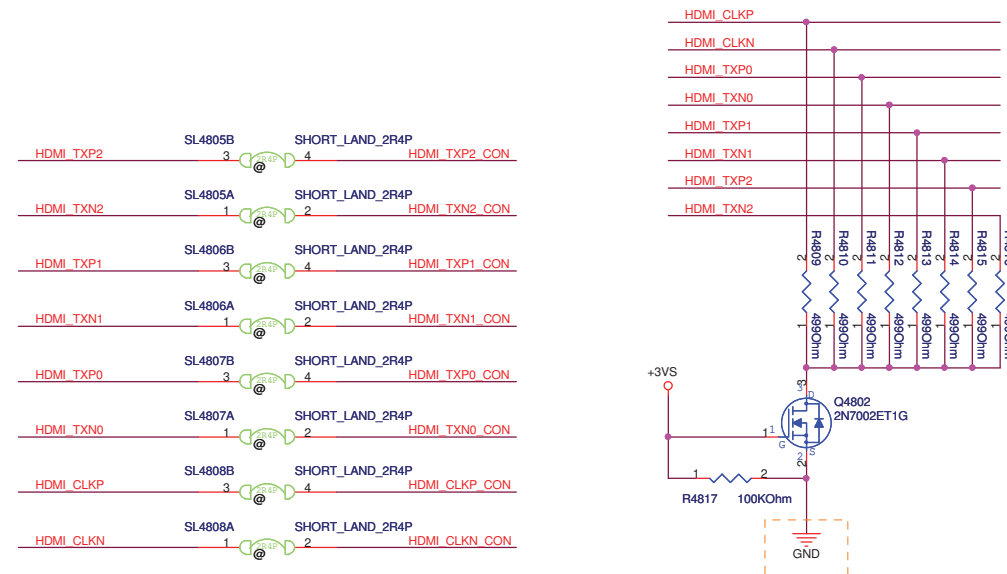
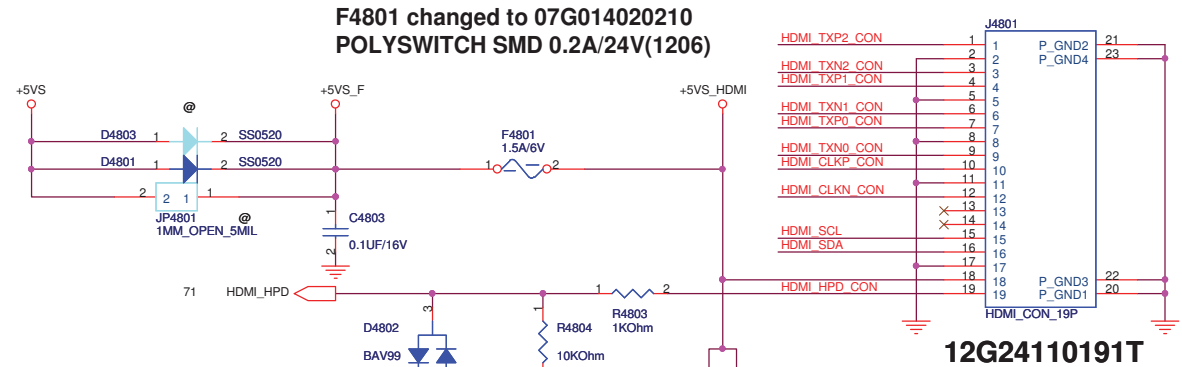
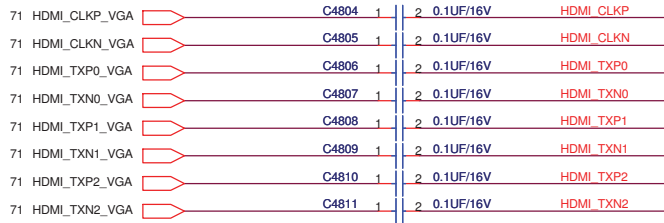
ASUS		Title : CRT_D-Sub	
ASUSTeK COMPUTER INC. NB4		Engineer: Ryan_Wang	
Size B	Project Name K72Jr	Rev 2.0	
Date: Friday, December 11, 2009		Sheet 46 of 100	



<http://laptop-motherboard-schematic.blogspot.com/>

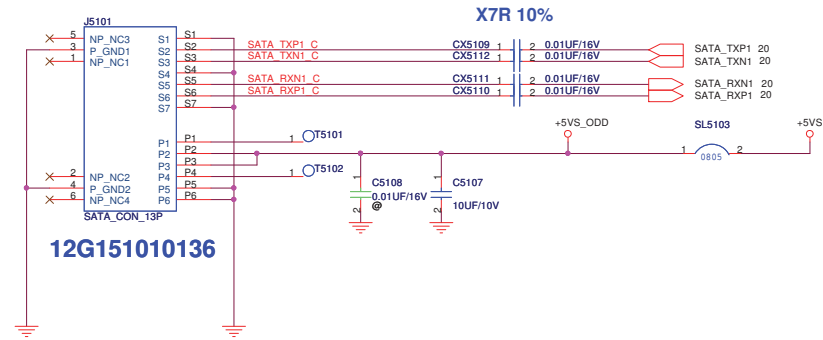
		Title :	
ASUSTeK COMPUTER INC. NB4		Engineer: <i>Ryan_Wang</i>	
Size	Project Name		Rev
C	K72Jr		1.0
Date: Friday, December 11, 2009		Sheet	47 of 100

PLACE HDMI 0.1uF near connector J4801

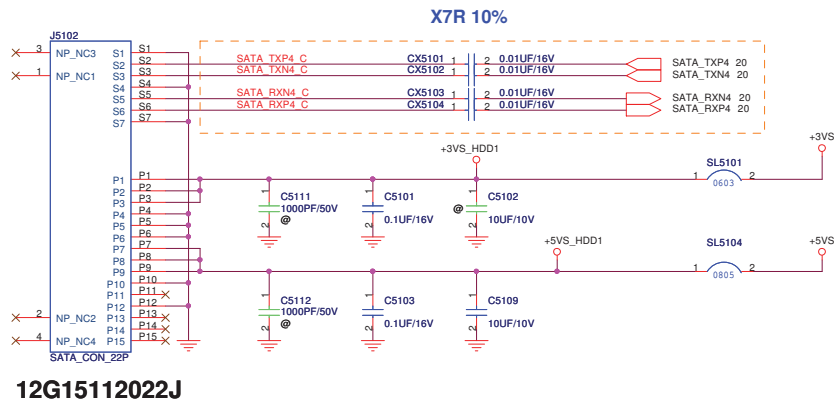


		Title : <u>TV_HDMI</u>	
ASUSTek COMPUTER INC. NB4		Engineer: <u>Ryan_Wang</u>	
Size B	Project Name K72Jr	Rev 2.0	
Date: <u>Monday, February 01, 2010</u>		Sheet	48 of 100

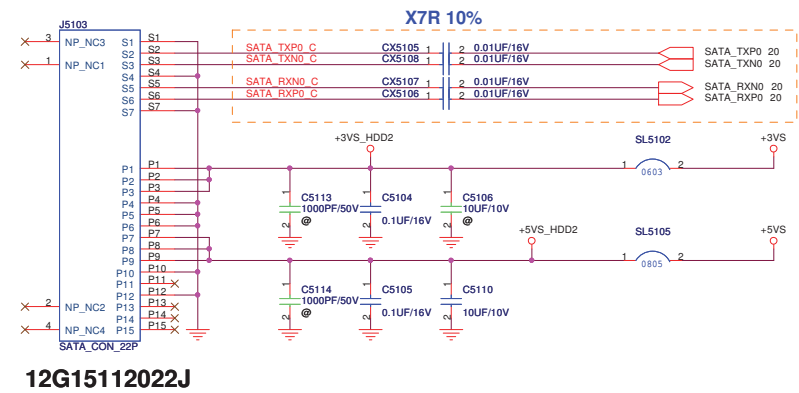
ODD

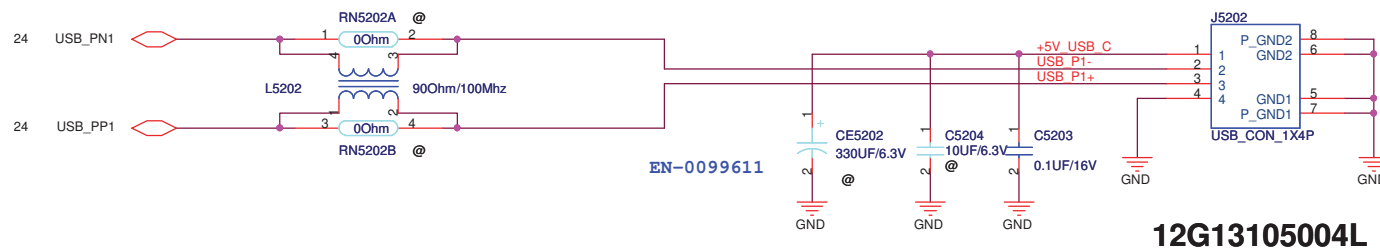
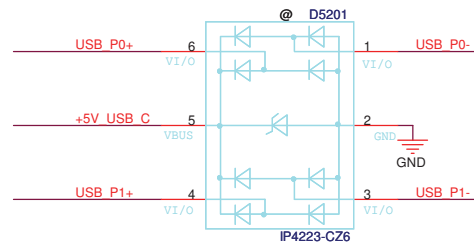
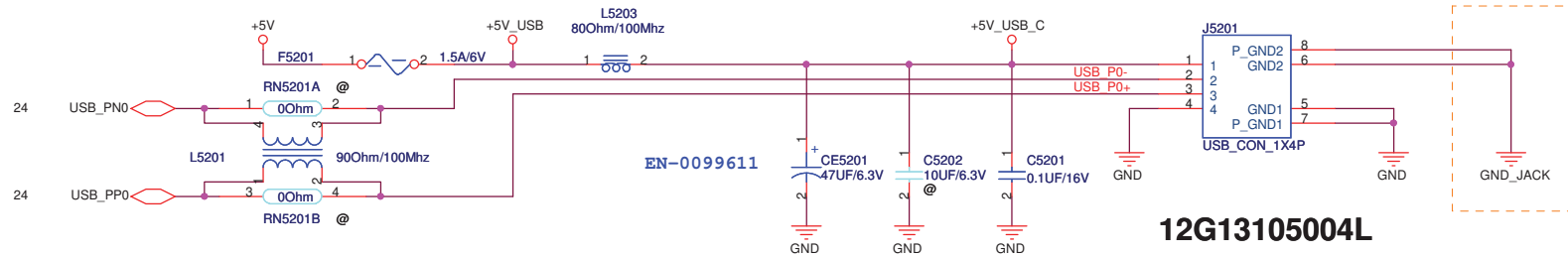


HDD (2nd) Right side



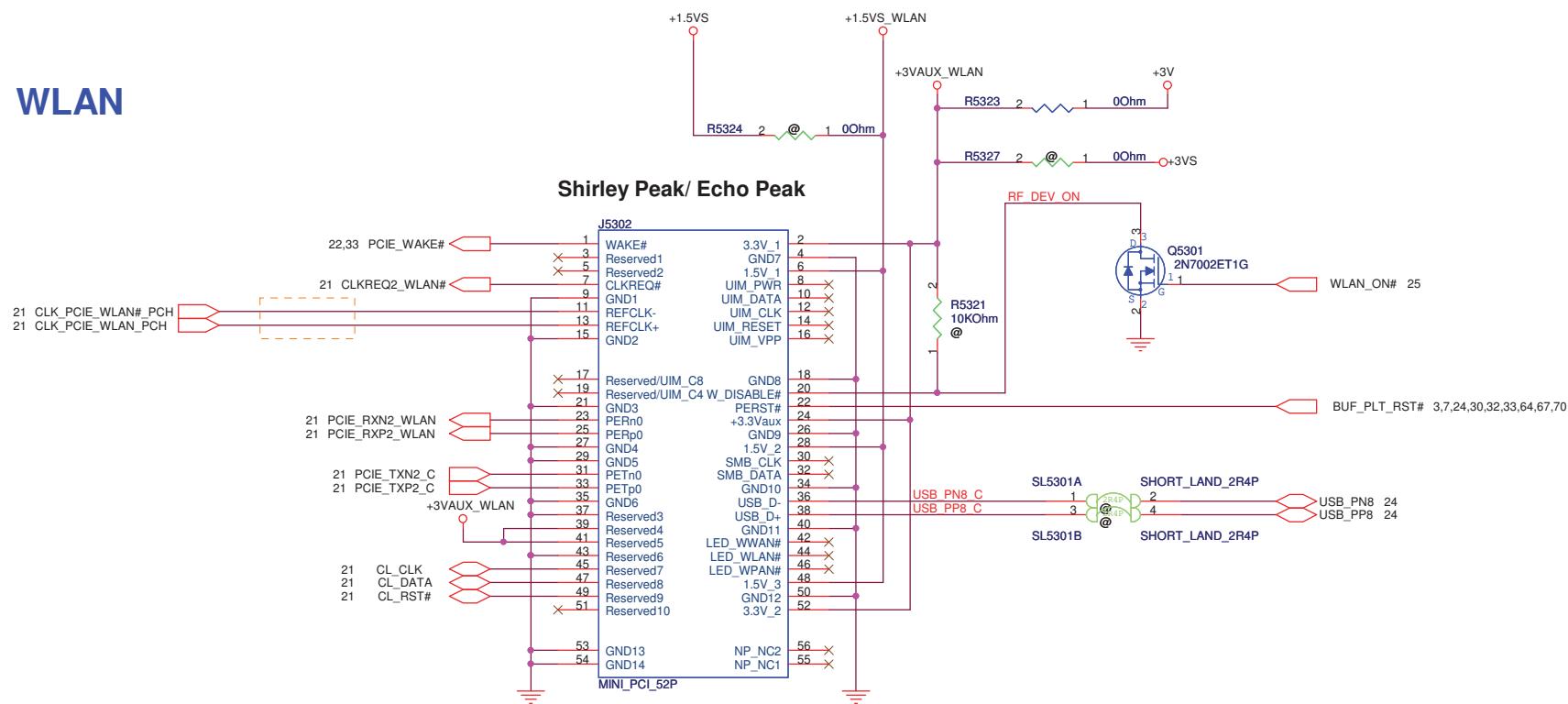
HDD (1st) Left side





		Title : USB Port	
ASUSTeK COMPUTER INC. NB4		Engineer: Jerry Mou	
Size Custom	Project Name K72Jr		Rev 2.0
Date: Friday, December 11, 2009		Sheet 52 of 100	

WLAN

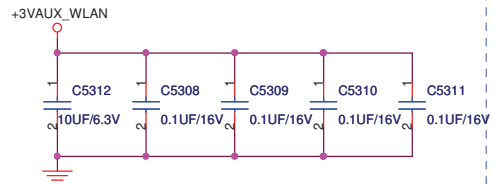


12G03011052N

WLAN +3VAUX bypass capactor:

Place 0.1UF near pin 2, 24, 52, 39 41.

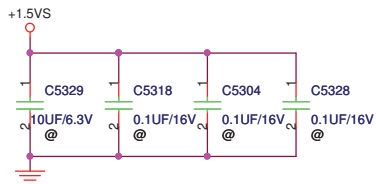
Place 10UF near +3VAUX_WLAN source side.



WLAN +1.5VS bypass capactor:

Place 0.1UF near pin 6,28,48.

Place 10UF near +1.5VS source side.

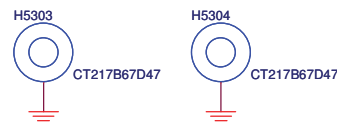


WLAN nuts:

Minicard spec R1.2:

Full size card= 2pcs.

Half size card= 2pcs.

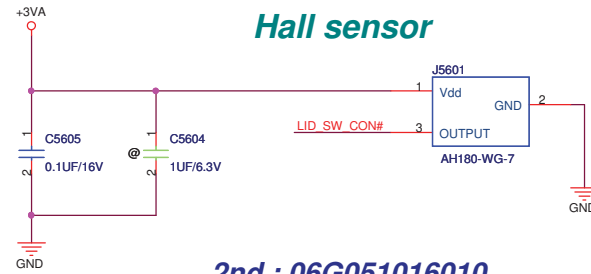
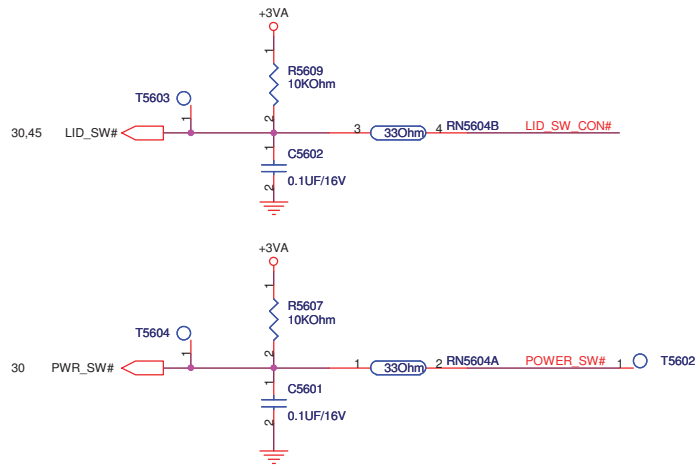


13G021043011

13G021043011

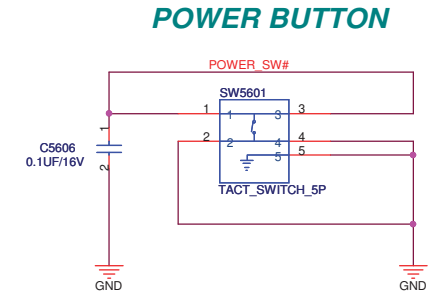
2ND : 13G021085000





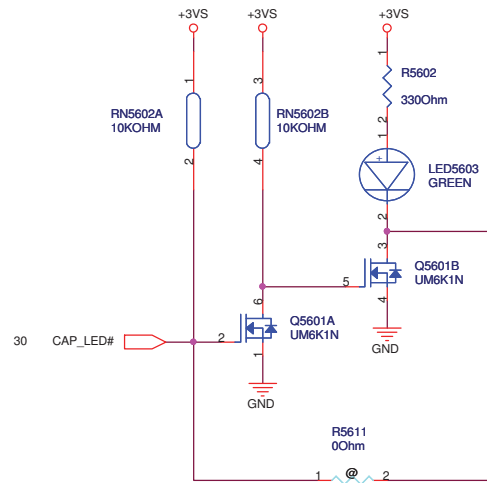
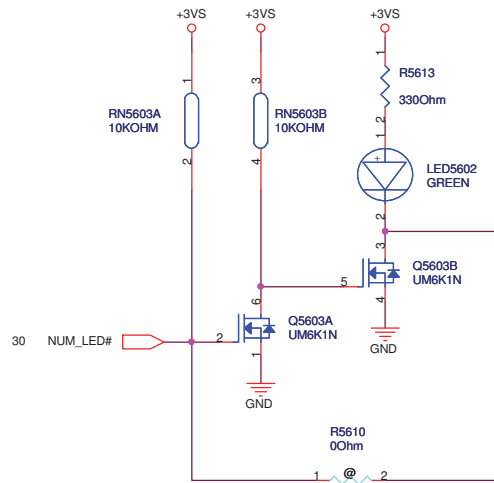
2nd : 06G051016010

(3rd : 06G036022010)



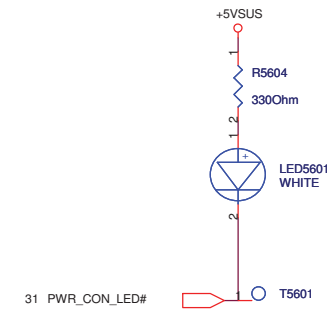
2nd : 07G015200351

(3rd : 07G015500051)

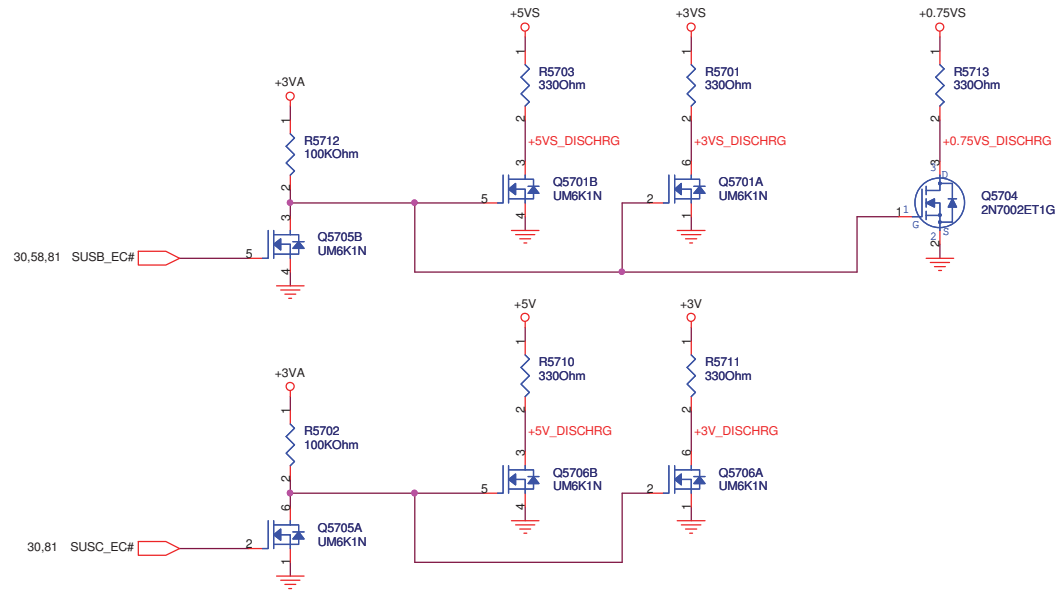


2nd : 07G01570130A

(3rd : 07G015L0042A)

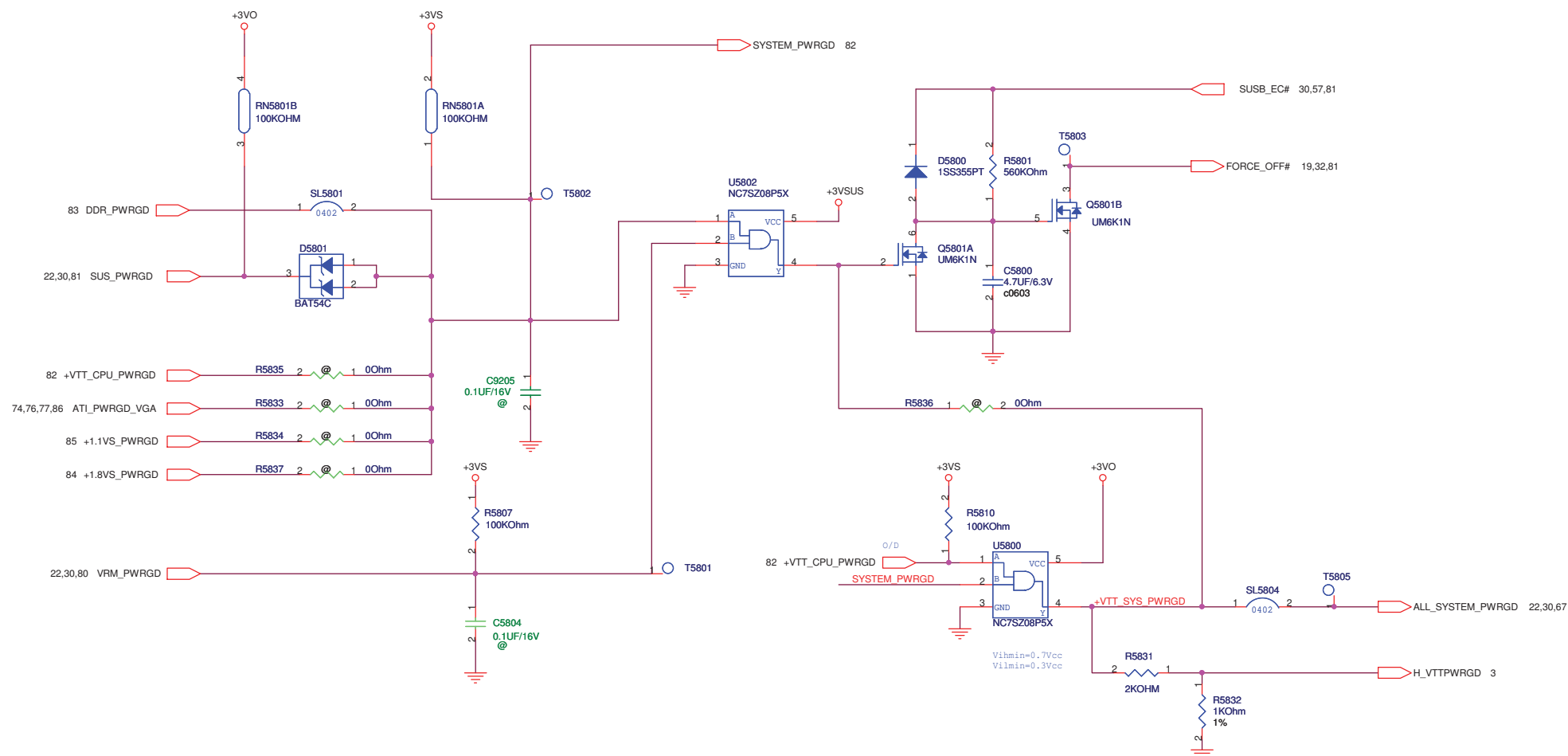


ASUS		Title : LED_Indicator	
ASUSTeK COMPUTER INC. NB4		Engineer: Ryan_Wang	
Size B	Project Name K72Jr		Rev 2.0
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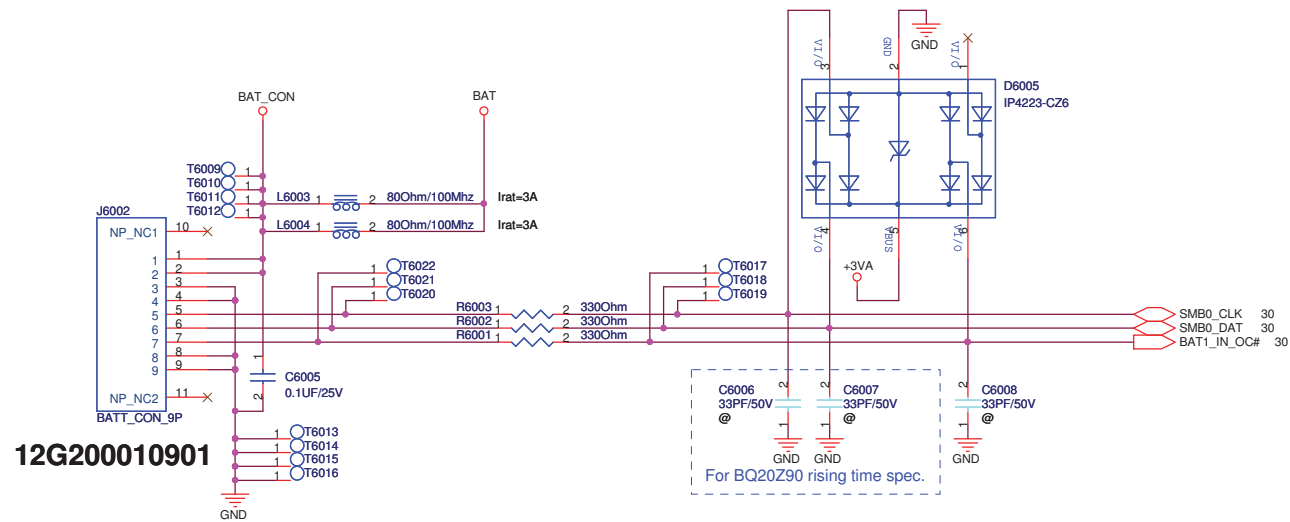
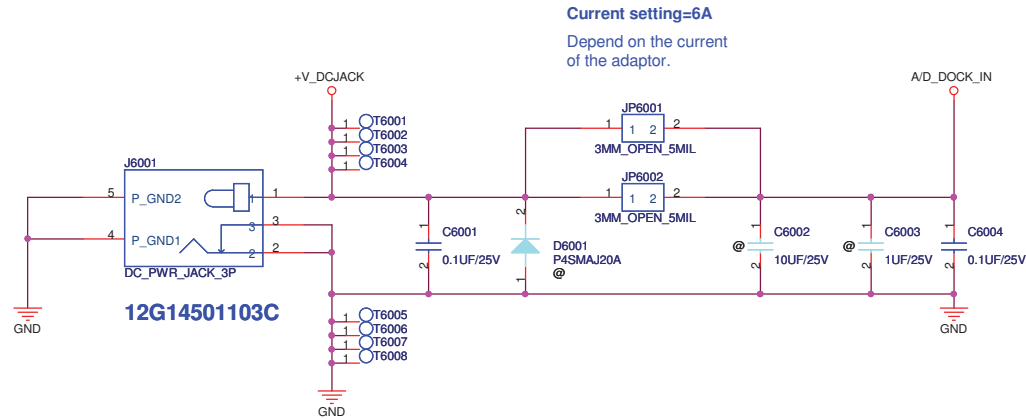


ASUS		Title : DSG_Discharge	
ASUSTeK COMPUTER INC. NB4		Engineer: Ryan_Wang	
Size B	Project Name K72Jr		Rev 2.0
Date: Friday, December 11, 2009		Sheet	57 of 100

POWER GOOD DETECTOR



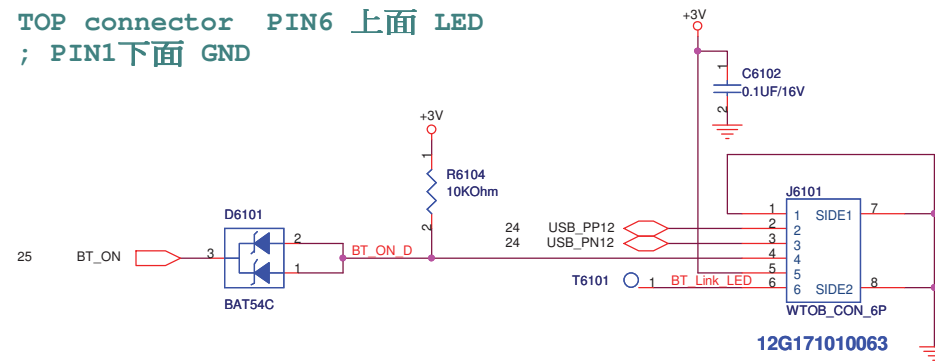
		Title : <i>PCI_****</i>	
ASUSTeK COMPUTER INC. NB4		Engineer: <i>Ryan_Wang</i>	
Size B	Project Name K72Jr	Rev 2.0	
Date: <i>Friday, December 11, 2009</i>		Sheet	<i>58</i> of <i>100</i>



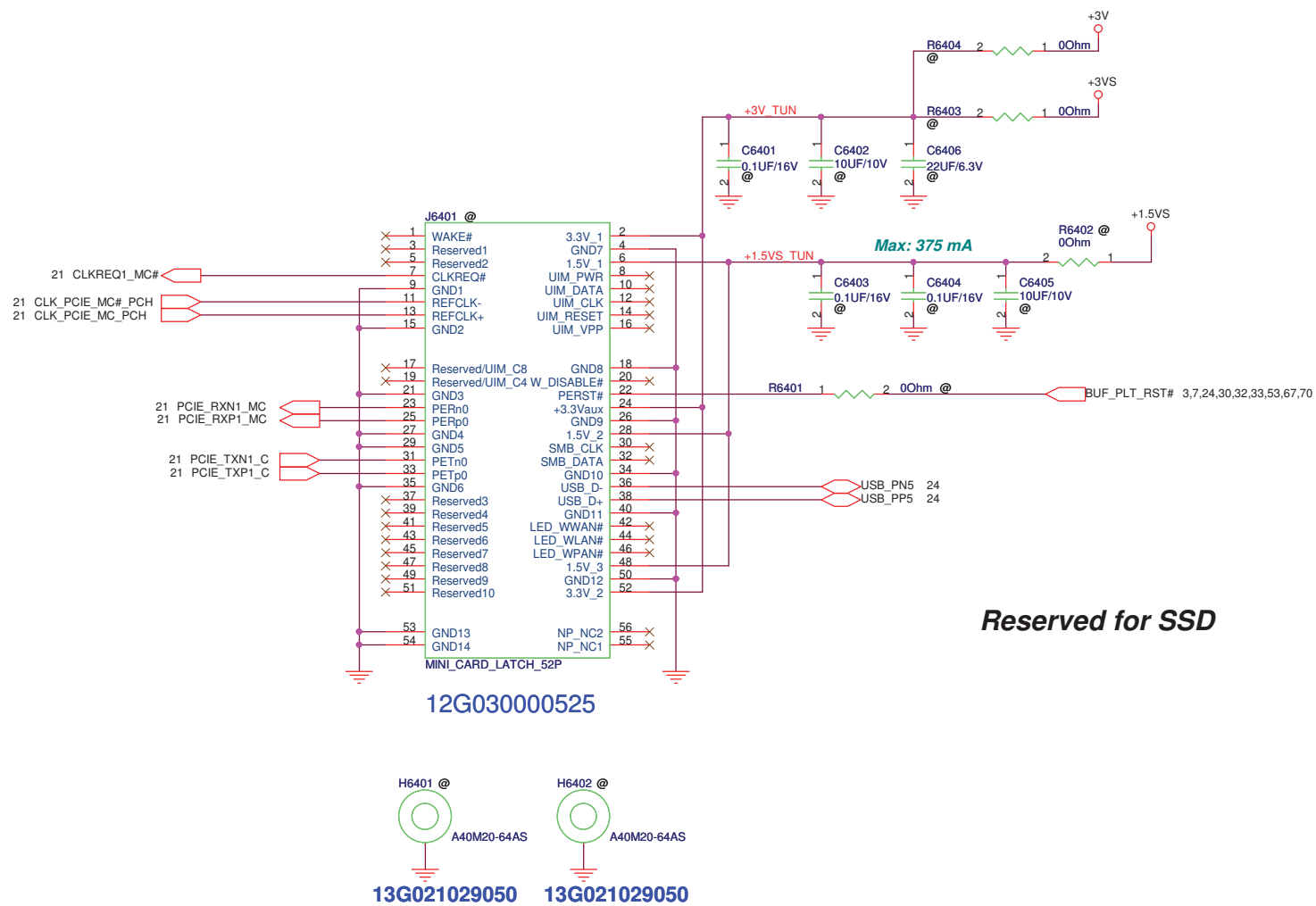
ASUS		Title : DC_DC & BAT Conn.	
ASUSTeK COMPUTER INC. NB4		Engineer: Ryan_Wang	
Size B	Project Name K72Jr		Rev 2.0
Date: Friday, December 11, 2009		Sheet	60 of 100

BLUETOOTH

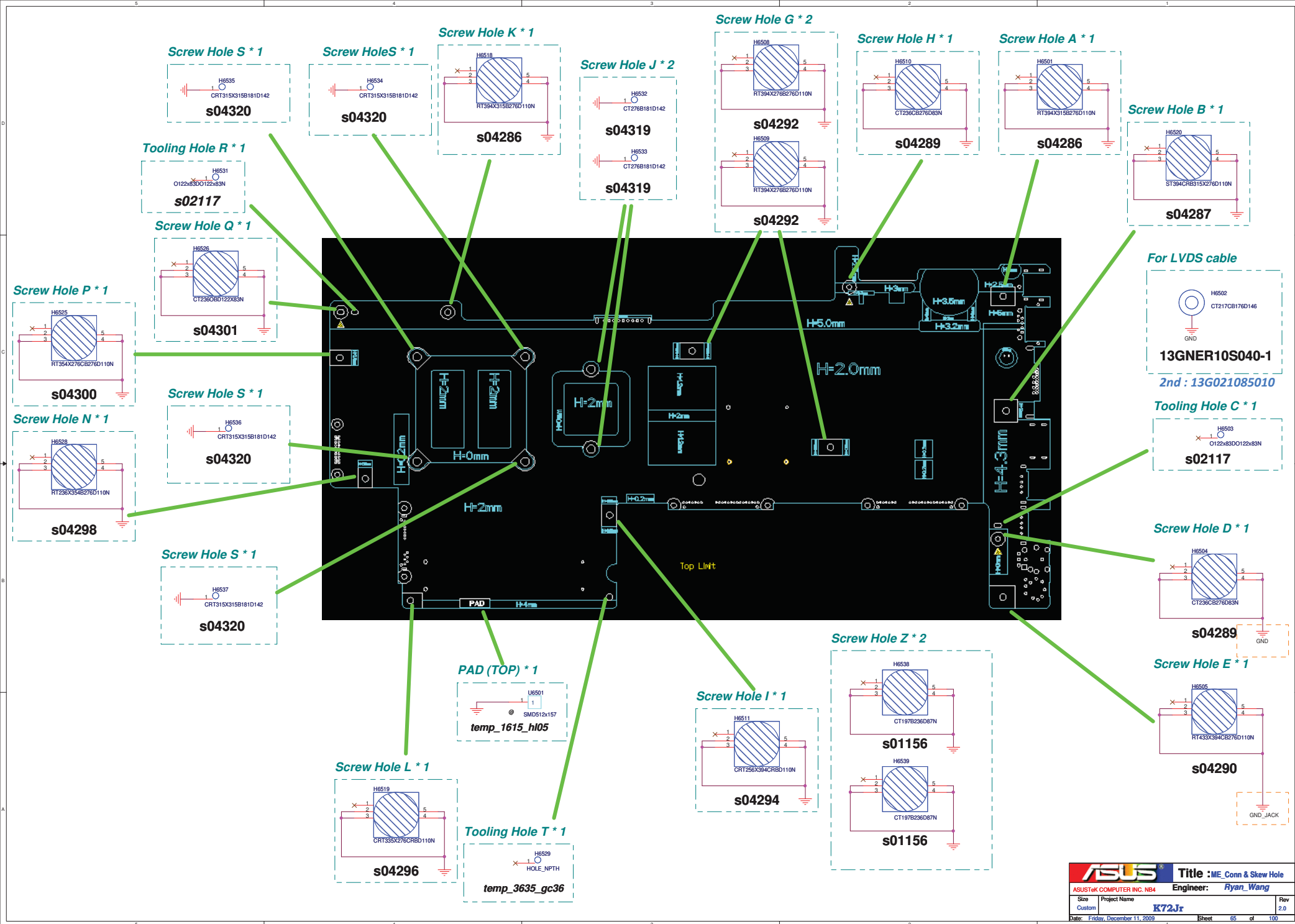
TOP connector PIN6 上面 LED
; PIN1下面 GND



		Title : <i>BT_Bluetooth</i>	
ASUSTeK COMPUTER INC. NB4		Engineer: <i>Ryan_Wang</i>	
Size	Project Name	K72Jr	Rev 2.0
Custom			
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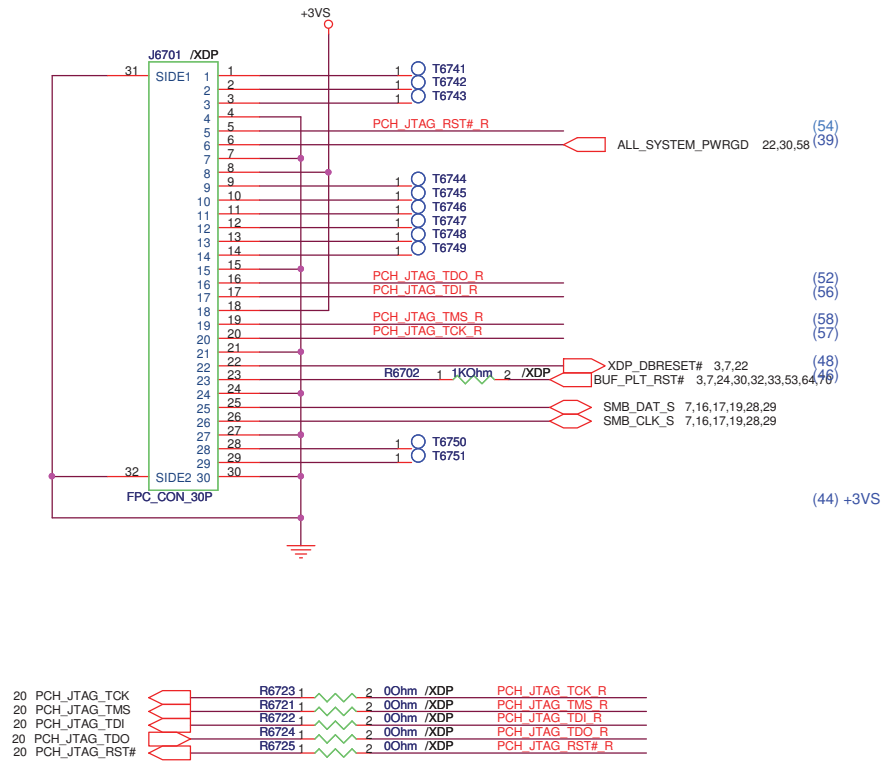
		Title :	
ASUSTeK COMPUTER INC. NB4		Engineer: <i>Ryan_Wang</i>	
Size Custom	Project Name K72Jr		Rev 2.0
Date: Friday, December 11, 2009		Sheet 64 of 100	



C6681 @

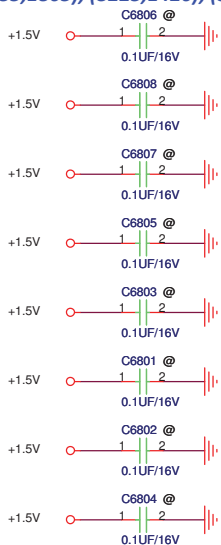


PCH XDP

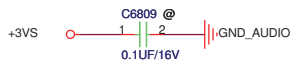


2009/8/25

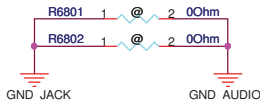
1.5V 對 GND, (1975,4025), (3250,4075), (3325,2310), (3870,2300), (3445,1720), (3735,1805), (3225,1420), (3635,1500) 預留 0402 電容



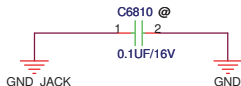
INT_MIC 跨 +3VS & GND_Audio 在 in2 切割，預留 +3VS 對 GND_AUDIO 電容



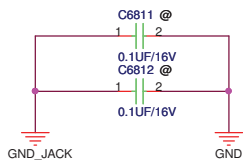
GND_Jack 對 GND_AUDIO 留 0 歐姆電阻: (11990, 2240), (11895, 1695)



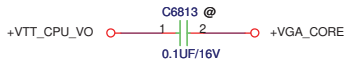
GND_Jack 對 GND: (12015, 2405) 預留電容



GND_audio 對 GND: (11655, 2495), (11655, 2200) 預留電容



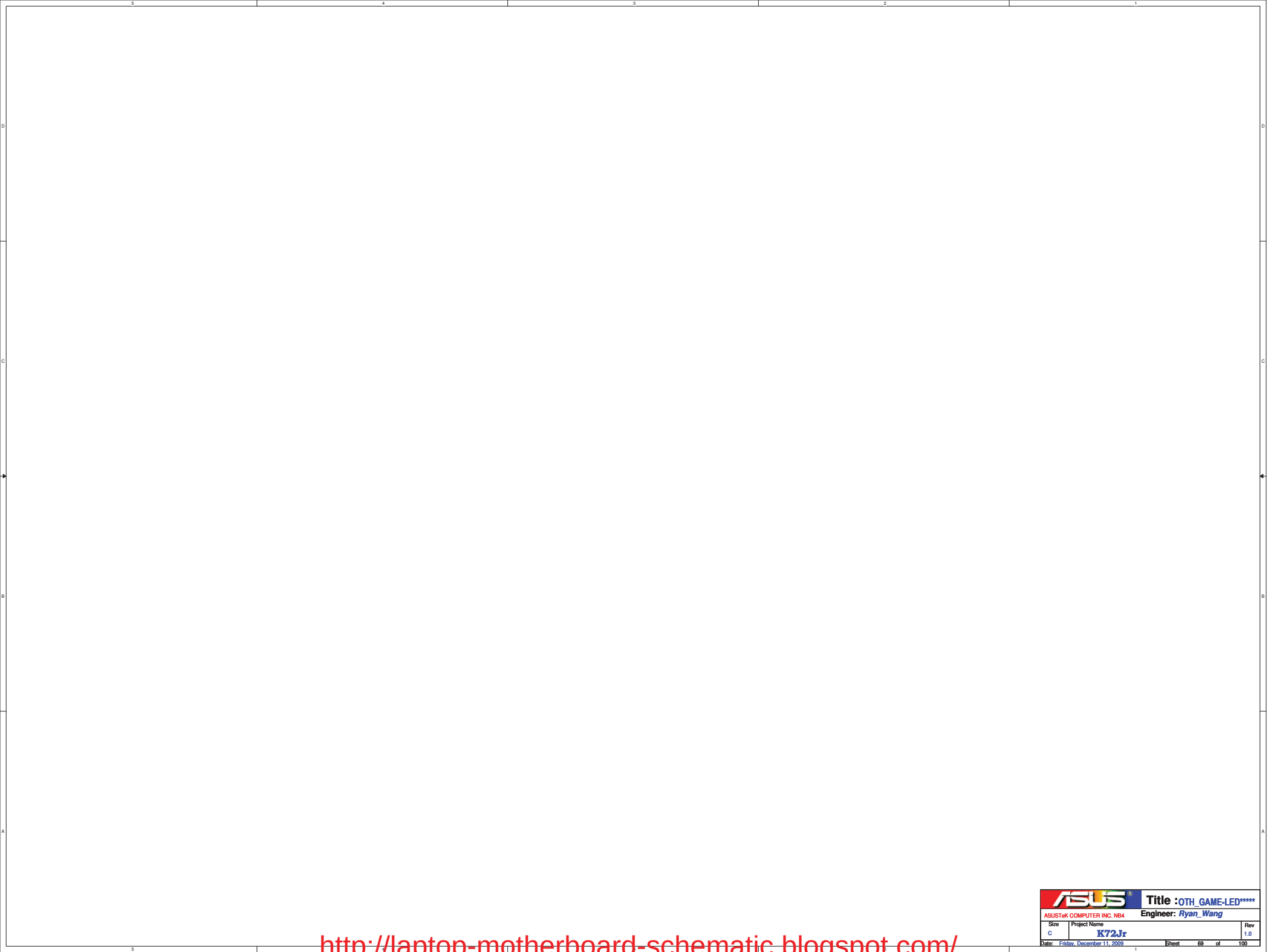
+VTT_CPU_VO 對 +VGA_Core: (5310, 5430) 預留電容



+5V 對 +VTT_CPU_VO: (2565, 5990) 預留電容

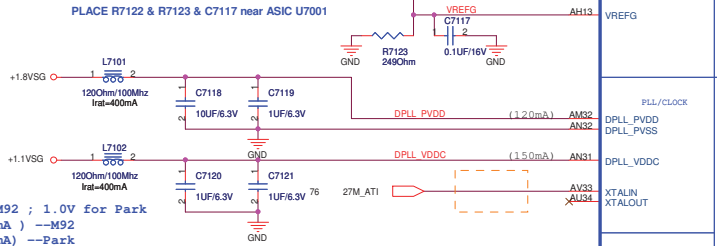
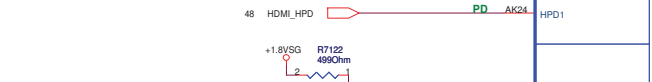
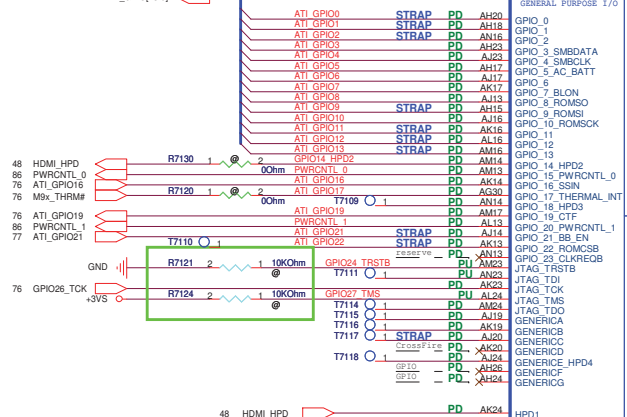
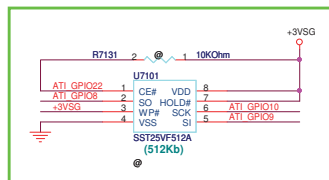


ASUS		Title : OTH_LCM	
ASUSTeK COMPUTER INC. NB4		Engineer: Ryan_Wang	
Size B	Project Name K72Jr		Rev 2.0
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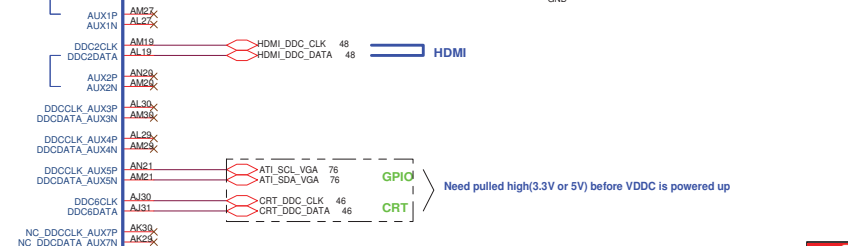
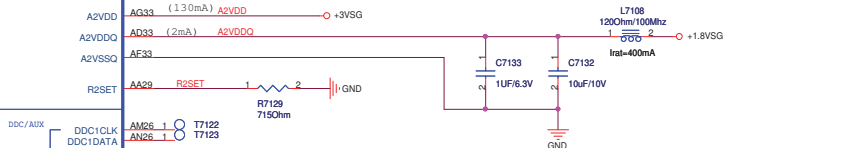
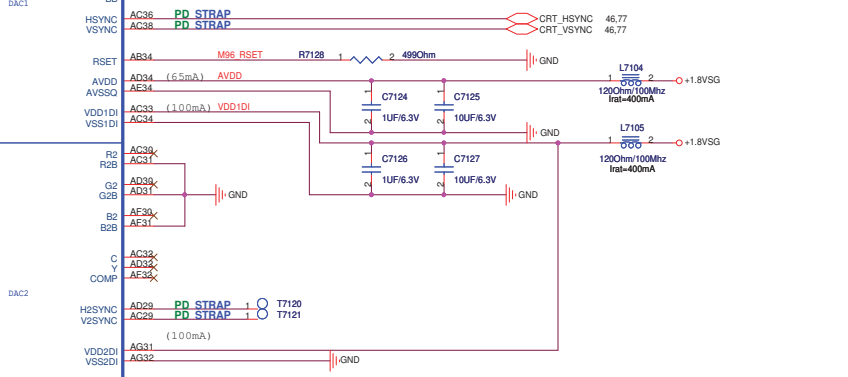
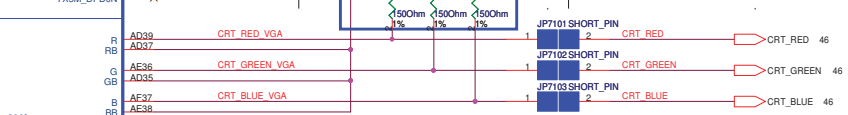
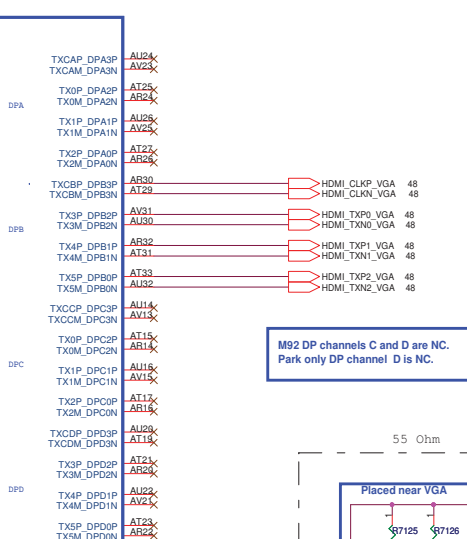
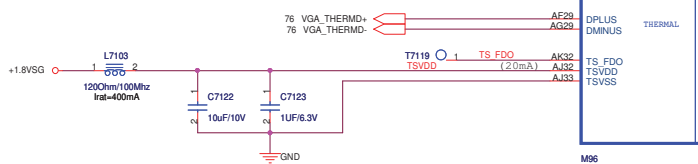


<http://laptop-motherboard-schematic.blogspot.com/>

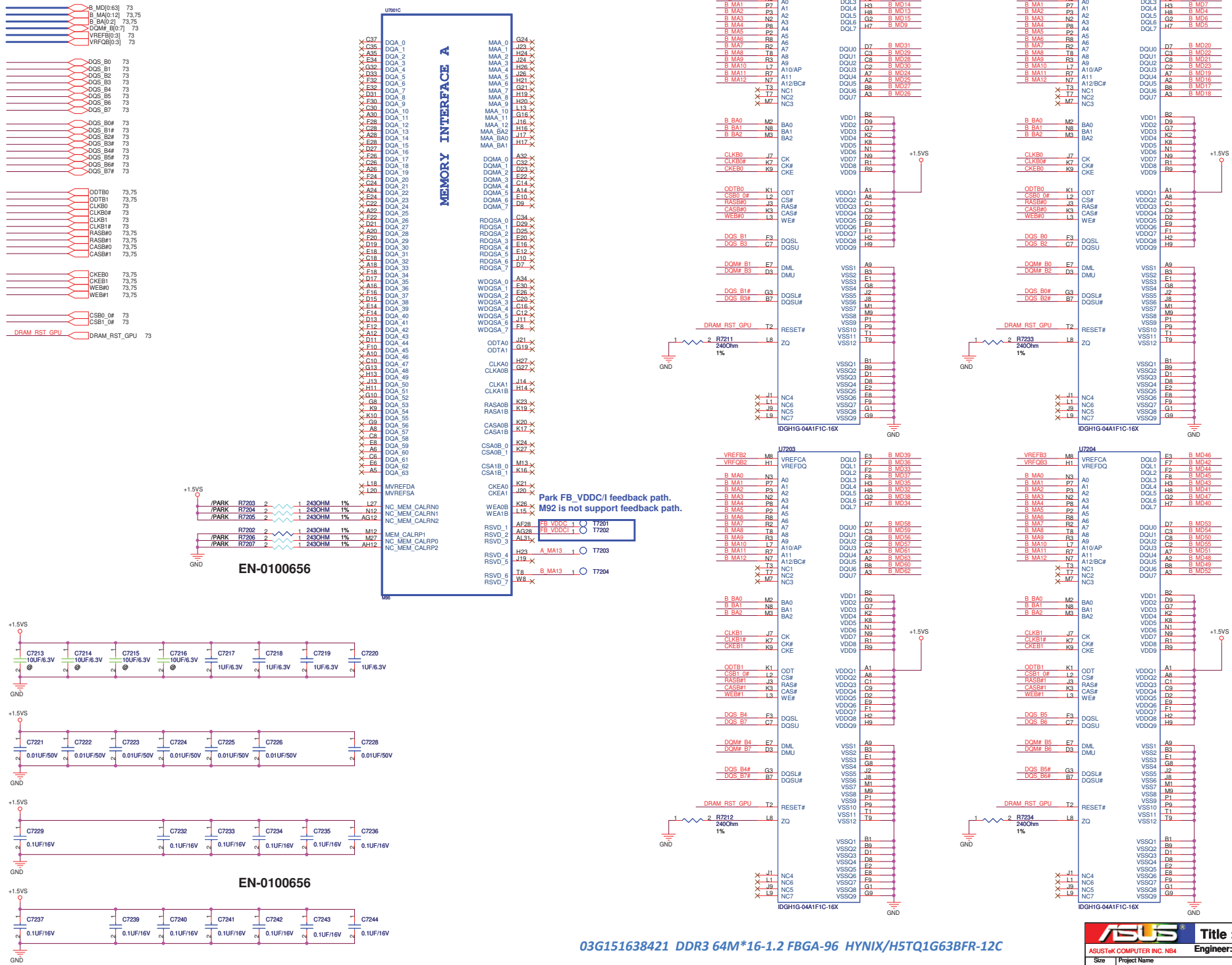
		Title : OTH_GAME-LED*****	
ASUSTeK COMPUTER INC. NB4		Engineer: Ryan_Wang	
Size	Project Name		Rev
C	K72Jr		1.0
Date: Friday, December 11, 2009		Sheet	69 of 100



```
+1.1VSG : 1.1V for M92 ; 1.0V for Park
DPLL_VDDC (1.1V@150mA) --M92
           (1.0V@125mA) --Park
```

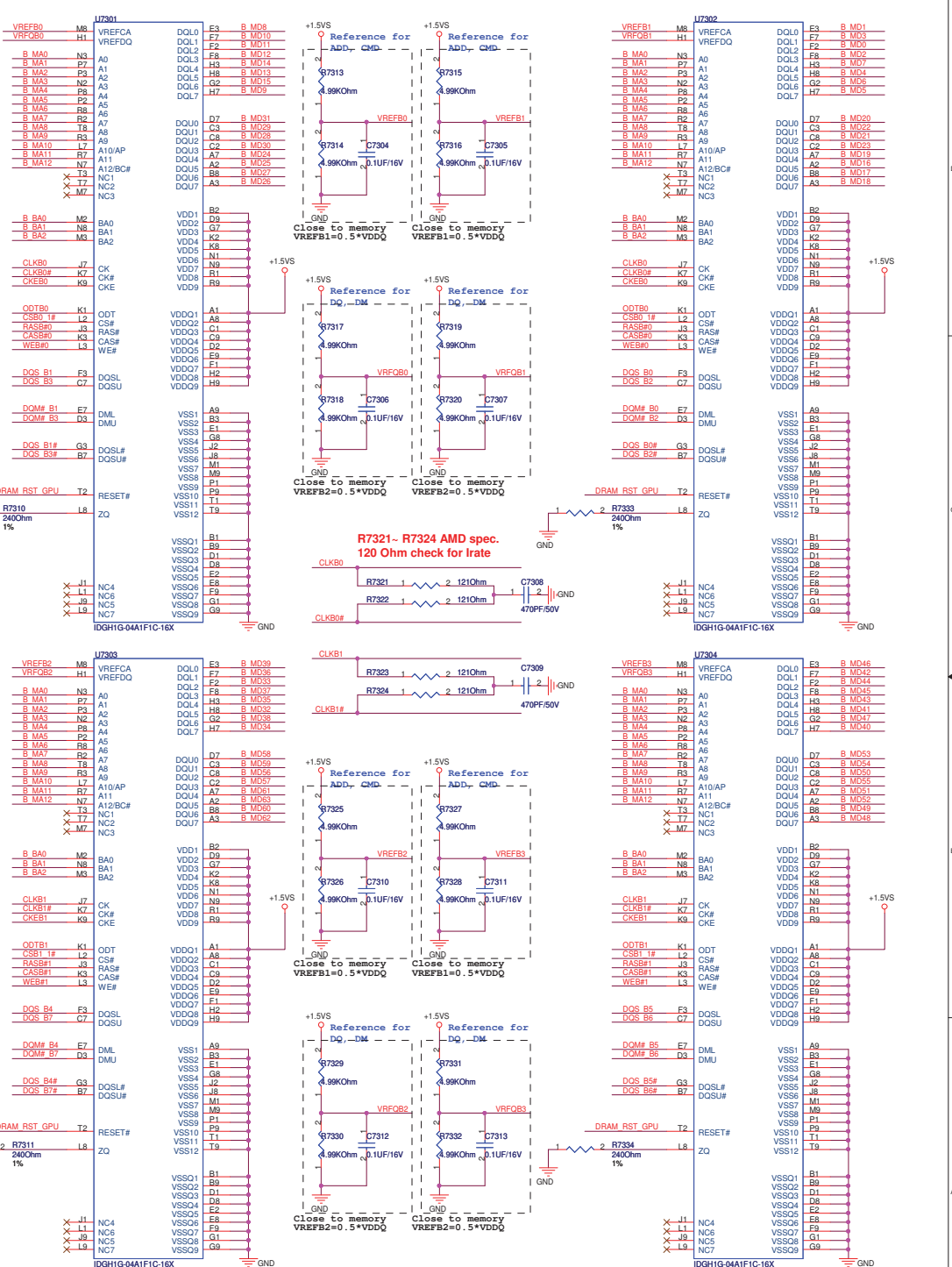
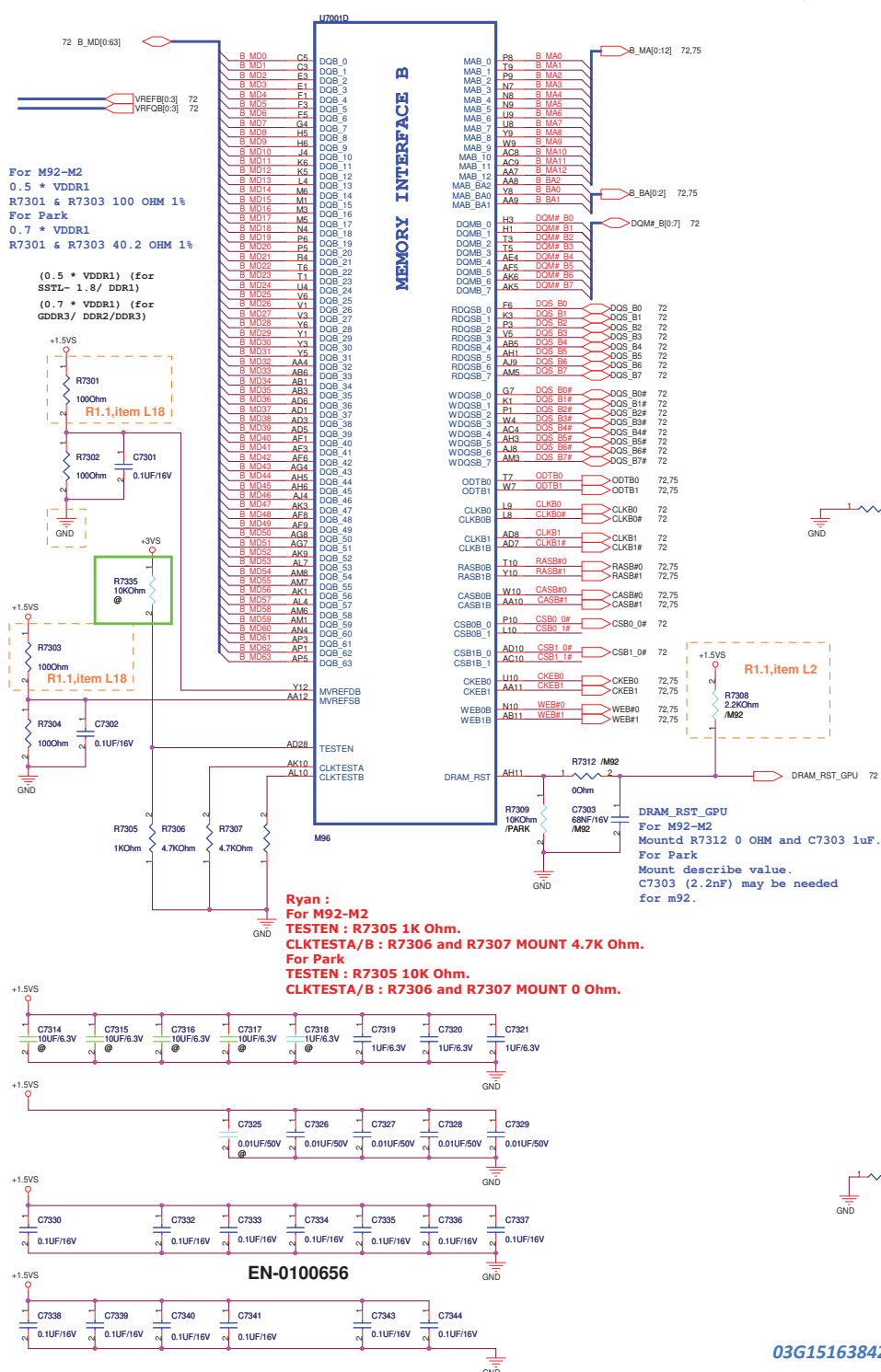


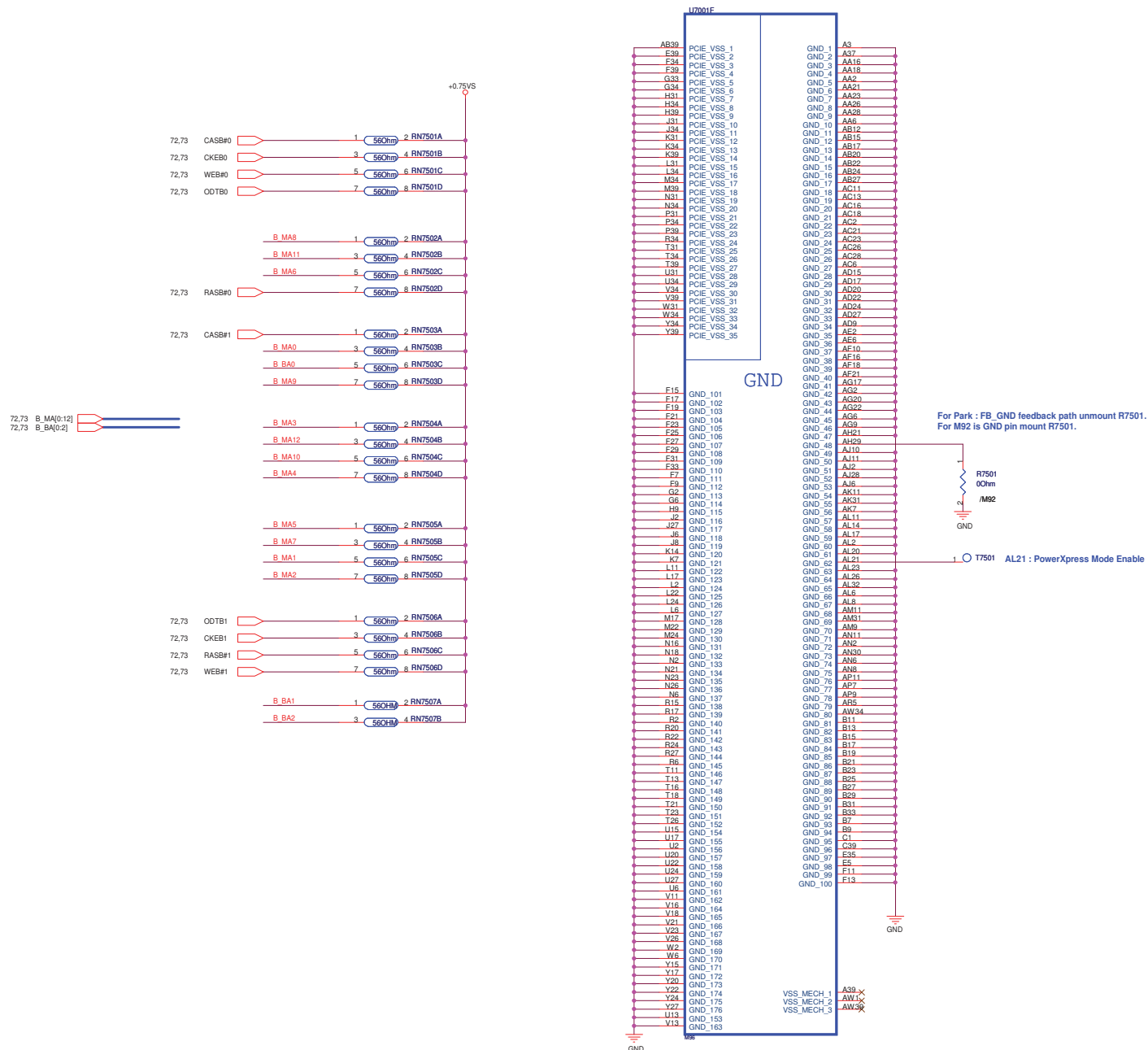
Channel B: Dual 1GB Rank DDR3 (Rank0)



03G151638421 DDR3 64M*16-1.2 FBGA-96 HYNIX/H5TQ1G63BFR-12C

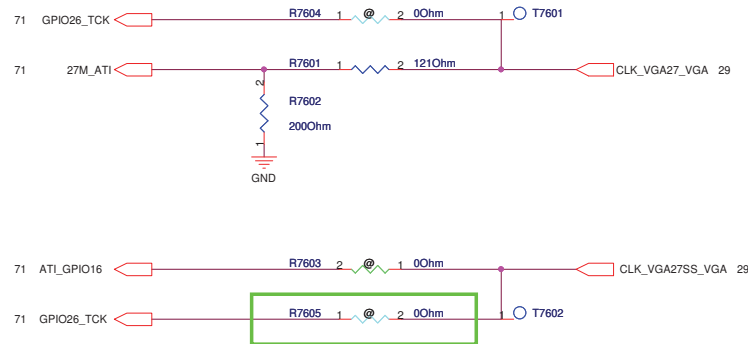
Channel B: Dual 1GB Rank DDR3 (Rank1)



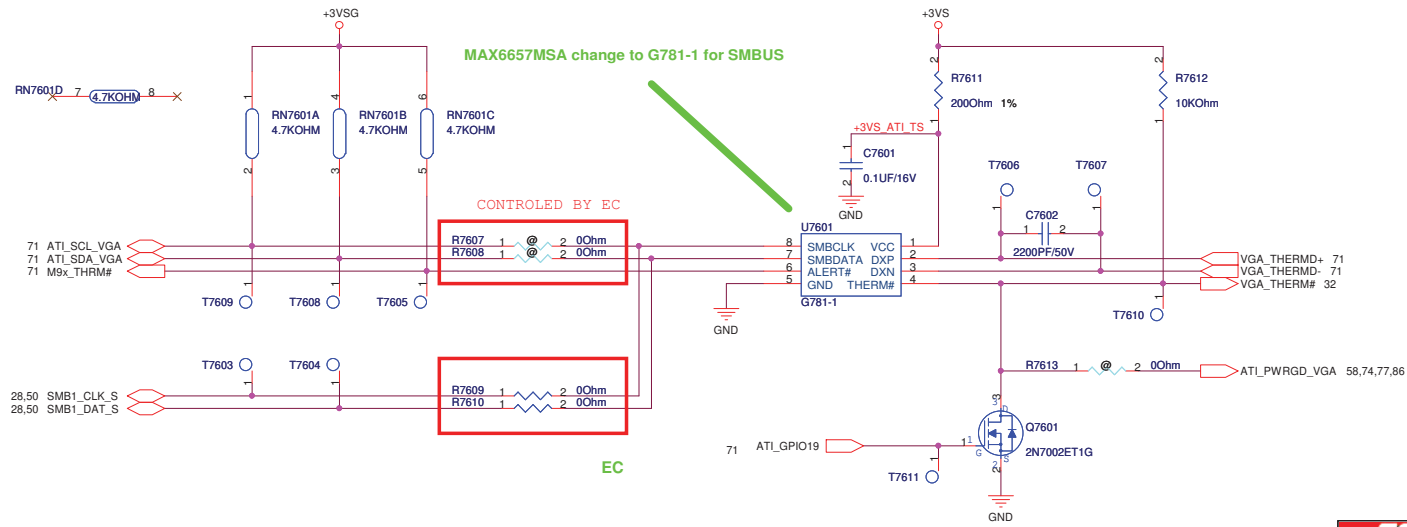


Memory Clock SS (Reserved)

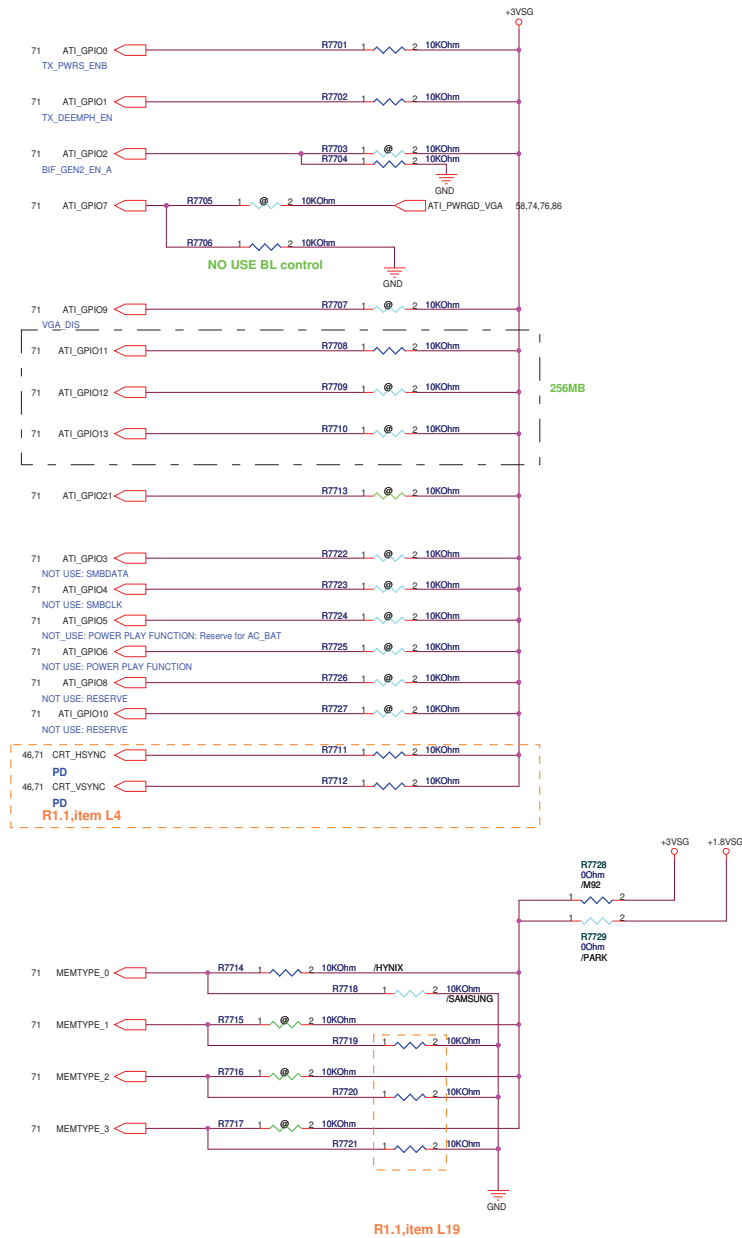
S0 (Spread Percentage Select):
GND: TBD%
VDD: TBD% (default PU)
NC : TBD%



	SMBUS SLAVE ADDRESS
G781	98 (1 0 0 1 1 0 0)
G781-1	9A (1 0 0 1 1 0 1)



OPTION STRAPS



VDDR4_VDDR5 : 3.3V for M92 ; 1.8V for Park
M92-M2 mount R7401& unmount L7402
Park mount L7402 & unmount R7401

M92 Straps

STRAPS	PIN	DESCRIPTION	ASIC DEFAULT
VIP_DEVICE_STRAP_EN	V2SYNC	0 - Ignore VIP device straps (DVPDATA_20) 1 - Use VIP device straps (DVPDATA_20)	0 (internal pull-down)
TX_PWRS_ENB	GPIO0	Transmitter Power Savings Enable 0: 50% Tx output swing for mobile mode 1: full Tx output swing <i>This setting can only be used if the PCIe bus design meets the "Low Loss Interconnect" requirements.</i>	0 (internal pull-down)
TX_DEEMPH_EN	GPIO1	Transmitter De-emphasis Enable 0: Tx de-emphasis disabled for mobile mode 1: Tx de-emphasis enabled	0 (internal pull-down)
BIF_GEN2_EN_A	GPIO2	1 = Advertises the PCI-E device as 5.0 GT/s capable at power-on 0 = Advertises the PCI-E device as 2.5 GT/s capable at power-on	0
VGA_DIS	GPIO9	0 - VGA Controller capacity enabled 1 - The device will not be recognized as the system's VGA controller	0 (internal pull-down)
ROMIDCFG(2:0)	GPIO(13:11)	If BIOS_ROM_EN=1, then Config(2:0) defines the ROM type. If BIOS_ROM_EN=0, then Config(2:0) defines the primary memory aperture size. 128MB---x000 32MB---Not Support 2GB---Not Support 256MB---x001 512MB---Not Support 4GB---Not Support 64MB---x010 1GB---Not Support	0000 (internal pull-down)
BIOS_ROM_EN	GPIO22_ROMCSB	Enable external BIOS ROM device 0-Disable external BIOS ROM device 1-Enable external BIOS ROM device	0 (internal pull-down)
AUD[1] AUD[0]	PEG_CRT_HSYNC_VGA PEG_CRT_VSYNC_VGA	AUD[1:0]: 00: No audio function; 01: Audio for DisplayPort and HDMI if adapter is detected; 10: Audio for DisplayPort only; 11: Audio for both DisplayPort and HDMI	0 (internal pull-down)
Reserved	H2SYNC GPIO 21_BB_EN GENERICC	ATI internal use only. THIS PAD HAS AN INTERNAL PULL-DOWN AND MUST BE 0 V AT RESET.	0 (internal pull-down)

AUDIO_EN	VIP_3	Enable HD Audio function in the PCI configuration space 0 - Disable HD Audio 1 - Enable HD Audio	0 (internal pull-down)
64BAR_EN_A	VIP_5	Enable 64-bit BARs Most commonly this strap is left at the default (32-bit BARs)	0 (internal pull-down)
MSI_DIS	VIP_1	Disable Message Signaled Interrupt is both a ROM strap and a pin strap. The pin strap is only applicable if a BIOS ROM is not present	0 (internal pull-down)
VIP_DEVICE	VHAD_0	VIP_DEVICE_STRAP_EN is set 0 => not used VIP Host interface VIP_DEVICE_STRAP_EN is set 1 => used VIP Host interface	0 (internal pull-down)
DEBUG_ACCESS	GPIO4	Debug access strap 3.3V ---ON 0V ---OFF	0 (internal pull-down)
DEBUG_L2C_ENABLE	GPIO6	ATI internal use only. Other logic must not affect this signal during RESET Recommended to 0	0 (internal pull-down)

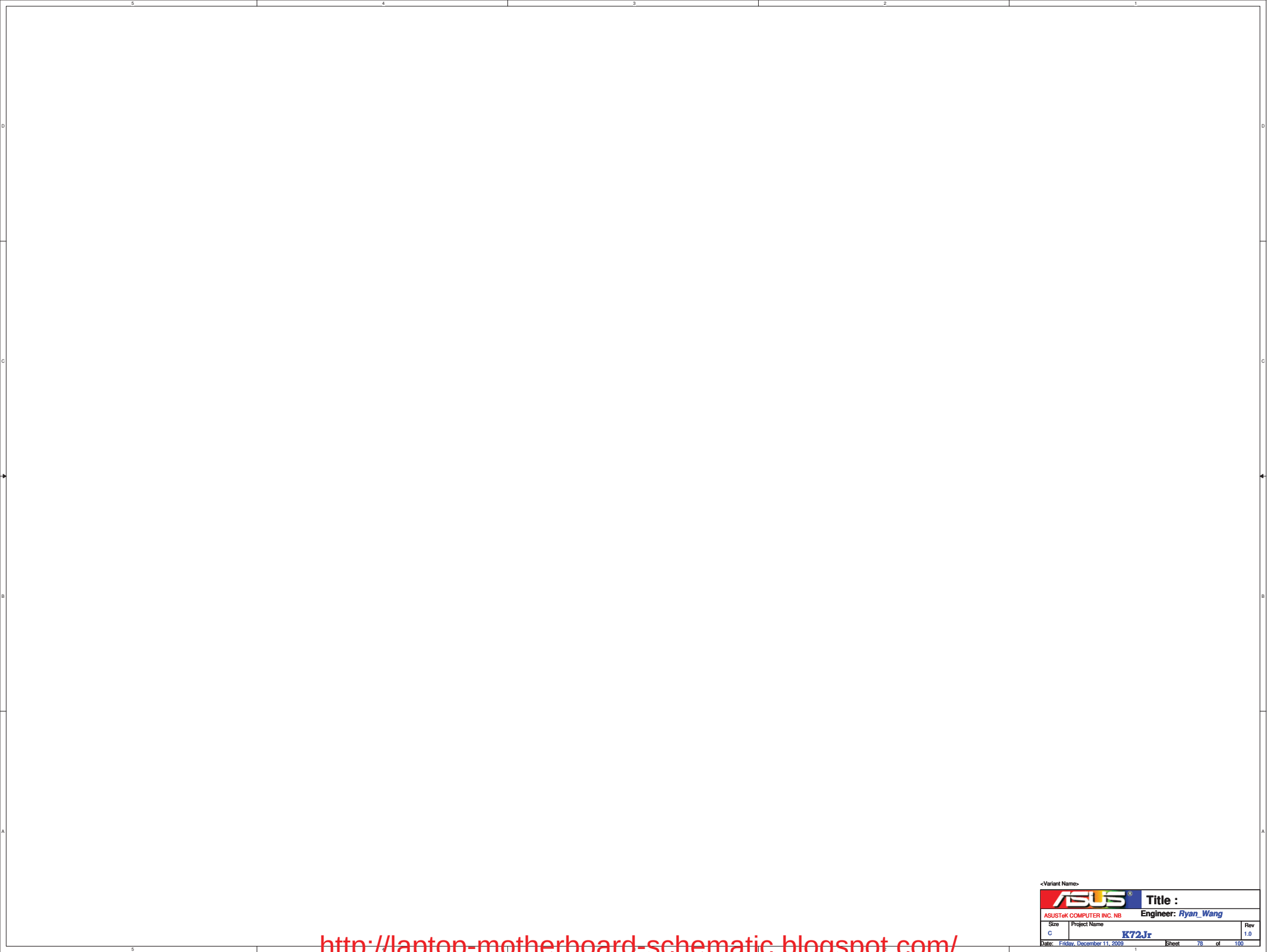
Dual Rank DDR3 1GB need AMD check pull low or high for following DDR3 VRAM
03G151638020 DDR3 64M*16-1.2 FBGA-96 SAMSUNG/K4W1G1646E-HC12
03G151638421 DDR3 64M*16-1.2 FBGA-96 HYNIX/H5TQ1G63BFR-12C

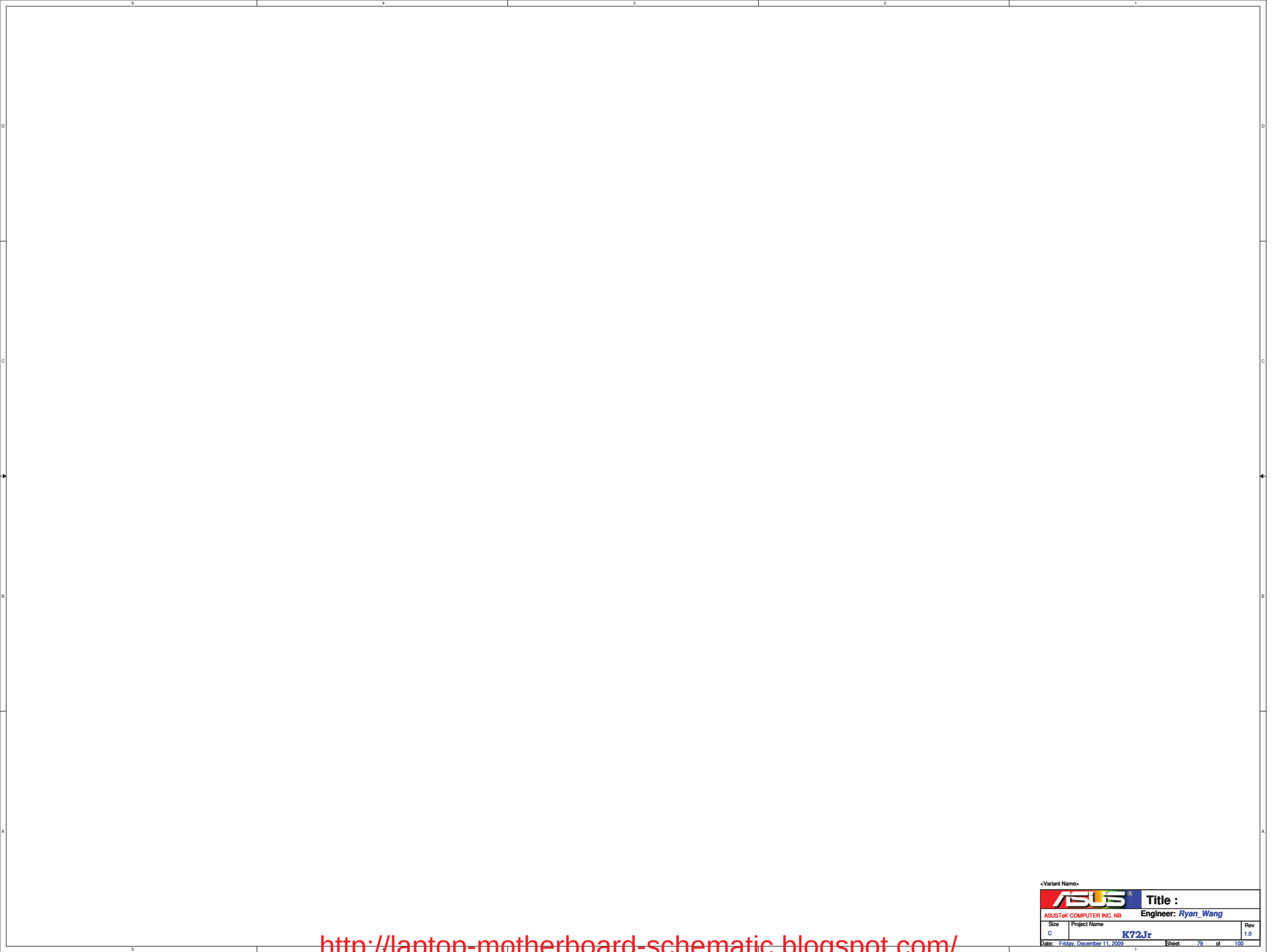
Memory ID Board Straps

Vendor	DVPDATA(3,2,1,0)	ID	DDR3 Memory Type	Channel Size
Samsung	0000	0	64M*16 (512MB) Dual Rank 512*2 = 1G	B channel dual-link
Hynix	0001	1	64M*16 (512MB) Dual Rank 512*2 = 1G	B channel dual-link

+VGA CORE	RTop	RBot	PWRCNTL_0	PWRCNTL_1
0.9V	8K	40K	Low	Low
1V	8K	40K 60.4K	High	Low
1.1V	8K	40K 30.1K	Low	High
1.2V	8K	40K 60.4K 30.1K	High	High

ASUS		Title : VGA ****	
ASUSTek COMPUTER INC. NB4		Engineer: Ryan_Wang	
Size	Project Name	K72Jr	Rev 2.0
Custom			
Date: Friday, January 22, 2010		Sheet	77 of 100





<http://laptop-motherboard-schematic.blogspot.com/>

<Variant Name>

**ASUS**[®]

Title :

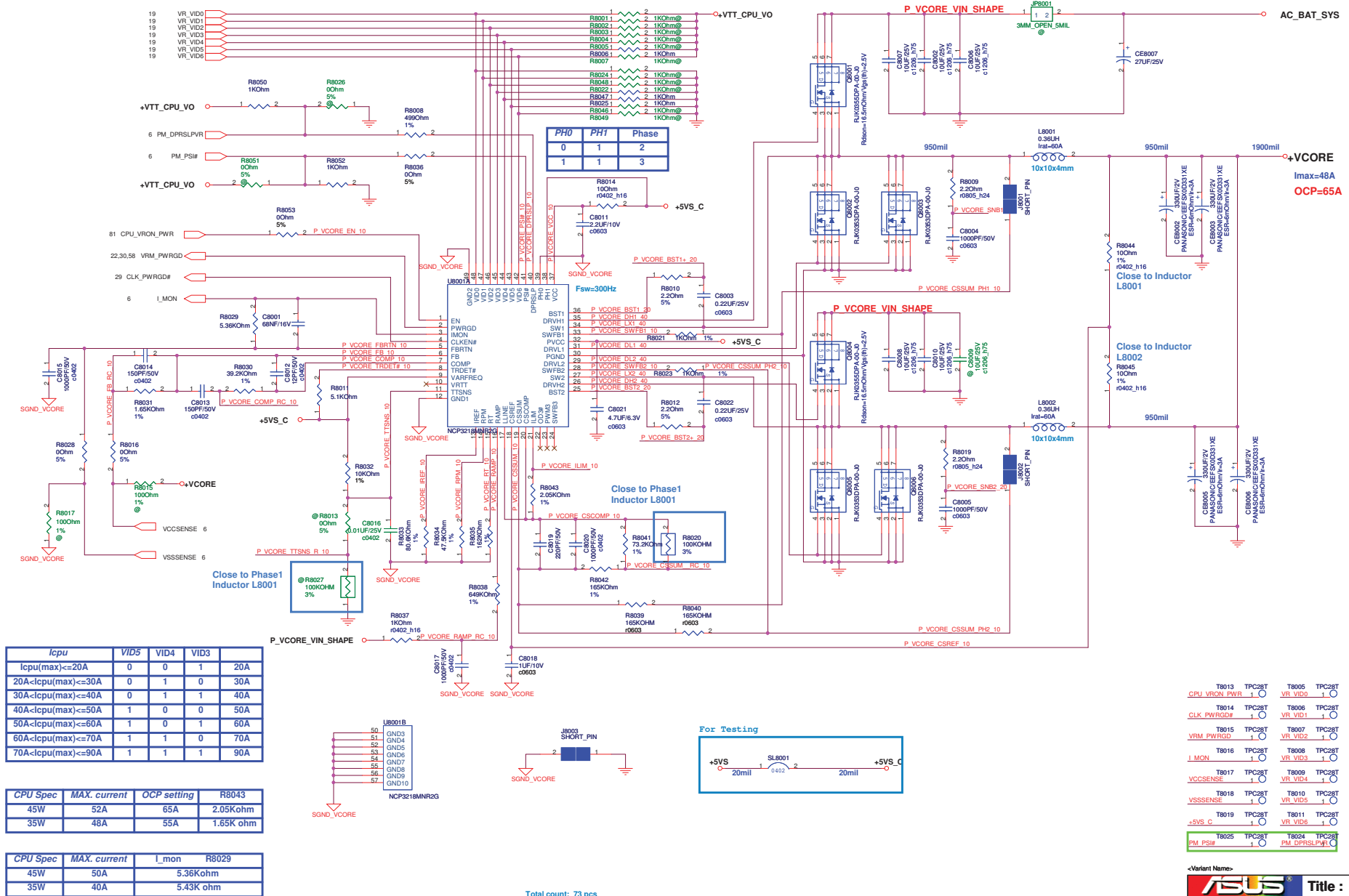
ASUSTeK COMPUTER INC. NB

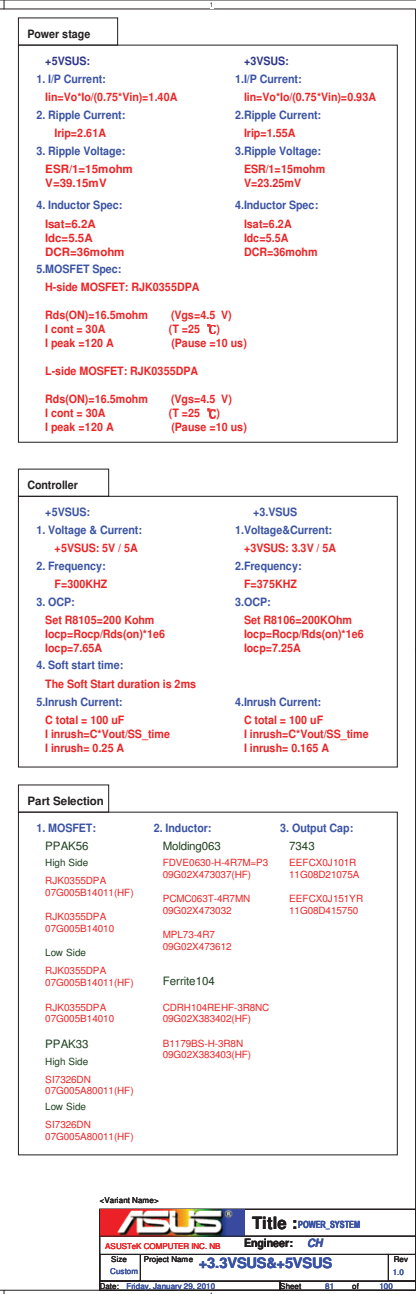
Engineer: *Ryan_Wang*

Size	Project Name	Rev
C	K72Jr	1.0

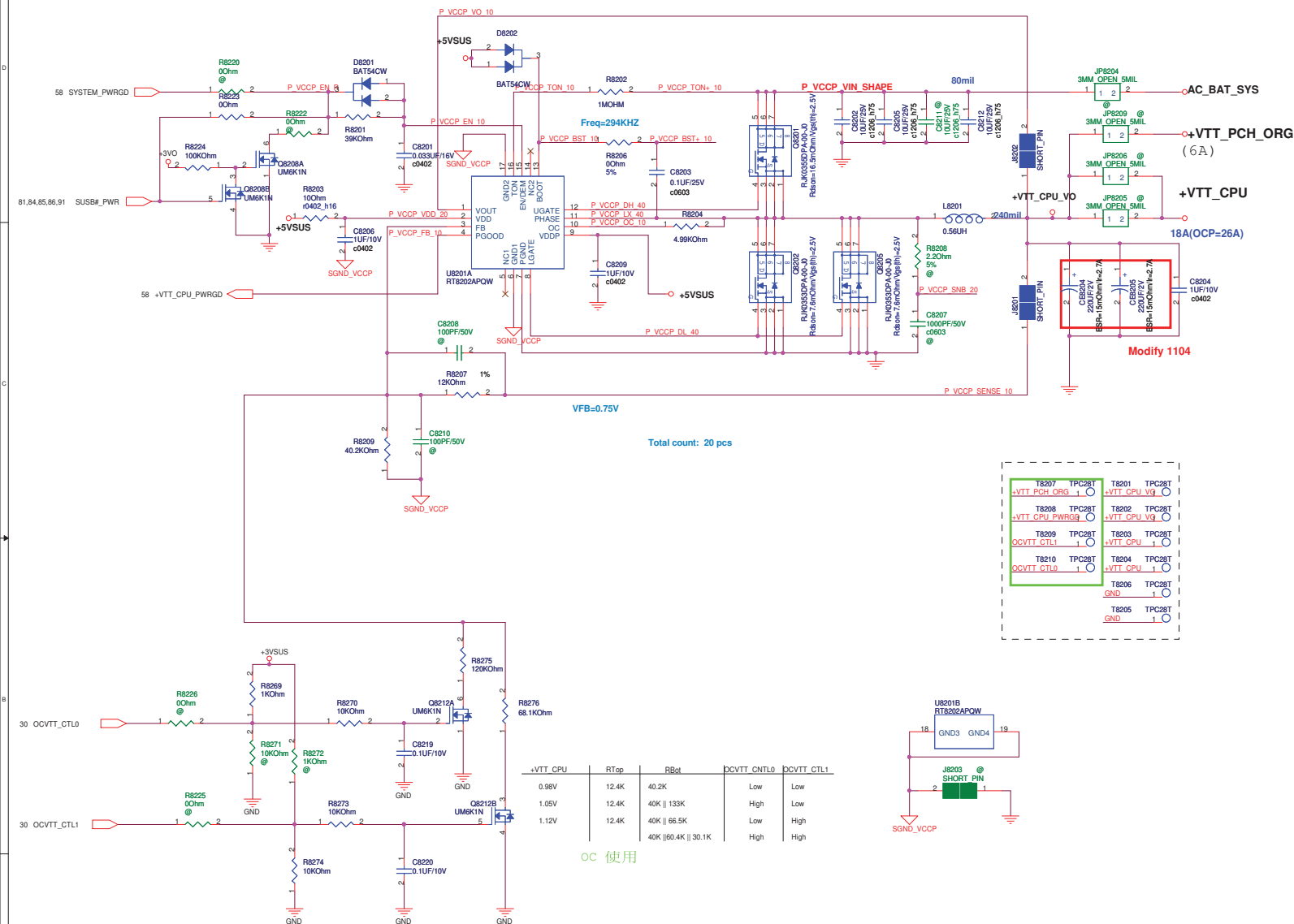
Date: Friday, December 11, 2009 Sheet 79 of 100

IMVP6.5 CPU VCORE REGULATOR





+VCCP POWER SUPPLY



Power stage

+VTT_CPU:

- 1. I/P Current:**
 $I_{in} = V_o / (10 \cdot (0.75 \cdot V_{in})) = 1.32A$
- 2. Ripple Current:**
 $I_{rip} = 5.9A$
- 3. Ripple Voltage:**
 $ESR / 1 = 10mohm$
 $V = 59mV$
- 4. Inductor Spec:**
 $I_{sat} = 30.5A$
 $I_{dc} = 22.9A$
 $DCR = 1.4mohm$
- 5. MOSFET Spec:**
H-side MOSFET: RJK0355DPA
 $R_{ds}(ON) = 16.5mohm$ ($V_{gs} = 4.5V$)
 $I_{cont} = 30A$ ($T = 25^\circ C$)
 $I_{peak} = 120A$ (Pause = 10 us)
- L-side MOSFET: RJK0353DPA**
 $R_{ds}(ON) = 7.6mohm$ ($V_{gs} = 4.5V$)
 $I_{cont} = 35A$ ($T = 25^\circ C$)
 $I_{peak} = 140A$ (Pause = 10 us)

Controller

+VTT_CPU

1. **Voltage & Current:**
+VCCP: 1.05V / 26A
2. **Frequency:**
F=294KHZ
3. **OCp:**
Set R8204=4.99 Kohm
locp=Rocp*20uA/Rds(on)
locp=26.26A
4. **Soft start time:**
The Soft Start duration is 1.35ms
5. **Inrush Current:**
C total = 220 uF
I inrush=C*Vout/SS_time
I inrush= 0.17 A

Part Selection

- | 1. MOSFET: | 2. Inductor: | 3. Output Cap: |
|--------------------------------|---|--------------------------------|
| PPAK56 | Molding063 | 7343 |
| High Side | FDVE0630-H-1R0M=P3
09G02X103506(HF) | EEFCX0D221YR
11G08D1227D0 |
| RJK035SDPA
07G005B14011(HF) | PCMC063T-1R0MN
09G02X103022 | EEFCX0D221R
11G08D2227D1 |
| RJK035SDPA
07G005B14010 | MPC7301R0M1
09G02X103H11 | ACAS2R0S221E15
11G09D2227D0 |
| Low Side | | |
| RJK035SDPA
07G005A92010 | Ferrite104 | |
| | FDUE1040D-H-1R0M=P3
09G02X103T25(HF) | |
| PPAK33 | | |
| High Side | PCMC104T-1R0MN
09G02X103J00 | |
| S17356DN
07G005A80011(HF) | MPO104-1R0
09G02X103R01 | |

<Variant Name>



+1.5V & 0.75VS POWER SUPPLY

Power stage

- DDR II:**
 - I/P Current:
 $I_{in} = V_o \cdot I_o / (0.75 \cdot V_{in}) = 1.052A$
 - Ripple Current:
 $I_{rip} = 3.07A$
 - Ripple Voltage:
 $ESR/1 = 10mohm$
 $V = 30.7mV$
 - Inductor Spec:
 $I_{sat} = 10.9A$
 $I_{dc} = 10A$
 $DCR = 12.1mohm$
 - MOSFET Spec:
H-side MOSFET: RJK0355DPA
 $R_{ds(ON)} = 16.5mohm$ ($V_{gs} = 4.5V$)
 $I_{cont} = 30A$ ($T = 25^\circ C$)
 $I_{peak} = 120A$ (Pause = 10 us)
L-side MOSFET: RJK0355DPA
 $R_{ds(ON)} = 16.5mohm$ ($V_{gs} = 4.5V$)
 $I_{cont} = 30A$ ($T = 25^\circ C$)
 $I_{peak} = 120A$ (Pause = 10 us)

Controller

- DDR II:**
 - Voltage & Current:
 $+1.5V: 1.5V / 10A$
 $+0.75V: 0.75V / 1A$
 - Frequency:
 $F = 294KHZ$
 - OCP:
Set $R8302 = 12Kohm$
 $I_{ocp} = R_{ocp} \cdot 20uA / R_{ds(on)}$
 $I_{ocp} = 14A$
 - Soft start time:
The Soft Start duration is 1.35ms
 - Inrush Current:
 $C_{total} = 560 uF$
 $I_{inrush} = C \cdot V_{out}/SS_time$
 $I_{inrush} = 0.17 A$

	+1.5V	RTop	RBot	DCVTT_GNTL0	DCVTT_CTL1
1.4V	20K	23.2K	23.2K 143K	Low	Low
1.5V	20K	23.2K	23.2K 143K	High	Low
1.6V	20K	23.2K	23.2K 73.2K	Low	High
1.7V	20K	23.2K	23.2K 73.2K 143K	High	High

Part Selection

1. MOSFET:	2. Inductor:	3. Output Cap:
PPAK56 High Side RJK0355DPA 07G005B14011(HF)	Molding063 FDVE0630-H-2R2M=P3 09G02X223809(HF)	7343 EEFCXD0221YR 11G08D1227D0
RJK0355DPA 07G005B14010	PCMC063T-2R2MN 09G02X223801	EEFCXD0221R1 11G08D2227D1
Low Side RJK0353DPA 07G005A92010	MPC730-2R2M01 09G02X223815	ACAS2R0S221E15 11G08D2227D0
PPAK33 High Side S1732DN 07G005A80011(HF)		

Total count: 29 pcs

<Variant Name>
ASUS Title : POWER_IO_DDR
 ASUSTek COMPUTER INC. NB Engineer: CH_LU
 Size Project Name K72J Rev 1.0
 Custom Date: Friday, January 29, 2010 Sheet 83 of 100

<http://laptop-motherboard-schematic.blogspot.com/>

+1.5V & 0.75VS POWER SUPPLY

+1.5V & 0.75VS POWER SUPPLY

Power stage

DDR II:

- I/P Current:
 $I_{in} = V_o \cdot I_o / (0.75 \cdot V_{in}) = 1.052A$
- Ripple Current:
 $I_{rip} = 3.07A$
- Ripple Voltage:
 $ESR/1 = 10mohm$
 $V = 30.7mV$
- Inductor Spec:
 $I_{sat} = 10.9A$
 $I_{dc} = 10A$
 $DCR = 12.1mohm$
- MOSFET Spec:
H-side MOSFET: RJK0355DPA
 $R_{ds(ON)} = 16.5mohm$ ($V_{gs} = 4.5V$)
 $I_{cont} = 30A$ ($T = 25^\circ C$)
 $I_{peak} = 120A$ (Pause = 10 us)
L-side MOSFET: RJK0355DPA
 $R_{ds(ON)} = 16.5mohm$ ($V_{gs} = 4.5V$)
 $I_{cont} = 30A$ ($T = 25^\circ C$)
 $I_{peak} = 120A$ (Pause = 10 us)

Controller

DDR II:

- Voltage & Current:
 $+1.5V: 1.5V / 10A$
 $+0.75V: 0.75V / 1A$
- Frequency:
 $F = 294KHZ$
- OCF:
Set $R8302 = 12Kohm$
 $I_{ocp} = R_{ocp} \cdot 20uA / R_{ds(on)}$
 $I_{ocp} = 14A$
- Soft start time:
The Soft Start duration is 1.35ms
- Inrush Current:
 $C_{total} = 560uF$
 $I_{inrush} = C \cdot V_{out} / SS_time$
 $I_{inrush} = 0.17A$

Part Selection

1. MOSFET:	2. Inductor:	3. Output Cap:
PPAK56	Molding063	7343
High Side	FDVE0630-H-2R2M-P3	EEFCX0D221YR
RJK0355DPA	09G02X223809(HF)	11G08D1227D0
07G005B14011(HF)	PCMC063T-2R2MN	EEFCX0D221R1
RJK0355DPA	09G02X223801	11G08D2227D1
07G005B14010	MPC730-2R2M01	ACAS2R0S221E15
Low Side	09G02X223815	11G08D2227D0
RJK0353DPA		
07G005A92010		
PPAK33		
High Side		
S1732DN		
07G005A80011(HF)		

Variant Name: ASUS
ASUSTek COMPUTER INC. NB
Project Name: K72J
Date: Friday, January 29, 2010
Sheet: 83 of 100

Title: POWER_IO_DDR
Engineer: CH_LU
Rev: 1.0

Total count: 29 pcs

- ## +1.5V & 0.75VS POWER SUPPLY

+1.5V & 0.75VS POWER SUPPLY

Power stage

DDR II:

- I/P Current:
 $I_{in} = V_o \cdot I_o / (0.75 \cdot V_{in}) = 1.052A$
- Ripple Current:
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 $ESR/1 = 10mohm$
 $V = 30.7mV$
- Inductor Spec:
 $I_{sat} = 10.9A$
 $I_{dc} = 10A$
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- MOSFET Spec:
H-side MOSFET: RJK0355DPA
 $R_{ds(ON)} = 16.5mohm$ ($V_{gs} = 4.5V$)
 $I_{cont} = 30A$ ($T = 25^\circ C$)
 $I_{peak} = 120A$ (Pause = 10 us)
L-side MOSFET: RJK0355DPA
 $R_{ds(ON)} = 16.5mohm$ ($V_{gs} = 4.5V$)
 $I_{cont} = 30A$ ($T = 25^\circ C$)
 $I_{peak} = 120A$ (Pause = 10 us)

Controller

DDR II:

- Voltage & Current:
 $+1.5V: 1.5V / 10A$
 $+0.75V: 0.75V / 1A$
- Frequency:
 $F = 294KHZ$
- OCF:
Set $R8302 = 12Kohm$
 $I_{ocp} = R_{ocp} \cdot 20uA / R_{ds(on)}$
 $I_{ocp} = 14A$
- Soft start time:
The Soft Start duration is 1.35ms
- Inrush Current:
 $C_{total} = 560uF$
 $I_{inrush} = C \cdot V_{out} / SS_time$
 $I_{inrush} = 0.17A$

Part Selection

1. MOSFET:	2. Inductor:	3. Output Cap:
PPAK56	Molding063	7343
High Side	FDVE0630-H-2R2M-P3	EEFCX0D221YR
RJK0355DPA	09G02X223809(HF)	11G08D1227D0
07G005B14011(HF)	PCMC063T-2R2MN	EEFCX0D221R1
RJK0355DPA	09G02X223801	11G08D2227D1
07G005B14010	MPC730-2R2M01	ACAS2R0S221E15
Low Side	09G02X223815	11G08D2227D0
RJK0353DPA		
07G005A92010		
PPAK33		
High Side		
S1732DN		
07G005A80011(HF)		

Variant Name: ASUS
ASUSTek COMPUTER INC. NB
Project Name: K72J
Date: Friday, January 29, 2010
Sheet: 83 of 100

Title: POWER_IO_DDR
Engineer: CH_LU
Rev: 1.0

Total count: 29 pcs

- +1.5V & 0.75VS POWER SUPPLY

Power stage

DDR II:

 - I/P Current:
 $I_{in} = V_o \cdot I_o / (0.75 \cdot V_{in}) = 1.052A$
 - Ripple Current:
 $I_{rip} = 3.07A$
 - Ripple Voltage:
 $ESR/1 = 10mohm$
 $V = 30.7mV$
 - Inductor Spec:
 $I_{sat} = 10.9A$
 $I_{dc} = 10A$
 $DCR = 12.1mohm$
 - MOSFET Spec:
H-side MOSFET: RJK0355DPA
 $R_{ds(ON)} = 16.5mohm$ ($V_{gs} = 4.5V$)
 $I_{cont} = 30A$ ($T = 25^\circ C$)
 $I_{peak} = 120A$ (Pause = 10 us)
L-side MOSFET: RJK0355DPA
 $R_{ds(ON)} = 16.5mohm$ ($V_{gs} = 4.5V$)
 $I_{cont} = 30A$ ($T = 25^\circ C$)
 $I_{peak} = 120A$ (Pause = 10 us)

Controller

DDR II:

 - Voltage & Current:
 $+1.5V: 1.5V / 10A$
 $+0.75V: 0.75V / 1A$
 - Frequency:
 $F = 294KHZ$
 - OCF:
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 $I_{ocp} = R_{ocp} \cdot 20uA / R_{ds(on)}$
 $I_{ocp} = 14A$
 - Soft start time:
The Soft Start duration is 1.35ms
 - Inrush Current:
 $C_{total} = 560uF$
 $I_{inrush} = C \cdot V_{out} / SS_time$
 $I_{inrush} = 0.17A$

Part Selection

1. MOSFET:	2. Inductor:	3. Output Cap:
PPAK56	Molding063	7343
High Side	FDVE0630-H-2R2M-P3	EEFCX0D221YR
RJK0355DPA	09G02X223809(HF)	11G08D1227D0
07G005B14011(HF)	PCMC063T-2R2MN	EEFCX0D221R1
RJK0355DPA	09G02X223801	11G08D2227D1
07G005B14010	MPC730-2R2M01	ACAS2R0S221E15
Low Side	09G02X223815	11G08D2227D0
RJK0353DPA		
07G005A92010		
PPAK33		
High Side		
S1732DN		
07G005A80011(HF)		

Variant Name: ASUS
ASUSTek COMPUTER INC. NB
Project Name: K72J
Date: Friday, January 29, 2010
Sheet: 83 of 100

Title: POWER_IO_DDR
Engineer: CH_LU
Rev: 1.0

Total count: 29 pcs

+1.5V & 0.75VS POWER SUPPLY

Power stage

DDR II:

- I/P Current:
 $I_{in} = V_o \cdot I_o / (0.75 \cdot V_{in}) = 1.052A$
- Ripple Current:
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- Ripple Voltage:
 $ESR/1 = 10mohm$
 $V = 30.7mV$
- Inductor Spec:
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 $I_{dc} = 10A$
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 $I_{peak} = 120A$ (Pause = 10 us)
L-side MOSFET: RJK0355DPA
 $R_{ds(ON)} = 16.5mohm$ ($V_{gs} = 4.5V$)
 $I_{cont} = 30A$ ($T = 25^\circ C$)
 $I_{peak} = 120A$ (Pause = 10 us)

Controller

DDR II:

- Voltage & Current:
 $+1.5V: 1.5V / 10A$
 $+0.75V: 0.75V / 1A$
- Frequency:
 $F = 294KHZ$
- OCF:
Set $R8302 = 12Kohm$
 $I_{ocp} = R_{ocp} \cdot 20uA / R_{ds(on)}$
 $I_{ocp} = 14A$
- Soft start time:
The Soft Start duration is 1.35ms
- Inrush Current:
 $C_{total} = 560uF$
 $I_{inrush} = C \cdot V_{out} / SS_time$
 $I_{inrush} = 0.17A$

Part Selection

1. MOSFET:	2. Inductor:	3. Output Cap:
PPAK56	Molding063	7343
High Side	FDVE0630-H-2R2M-P3	EEFCX0D221YR
RJK0355DPA	09G02X223809(HF)	11G08D1227D0
07G005B14011(HF)	PCMC063T-2R2MN	EEFCX0D221R1
RJK0355DPA	09G02X223801	11G08D2227D1
07G005B14010	MPC730-2R2M01	ACAS2R0S221E15
Low Side	09G02X223815	11G08D2227D0
RJK0353DPA		
07G005A92010		
PPAK33		
High Side		
S1732DN		
07G005A80011(HF)		

Variant Name: ASUS
ASUSTek COMPUTER INC. NB
Project Name: K72J
Date: Friday, January 29, 2010
Sheet: 83 of 100

Title: POWER_IO_DDR
Engineer: CH_LU
Rev: 1.0

Total count: 29 pcs

- ## +1.5V & 0.75VS POWER SUPPLY

+1.5V & 0.75VS POWER SUPPLY

Power stage

DDR II:

- I/P Current:
 $I_{in} = V_o \cdot I_o / (0.75 \cdot V_{in}) = 1.052A$
- Ripple Current:
 $I_{rip} = 3.07A$
- Ripple Voltage:
 $ESR/1 = 10mohm$
 $V = 30.7mV$
- Inductor Spec:
 $I_{sat} = 10.9A$
 $I_{dc} = 10A$
 $DCR = 12.1mohm$
- MOSFET Spec:
H-side MOSFET: RJK0355DPA
 $R_{ds(ON)} = 16.5mohm$ ($V_{gs} = 4.5V$)
 $I_{cont} = 30A$ ($T = 25^\circ C$)
 $I_{peak} = 120A$ (Pause = 10 us)
L-side MOSFET: RJK0355DPA
 $R_{ds(ON)} = 16.5mohm$ ($V_{gs} = 4.5V$)
 $I_{cont} = 30A$ ($T = 25^\circ C$)
 $I_{peak} = 120A$ (Pause = 10 us)

Controller

DDR II:

- Voltage & Current:
 $+1.5V: 1.5V / 10A$
 $+0.75V: 0.75V / 1A$
- Frequency:
 $F = 294KHZ$
- OCF:
Set $R8302 = 12Kohm$
 $I_{ocp} = R_{ocp} \cdot 20uA / R_{ds(on)}$
 $I_{ocp} = 14A$
- Soft start time:
The Soft Start duration is 1.35ms
- Inrush Current:
 $C_{total} = 560uF$
 $I_{inrush} = C \cdot V_{out} / SS_time$
 $I_{inrush} = 0.17A$

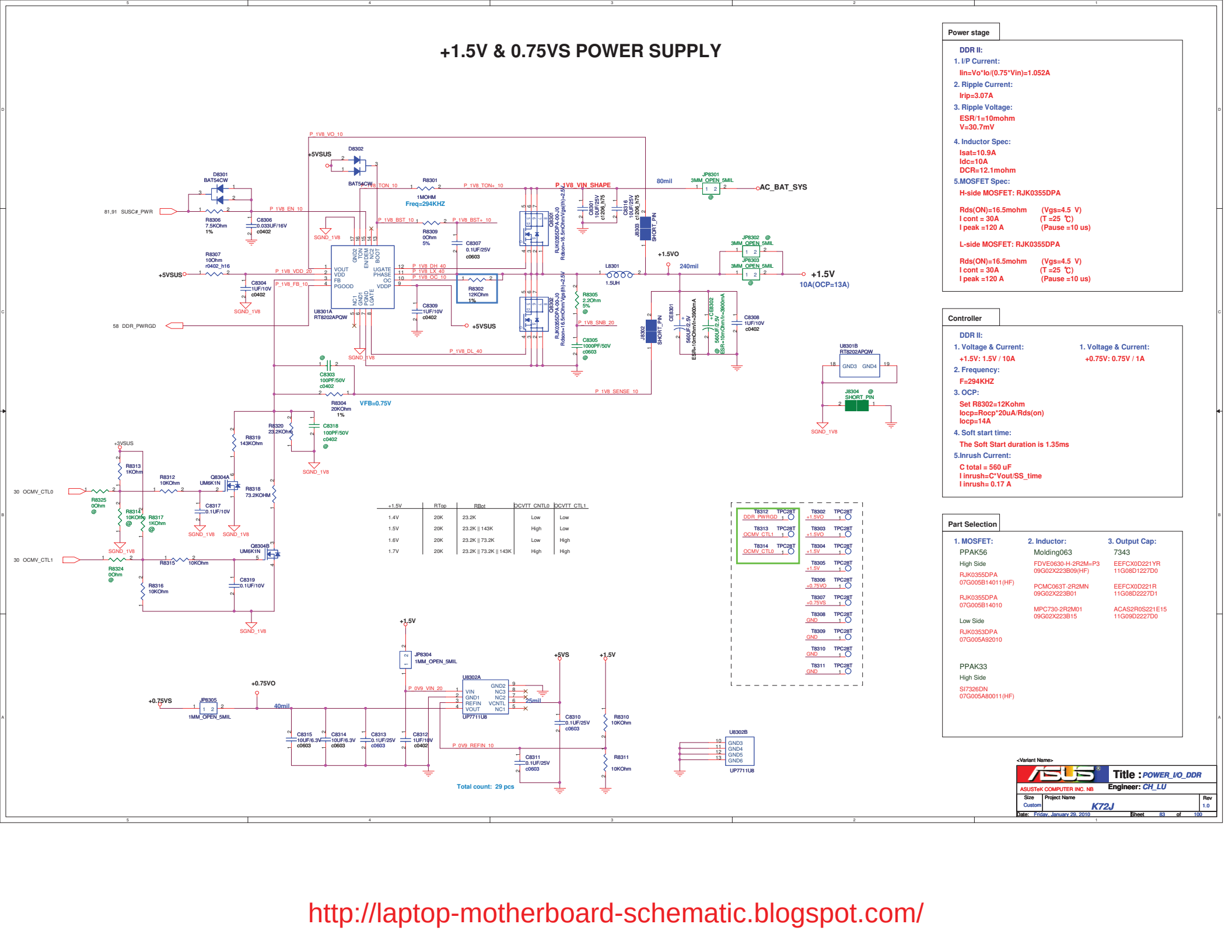
Part Selection

1. MOSFET:	2. Inductor:	3. Output Cap:
PPAK56	Molding063	7343
High Side	FDVE0630-H-2R2M-P3	EEFCX0D221YR
RJK0355DPA	09G02X223809(HF)	11G08D1227D0
07G005B14011(HF)	PCMC063T-2R2MN	EEFCX0D221R1
RJK0355DPA	09G02X223801	11G08D2227D1
07G005B14010	MPC730-2R2M01	ACAS2R0S221E15
Low Side	09G02X223815	11G08D2227D0
RJK0353DPA		
07G005A92010		
PPAK33		
High Side		
S1732DN		
07G005A80011(HF)		

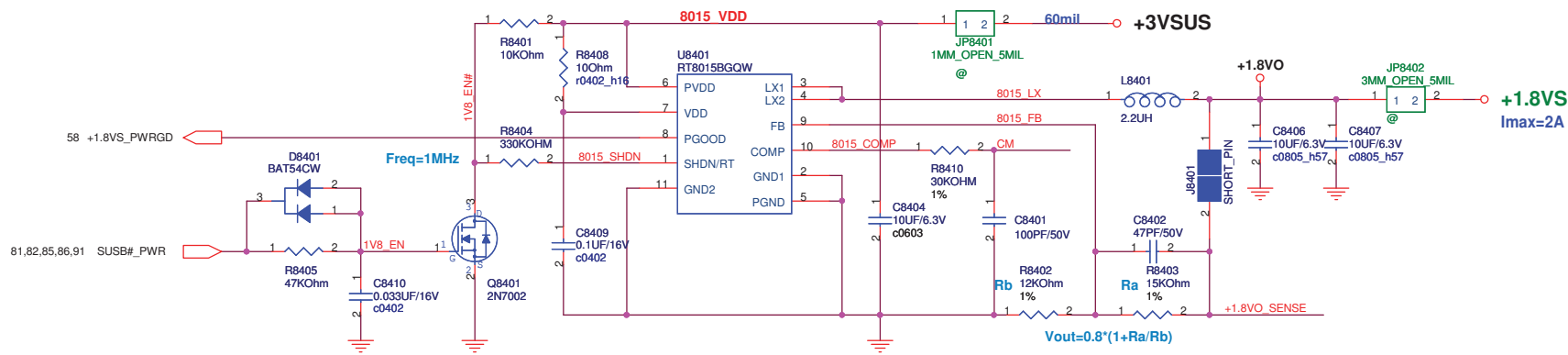
Variant Name: ASUS
ASUSTek COMPUTER INC. NB
Project Name: K72J
Date: Friday, January 29, 2010
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Title: POWER_IO_DDR
Engineer: CH_LU
Rev: 1.0

Total count: 29 pcs



+1.8V POWER SUPPLY



+1.8VS @ 2A

1. Supply Voltage:
 $V_{IN} = 3.3V$ (2.6V ~ 5.5V)
2. Supply Voltage:
 $V_{OUT} = 1.8V / 2A$
3. Current Limit:
 $I_{limit} = 3.2A$
4. Continue Current:
 $I_{cont} = 2A$
5. Feedback Voltage:
 $V_{FB} = 0.8V$
6. Switching Frequency:
 $R_{rt} = 330\text{ Kohm}$
 $F_{sw} = 1\text{ MHz}$

T8403	TPC28T
+1.8VO	1
T8404	TPC28T
+1.8VS	1
T8405	TPC28T
GND	1
T8406	TPC28T
GND	1
T8407	TPC28T
+1.8VS PWRGD	1

<Variant Name>

		Title : <u>POWER_I/O_+1.8VS</u>	
ASUSTek COMPUTER INC. NB		Engineer: <u>CH_LU</u>	
Size B	Project Name K72J	Rev 1.0	
Date: <u>Friday, January 29, 2010</u>		Sheet	84 of 100



<Variant Name>	
 Title :	
Engineer:	
Size Custom	Project Name
Date: Friday, January 28, 2010	Sheet 87 of 100



Battery Cells		
BATSEL_1	BATSEL_0	CELLS
H	H	2 CELLS
L	H	2 CELLS
H	L	3 CELLS
L	L	4 CELLS

Charger IC and EC Code correlation sheet :
Charger MAX8725 => EC CODE : 200
Charger MAX17015 => EC CODE : 201
Charger MB39A132 => EC CODE : 202



<Variant Name>			
		Title :	
<OrigName>		Engineer:	
Size	Project Name	Rev	
Custom		1.0	
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BATTERY IN DETECT

<Variant Name>

**ASUS**[®]

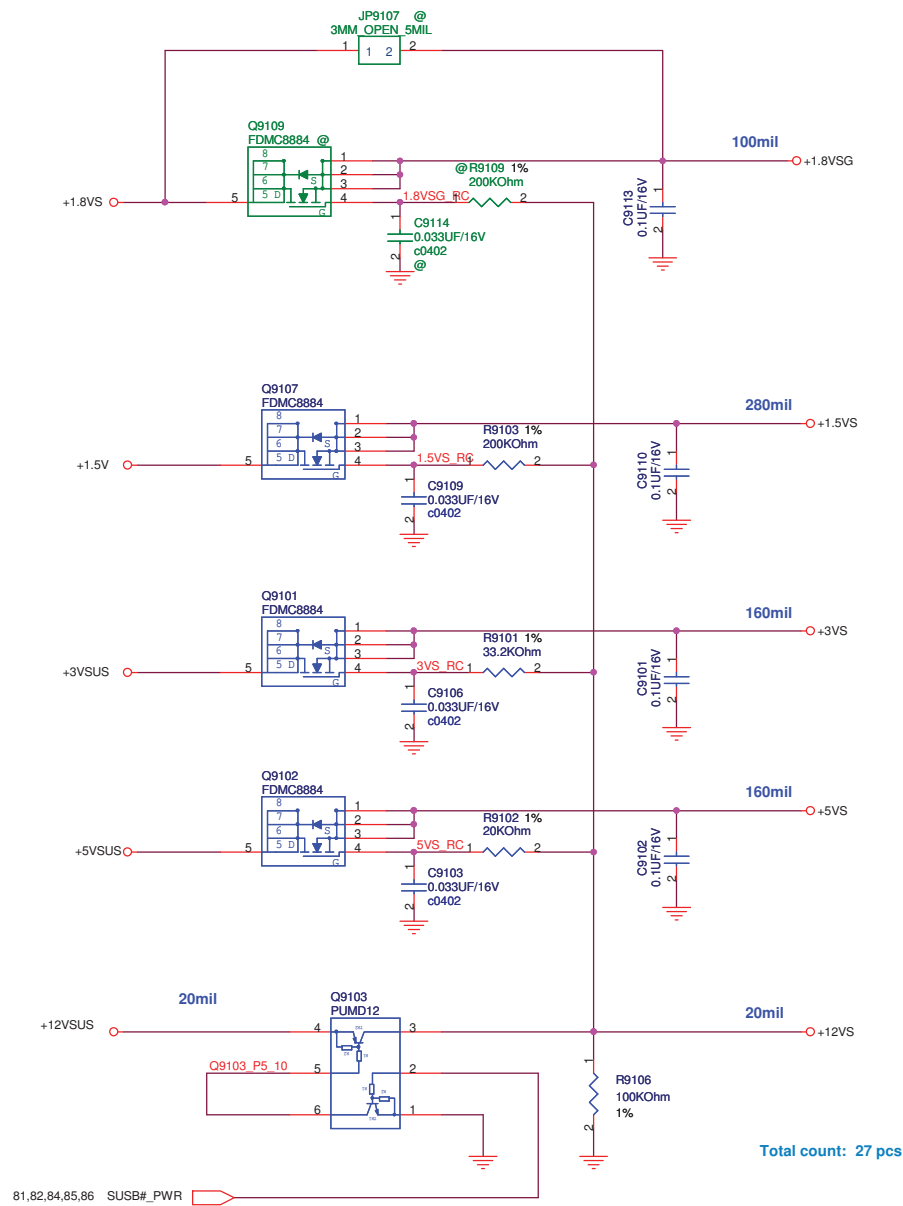
Title :POWER_DETECT

ASUSTeK COMPUTER INC. NBEngineer: *Morris*

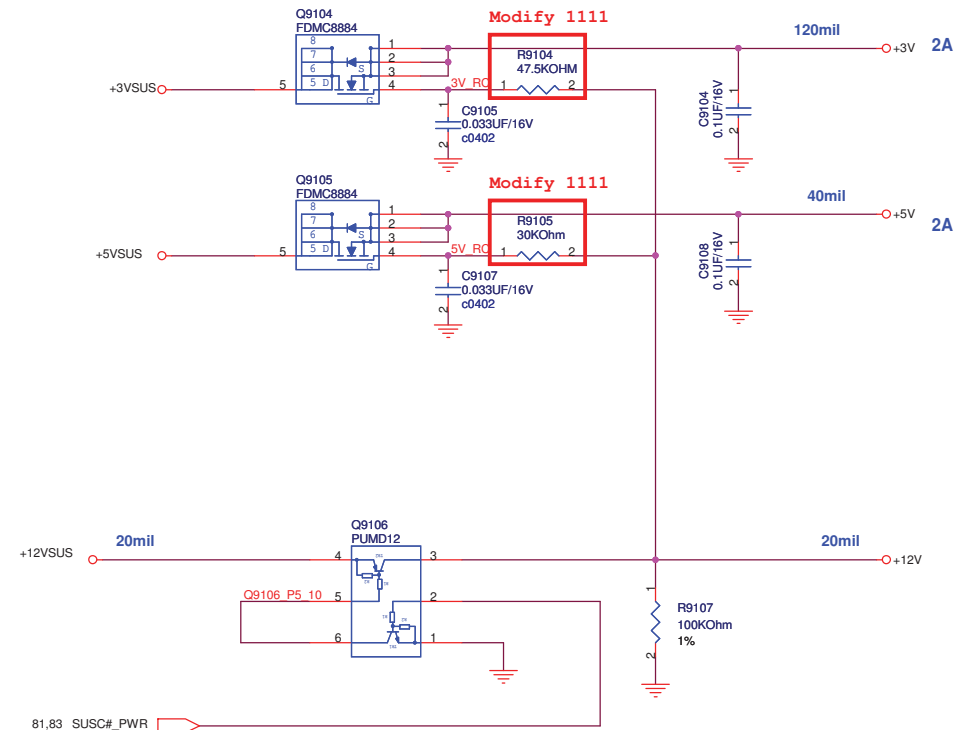
Size	Project Name	Rev
Custom	<i>Design IP</i>	1.0

Date: *Friday, January 28, 2010*Sheet 90 of 100

SUSB#_PWR POWER



SUSC#_PWR POWER



T9107	TPC28T	T9101	TPC28T
+12VS	1	+1.8VSG	1
T9108	TPC28T	T9102	TPC28T
+3V	1	+1.5VS	1
T9109	TPC28T	T9103	TPC28T
+5V	1	+3VS	1
T9110	TPC28T	T9104	TPC28T
+12V	1	+5VS	1
T9111	TPC28T	T9105	TPC28T
GND	1	GND	1
T9112	TPC28T	T9106	TPC28T
GND	1	GND	1

<Variant Name>

ASUS Title : **POWER_LOAD SWITCH**

ASUSTek COMPUTER INC. NB Engineer: **CH_LU**

Size	Project Name	Rev
B	K72J	1.0

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History

R1.0 to R1.1 :

Page 3 : Change R0363,R0364 to RN0302.
Remove SL0311,SL0312.
Change R0366,R0367 to SL0319,SL0320.
Change R0351 to SL0321.

Page 5 : DNI R0501,R0502,R0505,R0506.

Page 6 : Remove R0616,R0601.
Change R0607 to SL0601.
Change R0605,R0606 to RN0601.

Page 14 : Change CE1407 from 220uF to 100uF for cost down.
Change CE1401~CE1403,CE1406 from POSCAP to TAN for cost down.
Change JP1402 to R1414,R1415 for EMI request.
Correct CE1404 part reference to C1450.

Page 16 : Change R1605,R1606 to SL1601,SL1602.

Page 17 : Change R1705,R1706 to SL1701,SL1702.

Page 18 : Change C1811,C1802 from 0.1uF/10V to 0.1uF/16V.
Remove R1809,R1810.
Change R1801,R1802,R1803,R1804 to RN1802.

Page 19 : Add OC/UC circuit (IT8268).

Page 21 : Remove RX2105,RX2106,RX2107,RX2108,RX2140,RX2141.
Change R2136,R2137 to RN2101.

Page 22 : Chaneg R2257 to SL2201.
Remove R2245.
Change R2246 to SL2202.
Change R2239,R2240 to SL2203,SL2204.

Page 23 : Change R2322,R2323 to RN2301.

Page 24 : Change RX2401,RX2404,RX2406 from 22ohm to 47ohm.
Remove T2413.
Change RP2401~RP2403 to RN2401~RN2405.
Change Card Reader to USB port 11.

Page 25 : Remove R2504,R2523.

Page 26 : Remove JP2601.
Add D2605,R2623,Q2621,R2637,C2617 for ITE8541.

Page 27 : Change +VTT_PCH to +VTT_PCH_ORG.

Page 28 : Change SPI ROM circuit for ITE8541.

Page 29 : Add R2922 for CLK_PWRGD# (open drain).
Add +VDD_1.05 for ICS9LV3162.

Page 30 : Add U3004 co-lay with U3003.
Add R3010 for X'tal free option.
Add R3008,R3006 for ITE8541 VSUS_ON.
Add OCVTT_CTL0/1,OCMV_CTL0/1 for OC/UC option.

Page 31 : Change C3105 from 0.1uF/10V to 0.1uF/16V.

Page 33 : Remove R3314.
Remove AR8121 option circuit.

Page 34 : Change Transformer to 09G051059023 / 09G051059055.
Change +AVDD_CEN_LAN to +AVDD_1.7_LAN.

Page 37 : Change Jack Ground from GND_AUDIO to GND_JACK.
Add SL3740 for HP1_JD , SL3741 for EXT_MIC_JD.

Page 45 : Change R4501 from 330ohm to 150ohm.
C4507 from 1uF/10V to 1uF/6.3V.
Change C4511(0.1uF/10V) to C4513(0.1uF/16V).
Change RNX4501,LX4501 to SL4501.
Change C4514 connect to R4529 pin1.
Change L4503,C4509,C4512 connection.

Page 48 : Change VGND to GND.
Change F4801 from 0.2A/30V to 1.5A/6V.
Add D4803.

Page 53 : Remove RX5305,RX5306.

Page 56 : Change C5605 from 0.1uF/10V to 0.1uF/16V.
Change LED5601~LED5603 from BLUE to GREEN.
Change LED voltage from +5VS/+5VA to +3VS/+3VSUS.
Add CAP_LED#,NUM_LED# pull-up for open drain signal.

Page 57 : Change Q5703B to NC , R5708 pin1 to +VTT_CPU_VO.

Page 58 : Add R5836 (DNI).

Page 60 : Remove L6001,L6002.

Page 65 : Add H6502 for LVDS cable.

Page 68 : Add caps for EMI request.

Page 70 : Change VGND to GND.

Page 71 : Remove R7124.

Page 73 : Change VGND to GND.

Page 74 : Change CE7401 from 3528 to 7343 type.
Change all +VGA_CORE 0.01uF to 1uF for PARK.

Page 75 : Add RN7501~RN7507 for dual rank memory.

Page 76 : Change VGND to GND.

Page 80 : Mount R8050,R8052.
Change R8050,R8051,VID pull-up to +VTT_CPU_VO.

Page 82 : Change +VTT_PCH to +VTT_PCH_ORG.
Add OV/UV circuit , remove 1.1V support.

Page 83 : Add OV/UV circuit.

Page 84 : Change R8405 from 330K to 200K ohm for +1.8VS timing.

Page 86 : Change 5V_RUN to +5VSUS , VGND to GND.

Page 91 : Change JP8207 to JP9107.

*** Change all M92 parts to PARK parts ***

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<OrgName>		Engineer: Jerry Mou	
Size Custom	Project Name K72Jr		Rev 2.0
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R1.1 to R1.2 :

Page 20 : Change C2001,C2002 from 18pF to 15pF.

Page 24 : DNI U2401 , mount R2413.

Page 26 : DNI D2605 , mount R2623 for ITE8541.

Page 28 : DNI R2848 , mount R2857 for ITE8541.
Mount R2866~R2869 for ITE8541.

Page 29 : DNI L2904 & R2921 , mount L2903 for ICS9LVS3162.

Page 30 : DNI R3008 , mount R3006 for ITE8541.
Change C3016,C3017 from 15pF to 10pF.
DNI U3003,R3014 , mount R3002~R3005 for ITE8541.

Page 33 : Add R3321 for signal integrity.

Page 36 : Add D3601 for pop noise.

Page 37 : Change D3709 from RB717F to BAT54AW.
Change C3701 to X7R.

Page 45 : Change C4504 from 1uF/10V to 1uF/6.3V.

Page 47 : Change C4804~C4811 to X5R type.
Change R4801,R4802 to RN4801.

Page 57 : DNI R5705,R5706,Q5703,R5708,R5714,R5715,Q5707,R5712.

Page 58 : Change D5801 from BAT54CW to BAT54C.

Page 65 : Remove H6521,H6522,H6506,H6507,H6523,H6524.

Page 74 : Change L7405 to 09G013120400.
DNI Q7401,L7407 , mount R7402.
Change R7402 to 0805 type.

Page 75 : DNI R7501 for PARK.
Change pin AL21 to test point.

Page 82 : DNI R8220 & R8222 , mount R8223.
Add R8225 & R8226.
DNI R8271 & R8272.

Page 83 : Add R8324 & R8325.
DNI R8314 & R8317.

Page 84 : Change R8405 from 200K to 47K ohm for +1.8VS timing.

Page 85 : Add JP8505 , R8509.
Change R8511 from 7.5K to 5.1K ohm.
DNI U8501 related circuit for cost down.

R1.2 to R1.3 :

Page 21 : Change R2157 from 39 ohm to 15 ohm for single load.

Page 25 : Change PCB ID resistors.

Page 30 : Change R3021,R3023 from 47K ohm to 100K ohm for battery team request.
Add R3030 for VSUS_ON connection.
Delete J3001 & U3004 from schematic.
Add R3011 & Q3002 for ITE8570 X'tal free option.

Page 38 : Change R3852 to 0 ohm , C3801 to DNI.

Page 40 : Change SL4501 to L4502 for EMI request.

Page 52 : Change SL5201,SL5202 to L5201,L5202 for EMI request.

Page 65 : Modify H6518 shape for ME request.

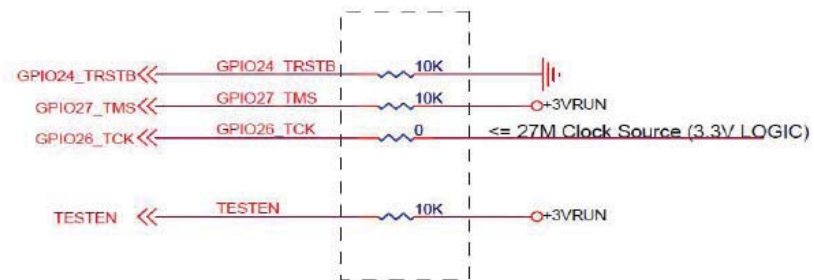
Page 71 : Change R7128 to 0402 type.

Page 77 : Change R7714 to /HYNIX , R7718 to /SAMSUNG.

Page 80 : Change 8029 to 5.36K , C8001 to 68nF , R8032 to 10K , C8019 to 220pF.
Change R8039,R8040 to 165K ohm.

Page 82 : Change CE8202 to C8221 & C8222 (DNI).

Page 70~77 : Add PARK errarta items as below.



In current reference design, TESTEN is pulled down through a resistor and GPIO24_TRSTB may be pulled-high or floating. To implement option 2, both of these resistors should be depopulated (keep the resistor pad for debugging purposes).

Option 2 requires that:

- 1) TESTEN and GPIO27_TMS be pulled high (3.3V)
- 2) GPIO24_TRSTB be pulled to ground (0V), and
- 3) A clock source (1KHz ~27MHz, 3.3V level) be provided on GPIO26_TCK (through a 0 Ohm resistor). The 27MHz oscillator output can be used (if present).

ASUS			Title : HISTORY	
<OrgName>			Engineer: Jerry Mou	
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R1.3 to R2.0 :

Page 19 : Add R1903.

Page 20 : DNI R2034~R2039 for Production PCH.

Page 21 : Change R2157 from 15 ohm to 24.9 ohm.

Page 32 : Mount R3207 for G709.

Page 36 : Change INT_MIC to Codec Port A for feedback issue.

Page 37 : Change Phone Jack P/N from 12G14030106L to 12G14000106M.

Page 38 : Change Internal Mic reference voltage to codec output.

Page 46 : DNI Q4601 , mount U4601 , change SL4601 & SL4602 to 33 ohm for HDMI audio disappear issue.

Page 48 : DNI D4803 for cost down.

Page 50 : Add G709 circuit , DNI G781 circuit.

Page 51 : Change R5101~R5103 to short land.

Page 56 : Change LED5601 from Green to White , R5604 pin1 from +3VSUS to +5VSUS.

Page 57 : Delete Q5702 & Q5703 & Q5707 discharge circuit , change Q5704 to 2N7002.

Page 60 : Delete JP6003 & JP6004.

Page 65 : Delete H6527.

Page 66 : Change C6607 from 0.1uF/16V to 0.1uF/25V.

Page 71 : Add U7101 & R7131 for PARK errata E2 , DNI R7121 & R7124 for production PARK.

Page 73 : DNI R7335 , mount R7305 for production PARK.

Page 76 : DNI R7605 for production PARK.

Page 82 : Modify CE8204 & CE8205 package.

Page 91 : Change R9104 to 47.5K , R9105 to 30K for power on fail issue.

		Title : HISTORY	
<OrgName>		Engineer: Jerry Mou	
Size Custom	Project Name K72Jr		Rev 2.0
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